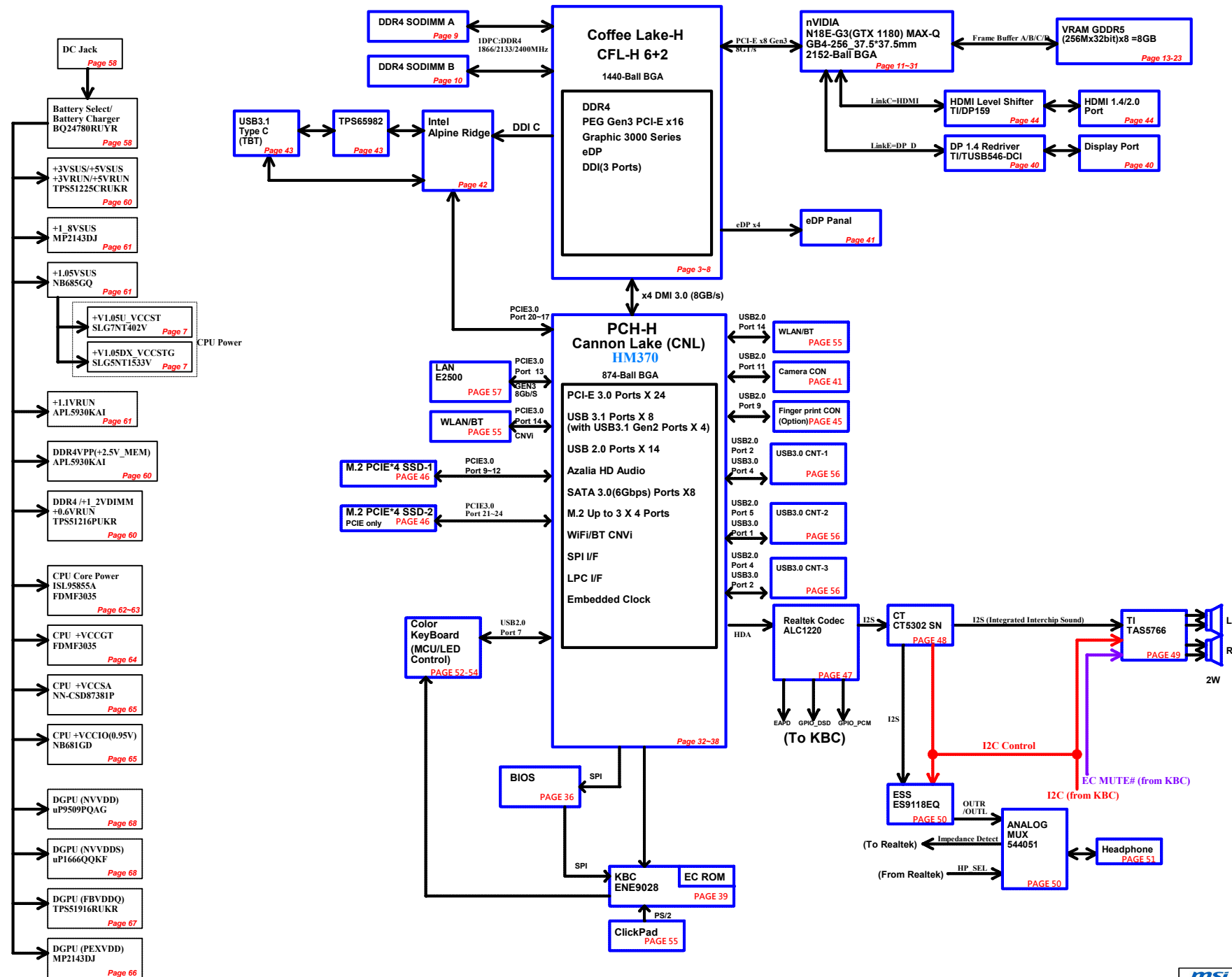
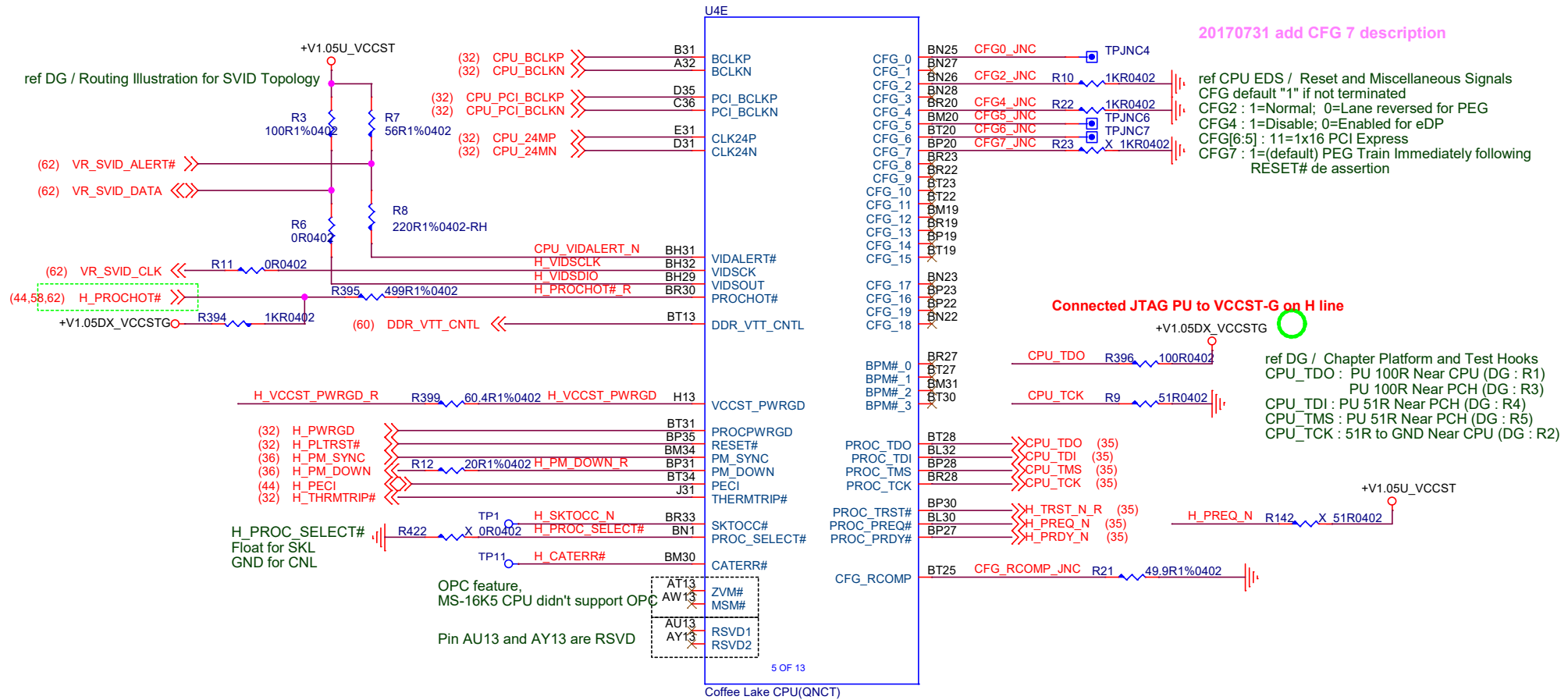
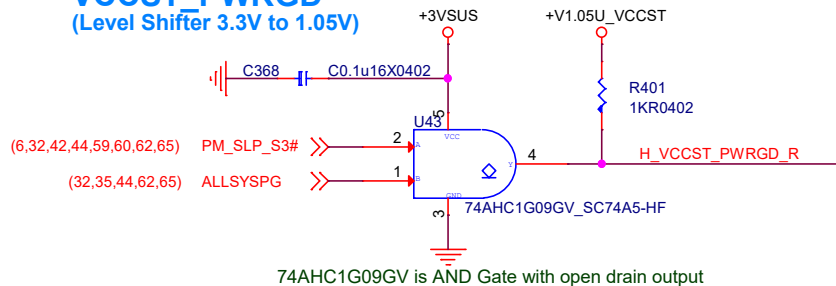


Intel Coffee Lake-H



CFL-H (HOST)

VCCST_PWRGD
(Level Shifter 3.3V to 1.05V)

msi		MICRO-STAR INT'L CO.,LTD.	
Title CFL-H(HOST)			
Size Custom	Document Number MS-16Q4		Rev 10
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Diagram illustrating the DDR Channel A and DDR Channel B configurations for the Coffee Lake CPU (QNC7).

DDR Channel A

Channel A is configured with 16GB (8GB x 2) of DDR4-2666 memory. The memory is organized into 8 banks (BA0-B7) and 16 rows (R0-R15). The channel is configured with 16GB (8GB x 2) of DDR4-2666 memory. The memory is organized into 8 banks (BA0-B7) and 16 rows (R0-R15).

DDR Channel B

Channel B is configured with 16GB (8GB x 2) of DDR4-2666 memory. The memory is organized into 8 banks (BA0-B7) and 16 rows (R0-R15). The channel is configured with 16GB (8GB x 2) of DDR4-2666 memory. The memory is organized into 8 banks (BA0-B7) and 16 rows (R0-R15).

Legend

- BA0-B7: Bank Address
- R0-R15: Row Address
- CL: Column Address
- CS: Chip Select
- WE: Write Enable
- OE: Output Enable
- WE# : Active Low Write Enable
- OE# : Active Low Output Enable
- CS# : Active Low Chip Select
- WE# : Active Low Write Enable
- OE# : Active Low Output Enable
- CS# : Active Low Chip Select

Notes

- DDR Channel A and B are configured with 16GB (8GB x 2) of DDR4-2666 memory.
- The memory is organized into 8 banks (BA0-B7) and 16 rows (R0-R15).
- The channel is configured with 16GB (8GB x 2) of DDR4-2666 memory.
- The memory is organized into 8 banks (BA0-B7) and 16 rows (R0-R15).

Diagram illustrating the DDR Channel A and DDR Channel B configurations for the Coffee Lake CPU (QNC7).

DDR Channel A

Channel A is configured with 16 data lines (DQ0-DQ15) and 16 address lines (A0-A15). The data lines are connected to the CPU pins BA0-BF7. The address lines are connected to the CPU pins BA8-BF7. The channel is configured for 16GB of memory (8GB x 2).

DDR Channel B

Channel B is configured with 16 data lines (DQ0-DQ15) and 16 address lines (A0-A15). The data lines are connected to the CPU pins BA0-BF7. The address lines are connected to the CPU pins BA8-BF7. The channel is configured for 16GB of memory (8GB x 2).

Resistor Configuration

The diagram shows the resistor configuration for the DDR channels. The resistors are connected to the CPU pins and the DDR memory modules. The resistors are labeled R25, R423, and R424. The values are 121R1%0402, 75R1%0402, and 100R1%0402 respectively.

Legend

- BA0-BF7: Data lines
- BA8-BF7: Address lines
- BA0-BF7: Data lines
- BA8-BF7: Address lines

Notes

- 1 of 1: DDR0_DQSN_8/DDR0_DQSN_8
- 2 of 13: DDR1_DQSN_8/DDR1_DQSN_8

MSI Logo

MSI MICRO-STAR INT'L CO.,LTD.

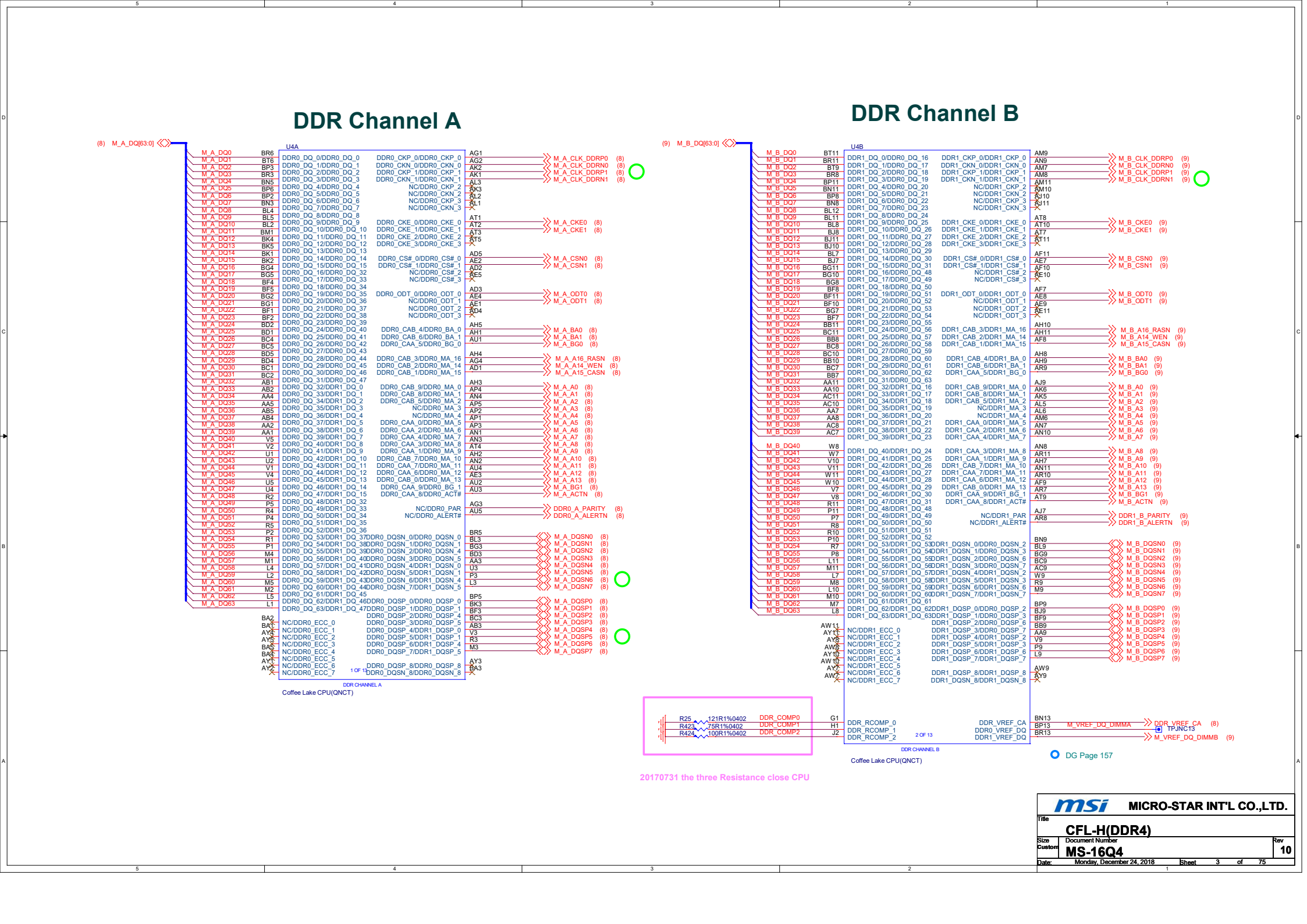
Model: CFL-H(DDR4)

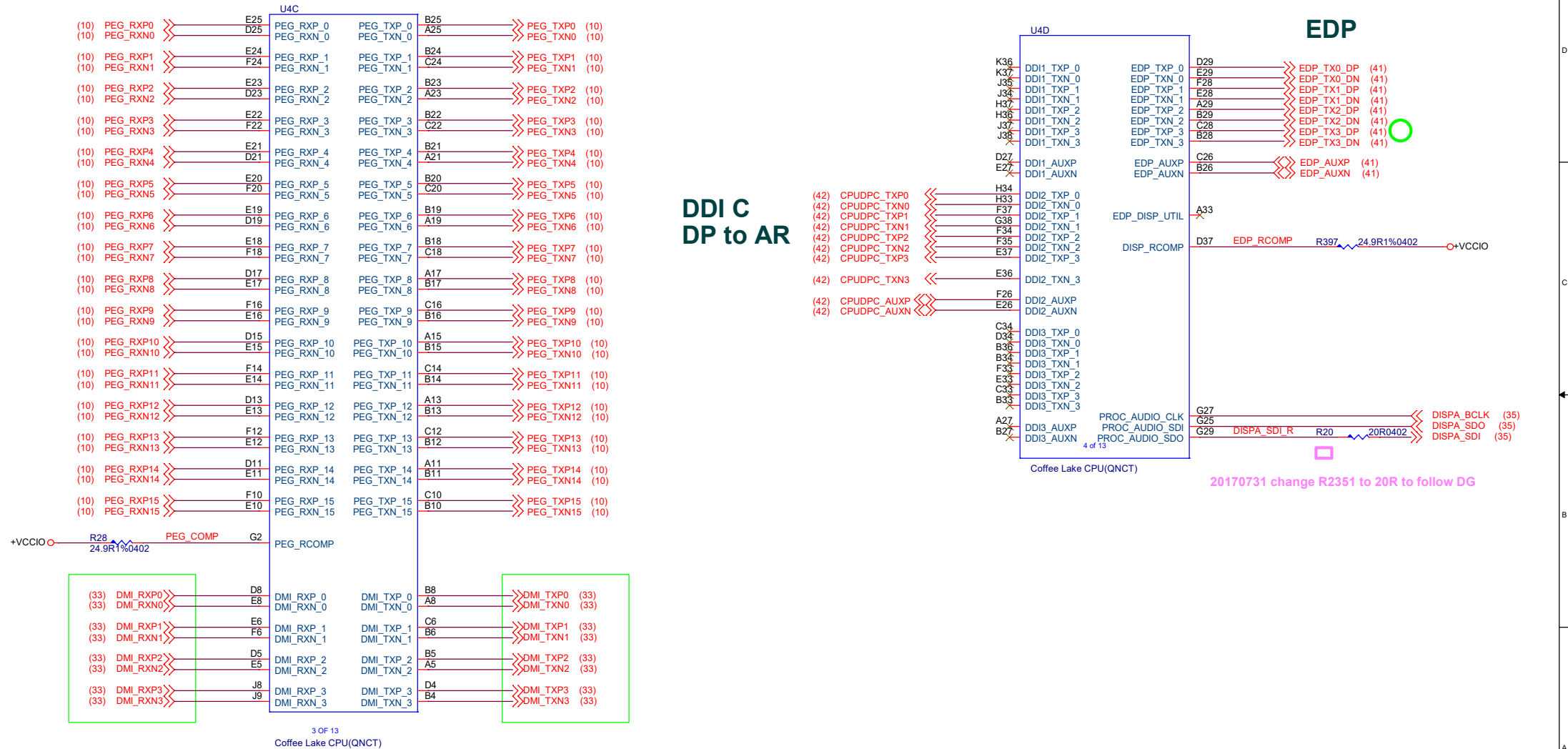
Document Number: MS-16Q4


Rev: 10

Date: Monday, December 24, 2018

Sheet: 3 of 75

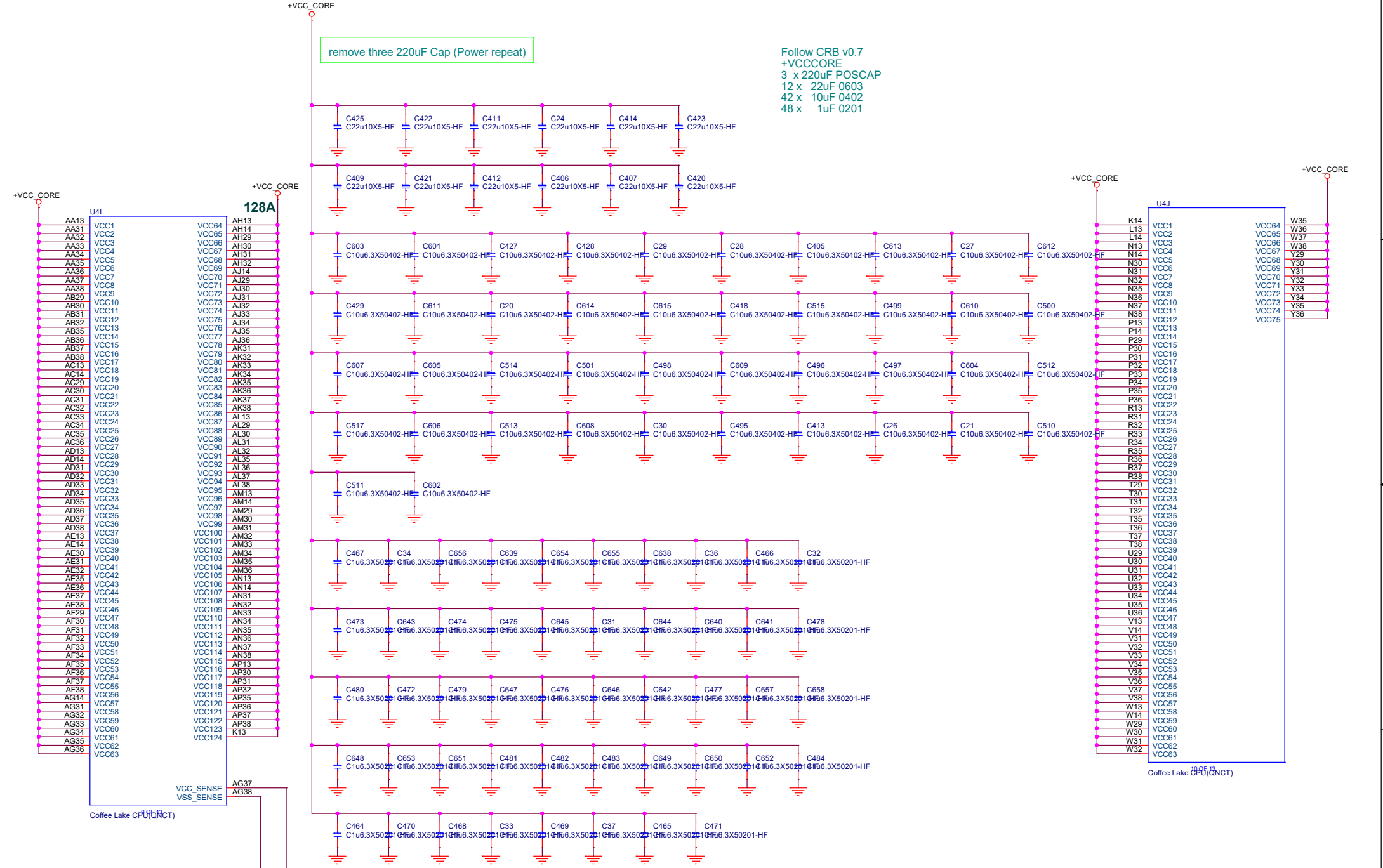




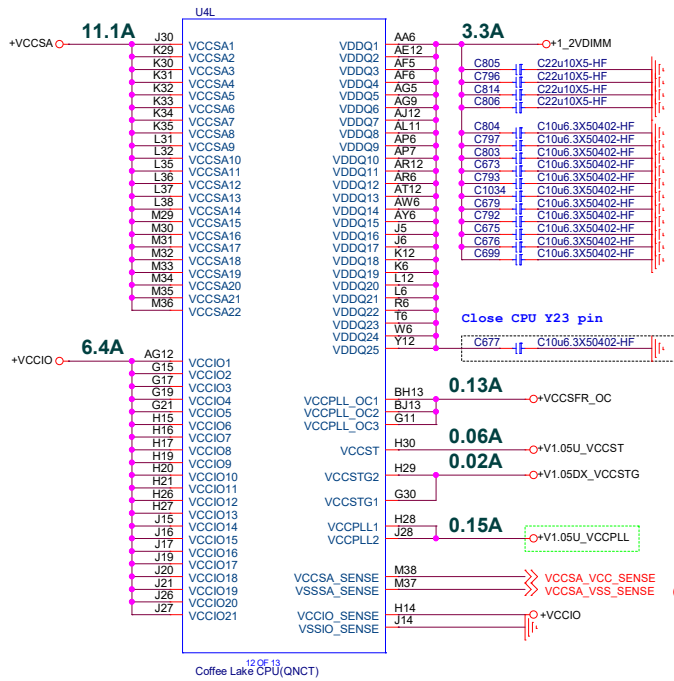
		MICRO-STAR INT'L CO.,LTD.	
Title			
CFL-H(DMI/Display)			
Size	Document Number		Rev
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Date:	Monday, December 24, 2018	Sheet	4 of 75

remove three 220uF Cap (Power repeat)

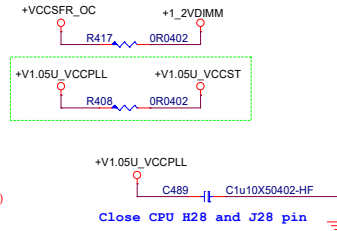
Follow CRB v0.7
+VCCCORE
3 x 220uF POSCAP
12 x 22uF 0603
42 x 10uF 0402
48 x 1uF 0201



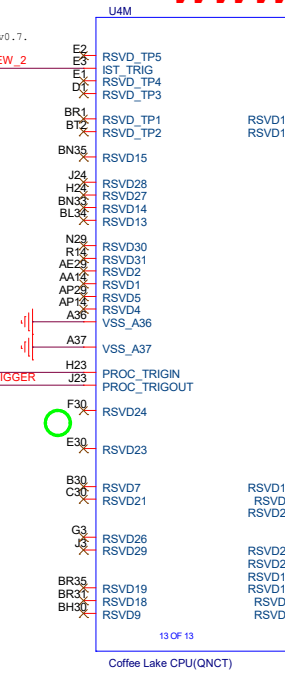
Follow CRB v0.7
+VCCDU (+1_2VDIMM)
4 x 22uF 0603
12 x 10uF 0402



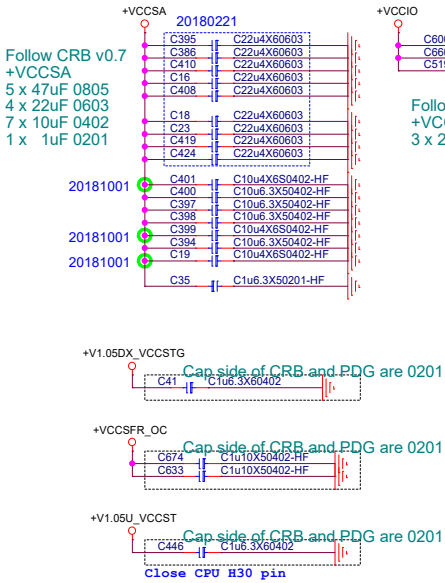
Remove +VCCVDD0_CLK, it combine with VDDQ.
Pin number: Y12



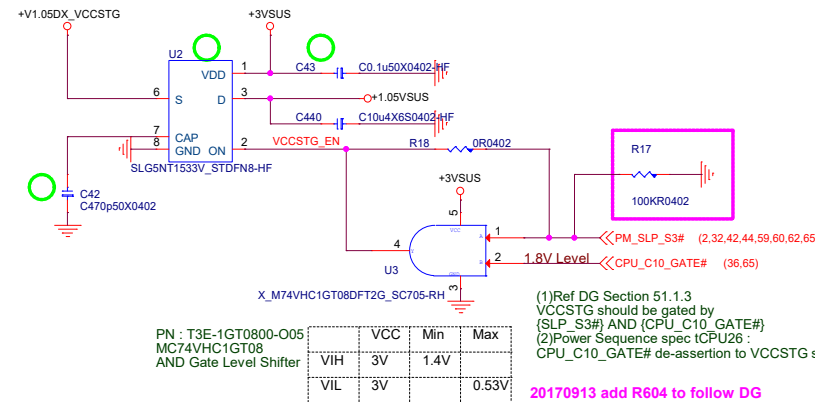
recommend external test point on CRBv0.7.
TPJNC14 TPEV_PEG_VIEW_2



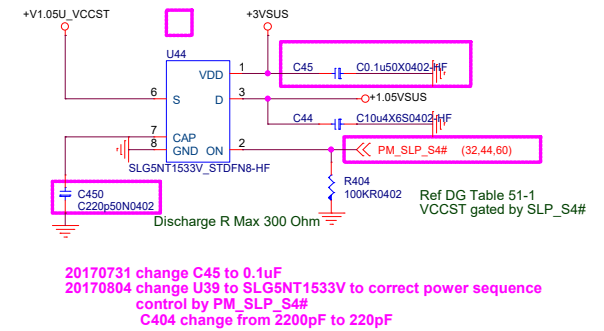
13 OF 13
Coffee Lake CPU (QNC7)

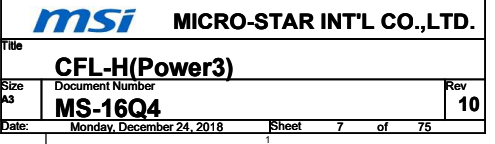


+V1.05DX_VCCSTG

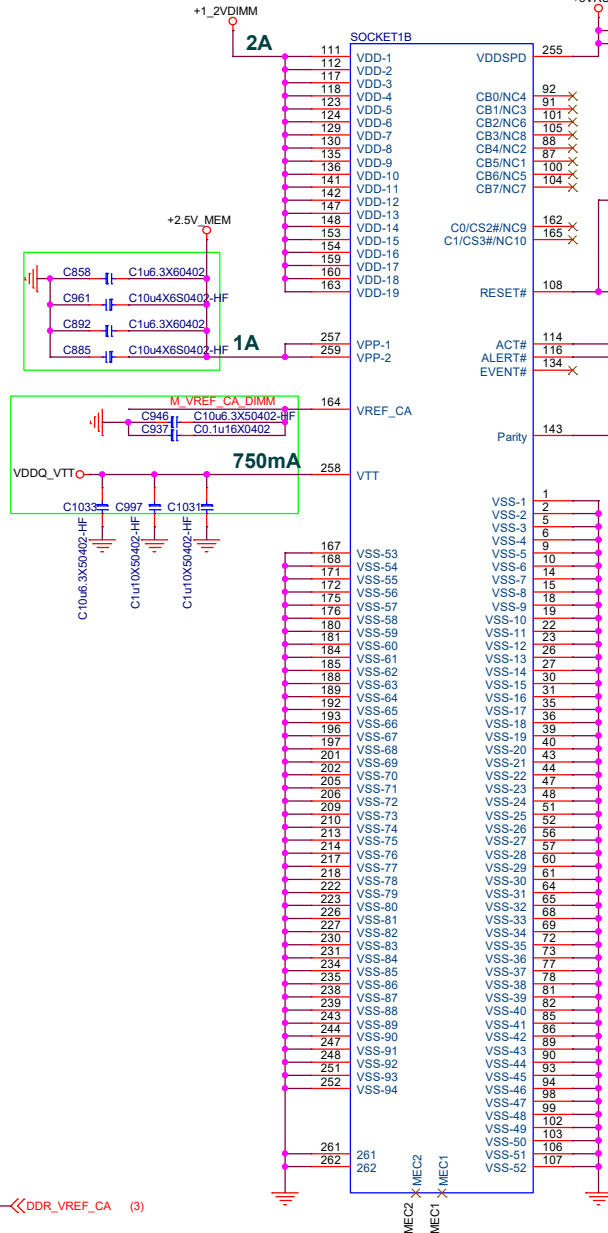
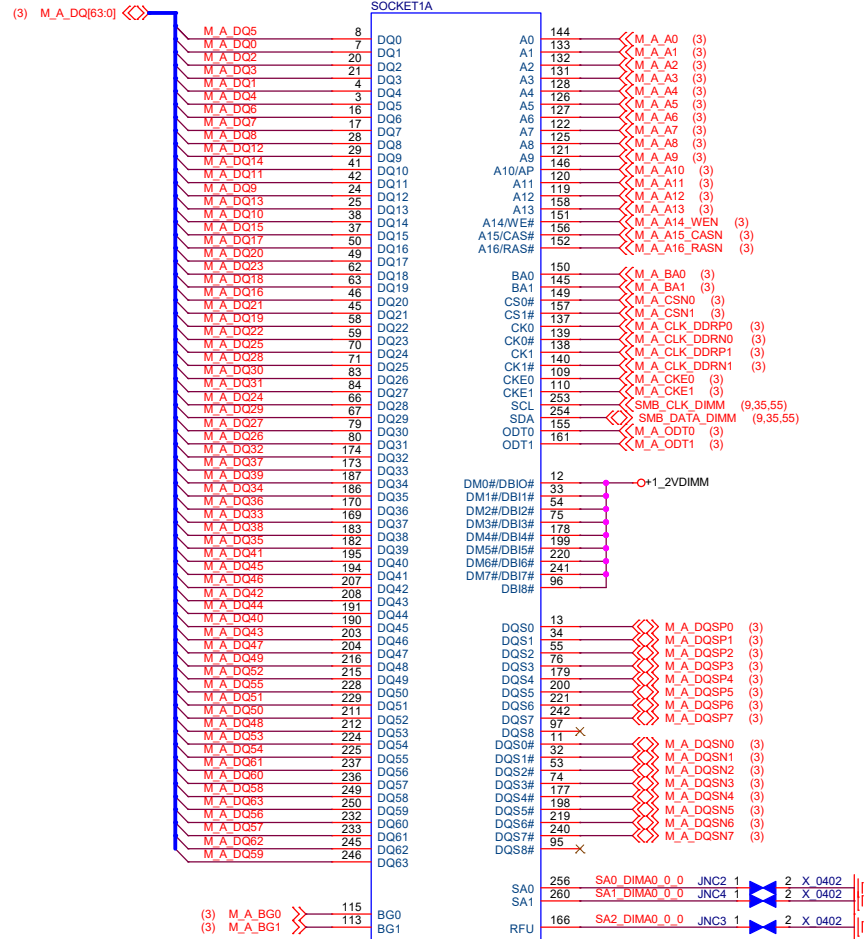


+V1.05U_VCCST



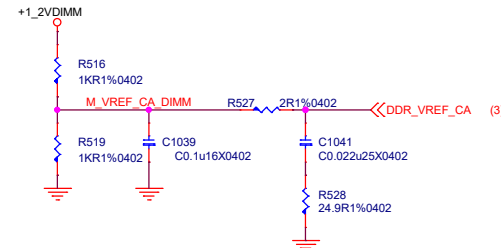
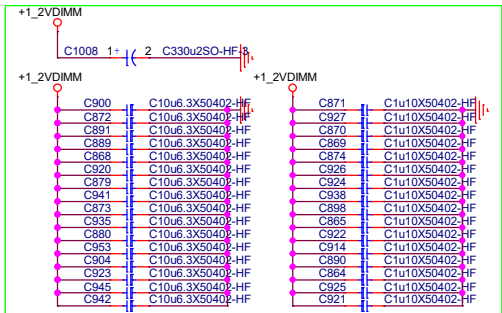


SODIMM_A0 (TOP-Reverse)



20170912 C922 change to C71-33102AE-P01
ref DG/ Section 4.14.1
CFL-H DDR4 SDDIMM Power Plane Decoupling

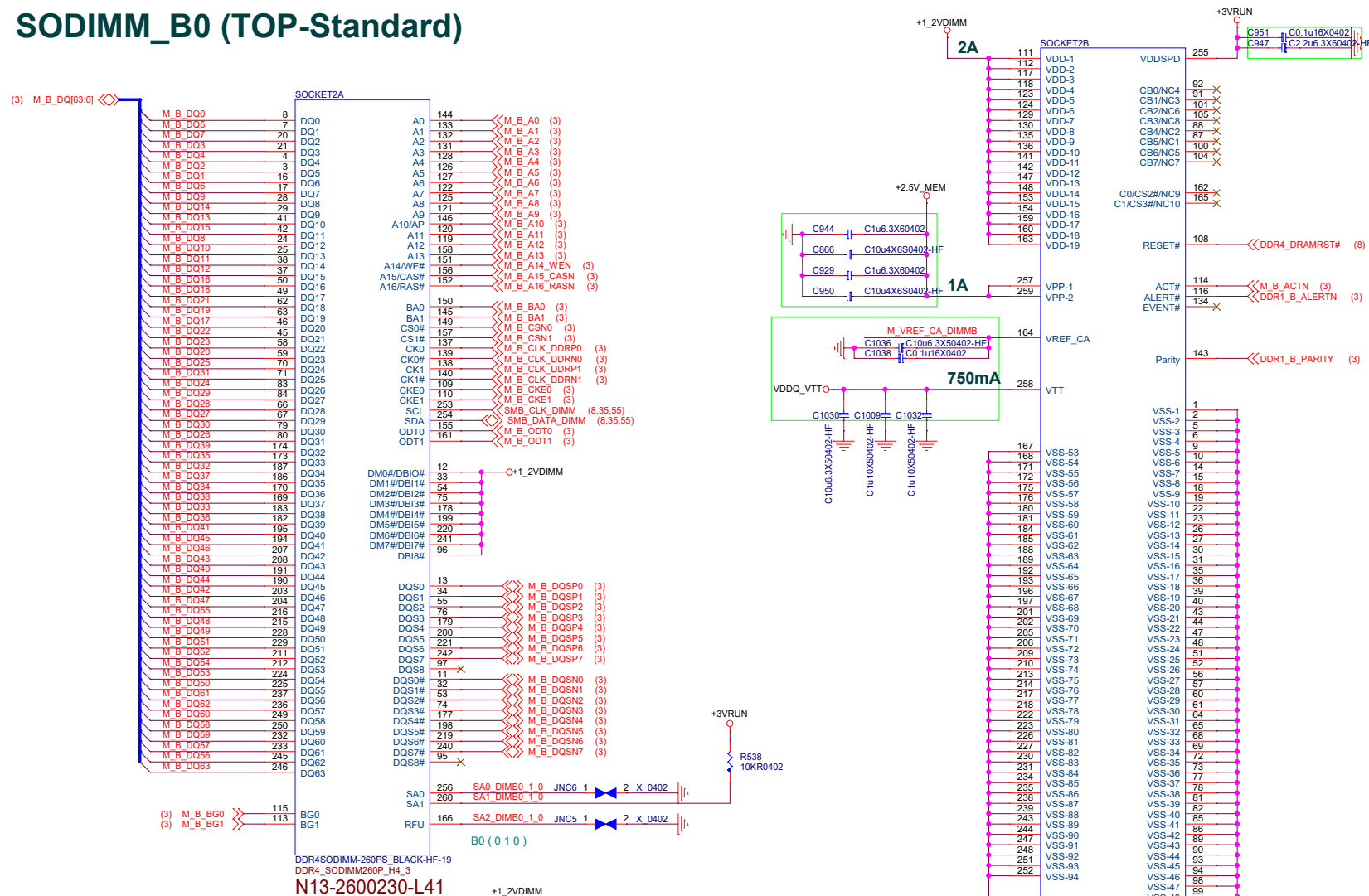
N13-2600220-L41



DDR4SODIMM-260PS_BLACK-HF-20
DDR4_SODIMM260P_H4_5
N13-2600220-L41

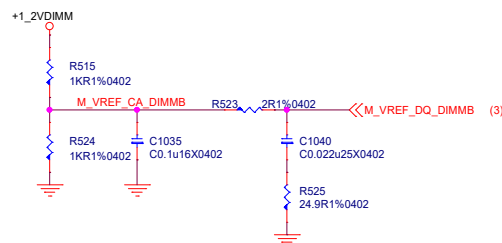
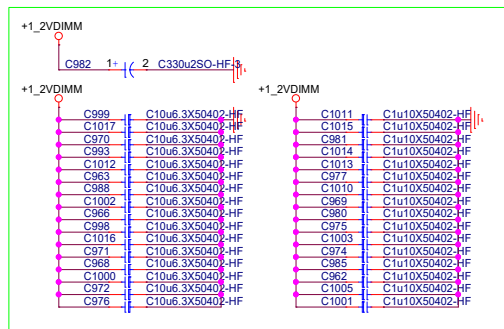
msi MICRO-STAR INT'L CO.,LTD.		
Title DDR4 SODIMM A0		
Size Custom	Document Number MS-16Q4	Rev 10
Date: Monday, December 24, 2018	Sheet 8	of 75

SODIMM_B0 (TOP-Standard)

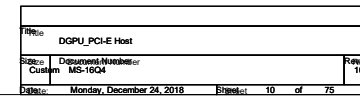


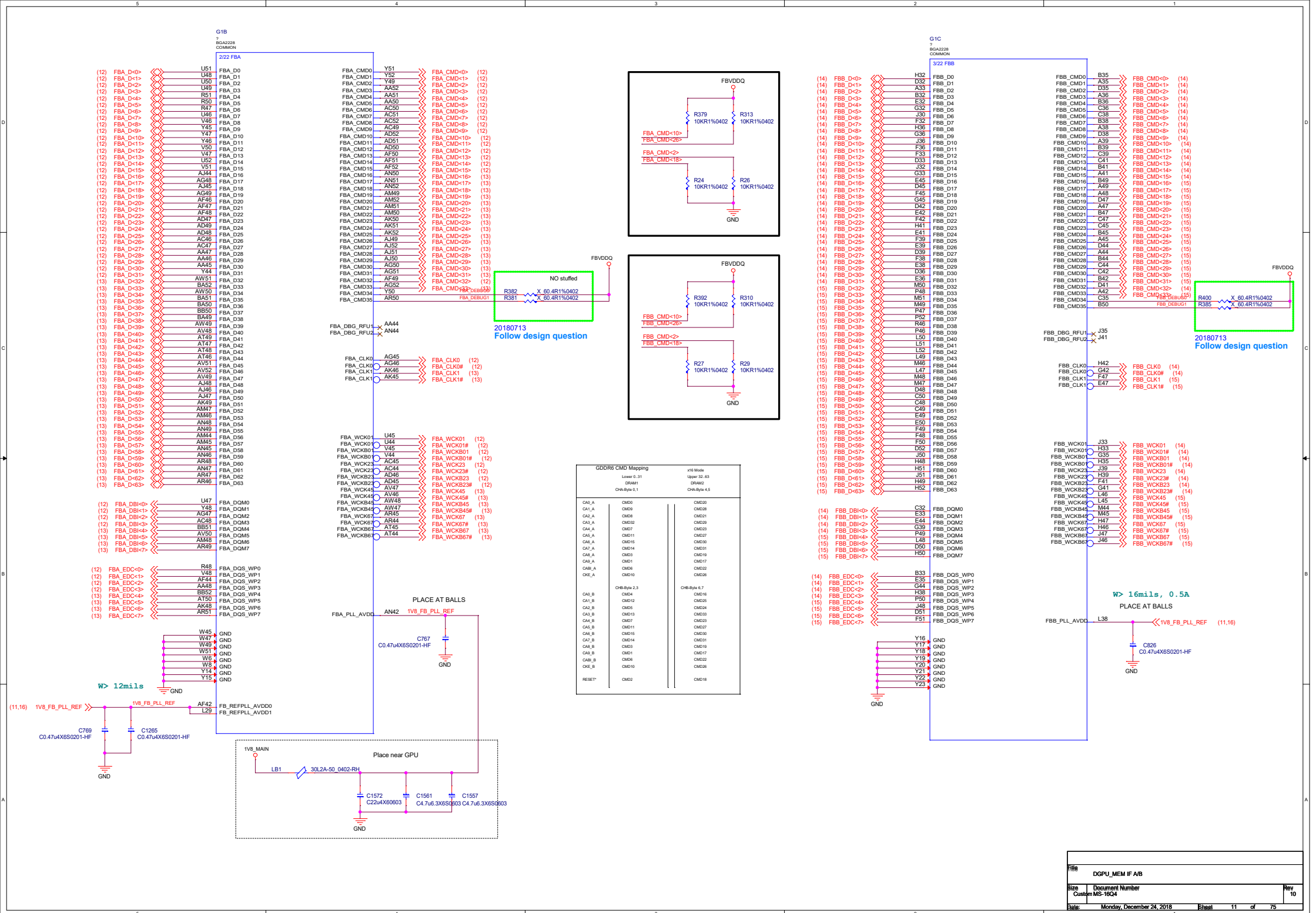
20170912 C872 change to C71-33102AE-P01

ref DG/ Section 4.14.1
CFL-H DDR4 SDDIMM Power Plane Decoupling



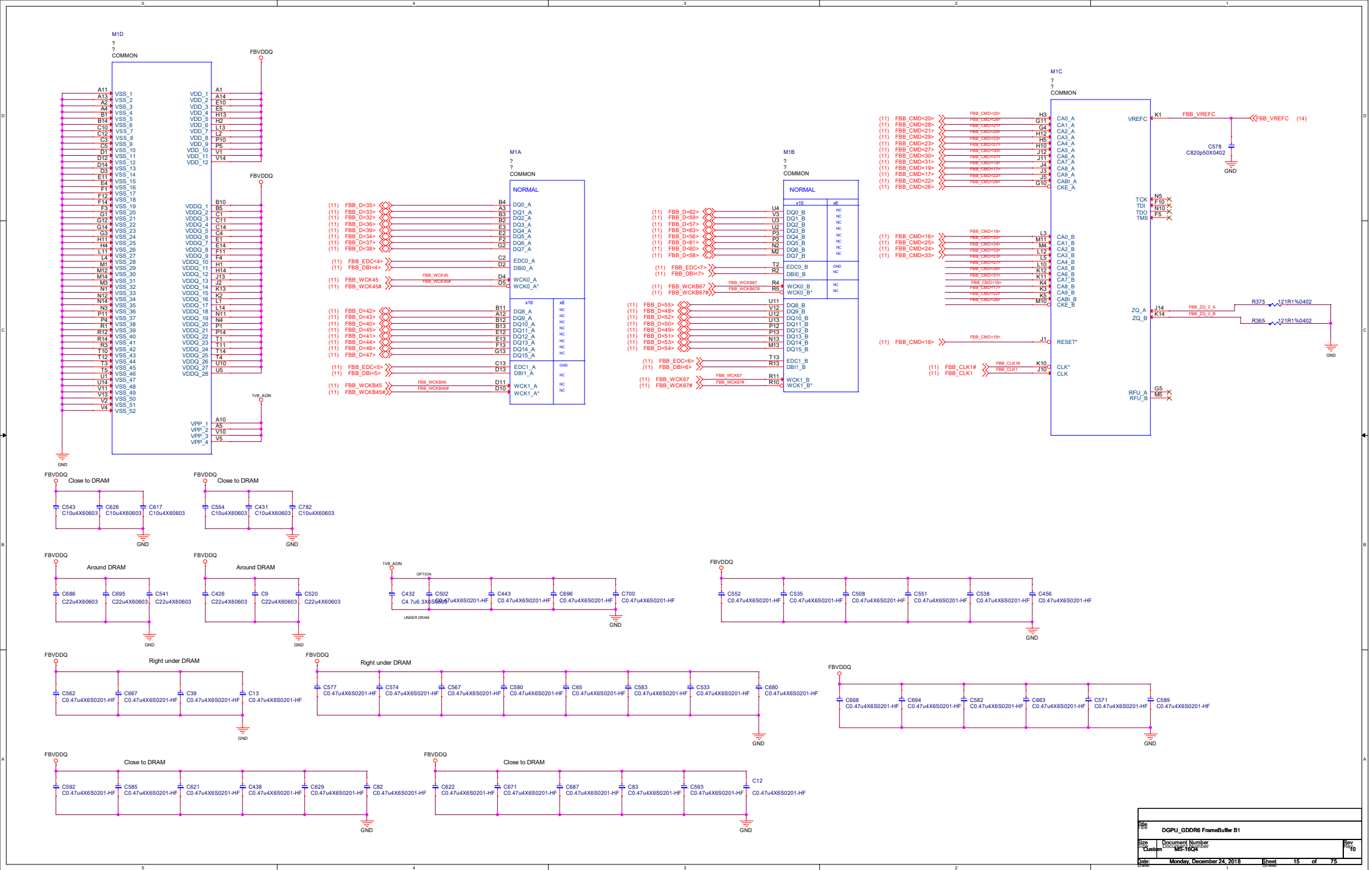
DDR4SODIMM-260PS_BLACK-HF-19
DDR4_SODIMM260P_H4_3
N13-2600230-L41



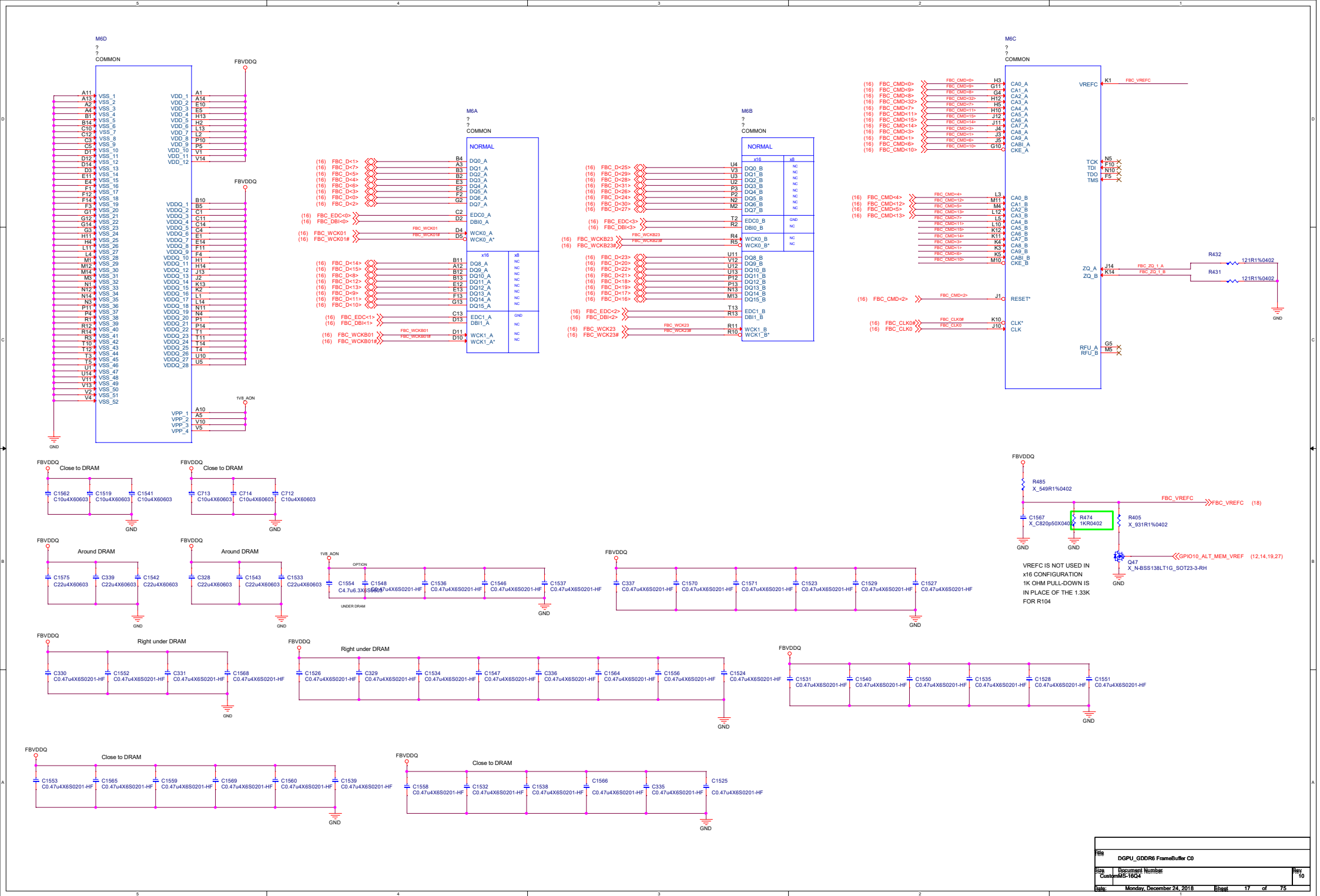


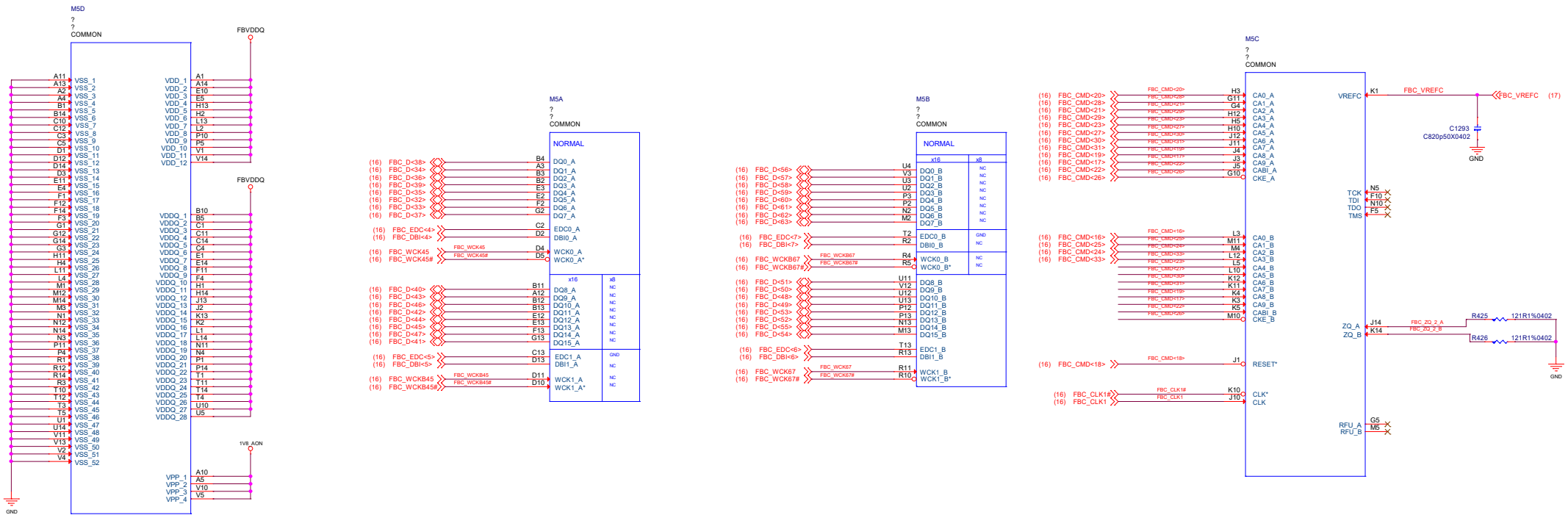


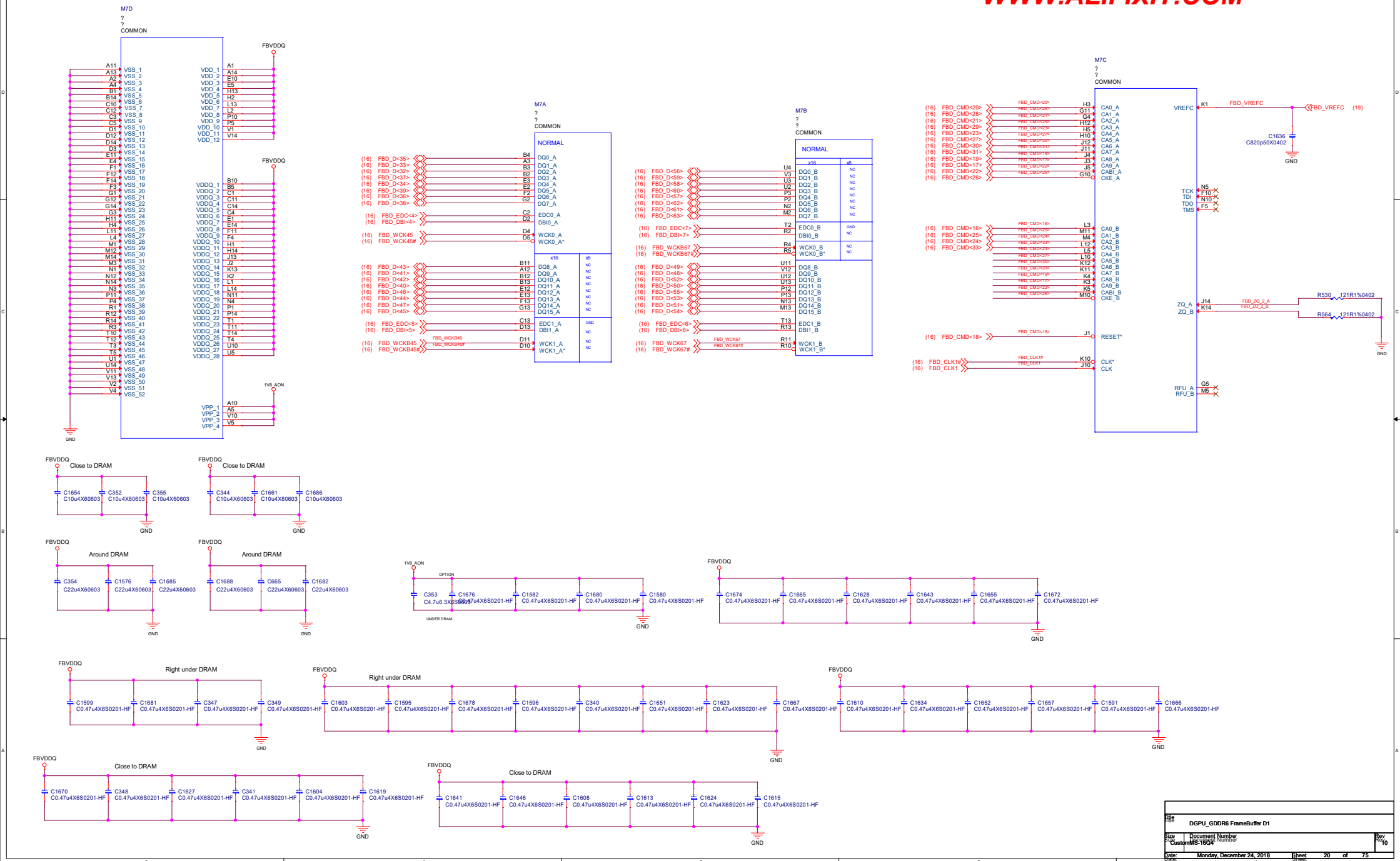


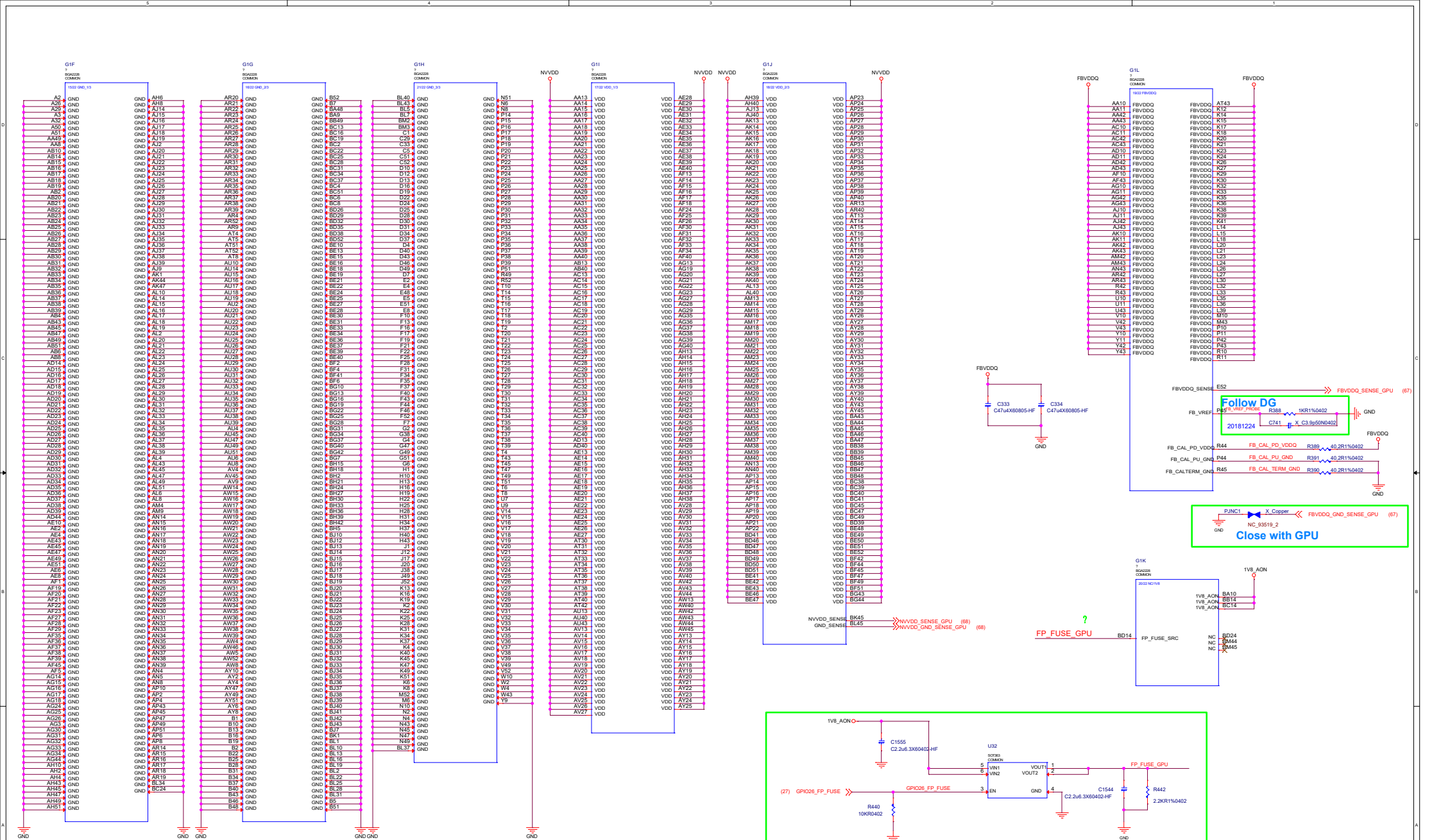


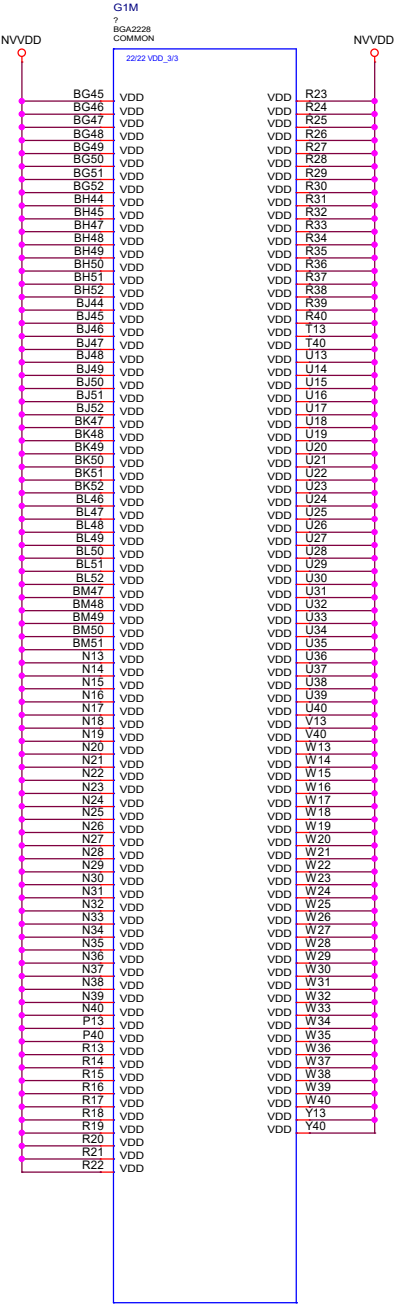




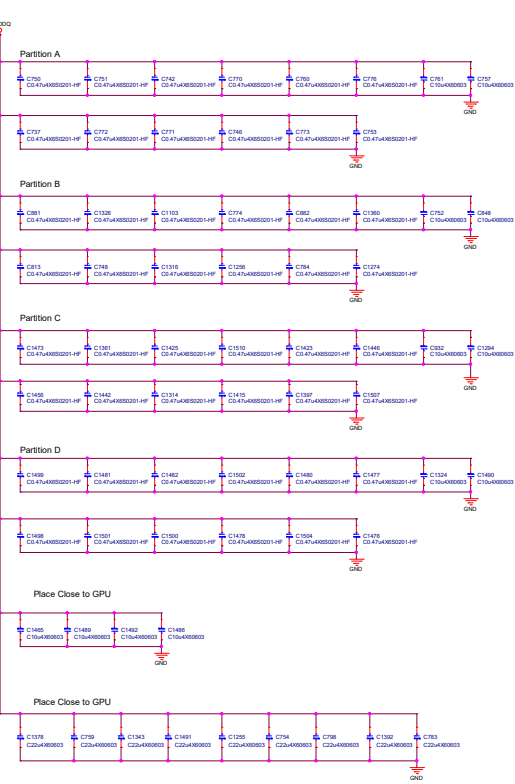




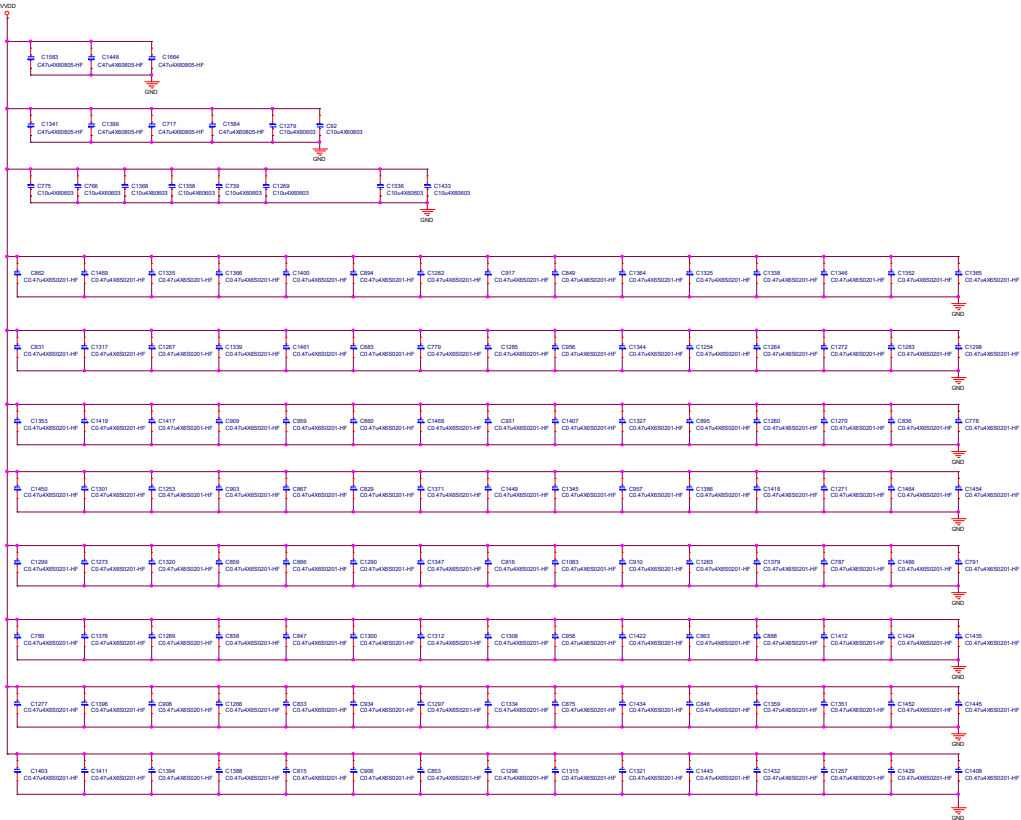




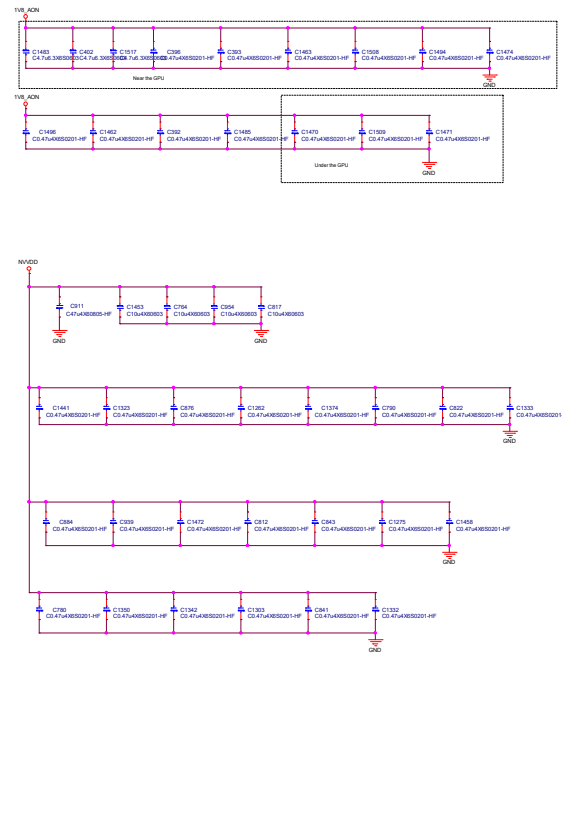
FBVDDQ_GPU



NVDD



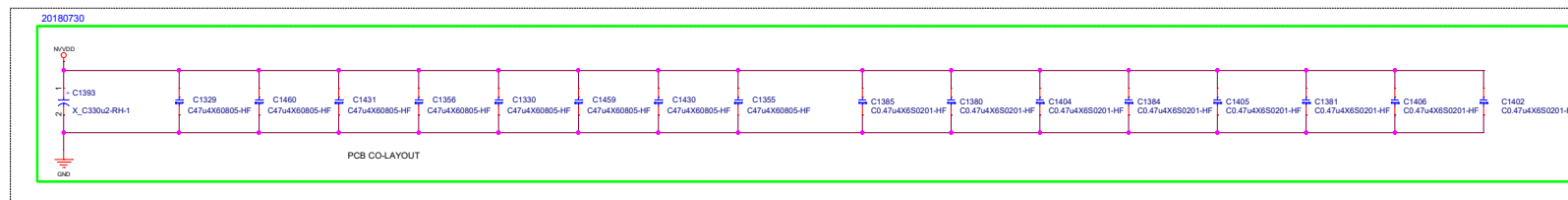
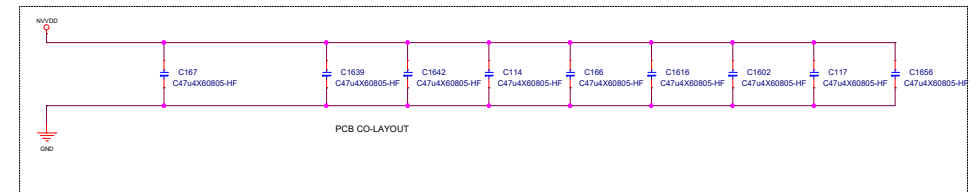
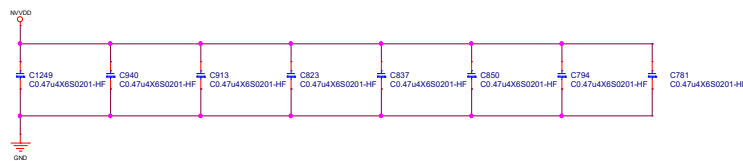
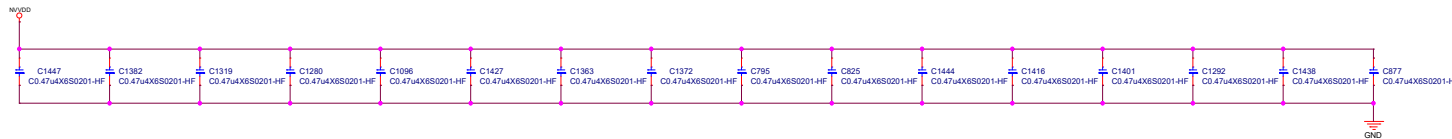
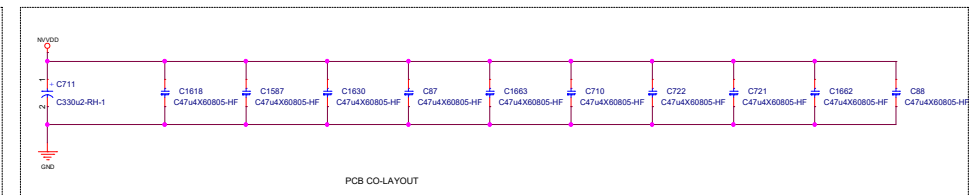
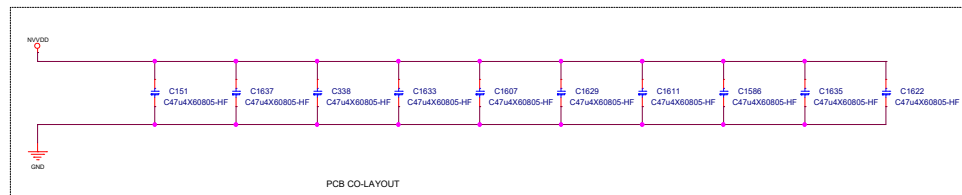
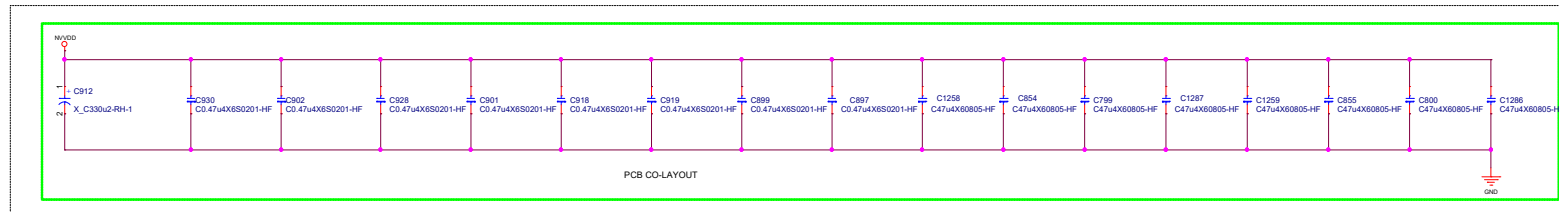
1V8_AON



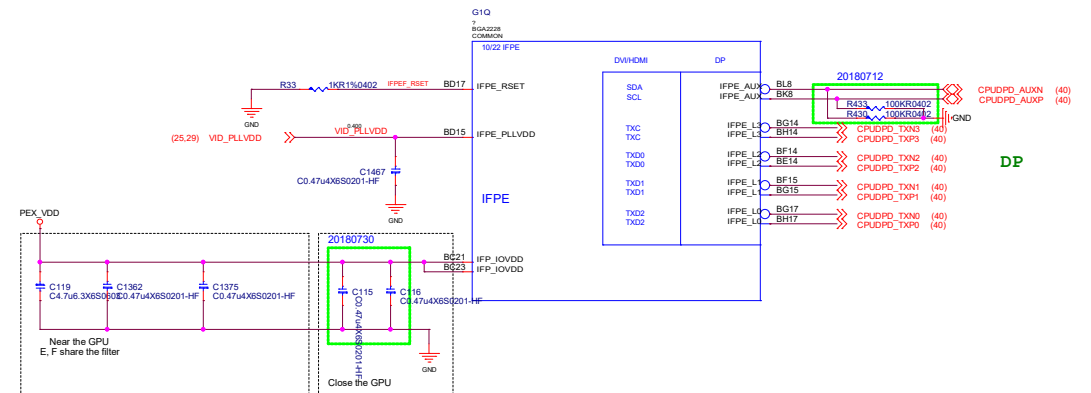
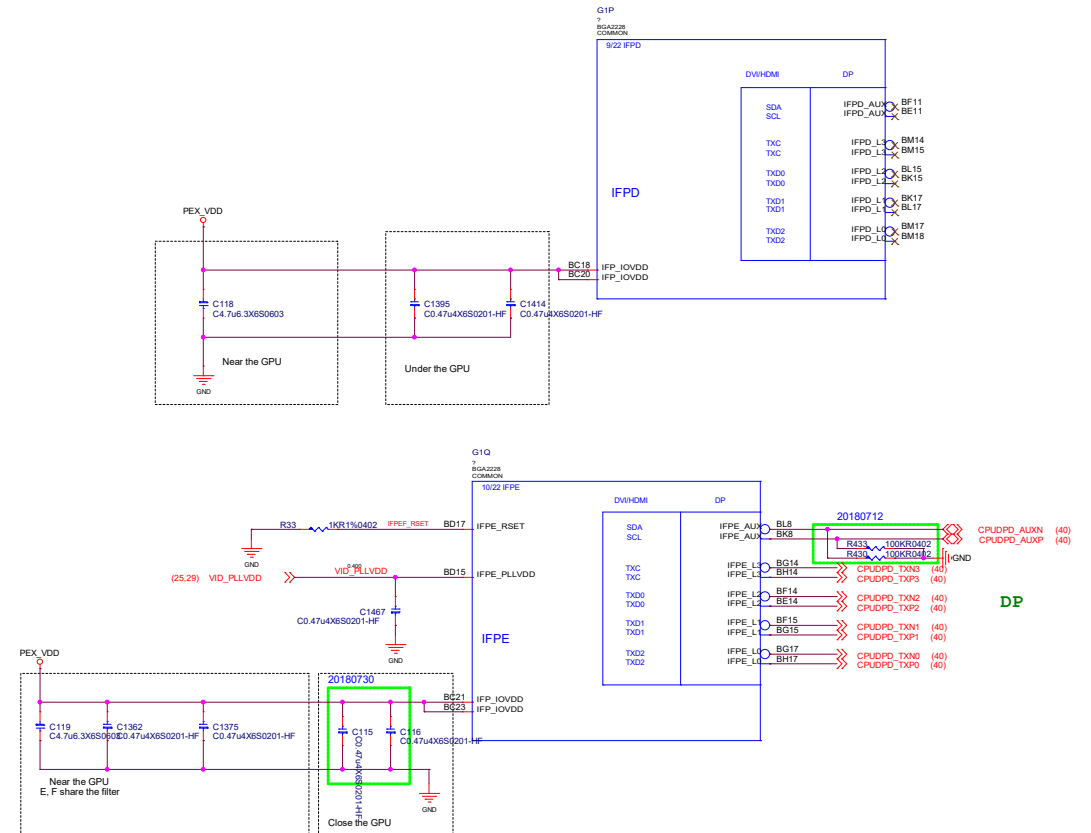
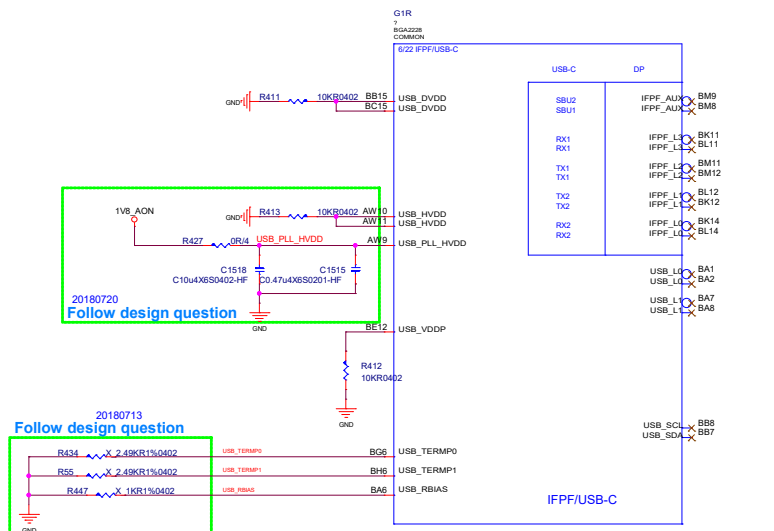
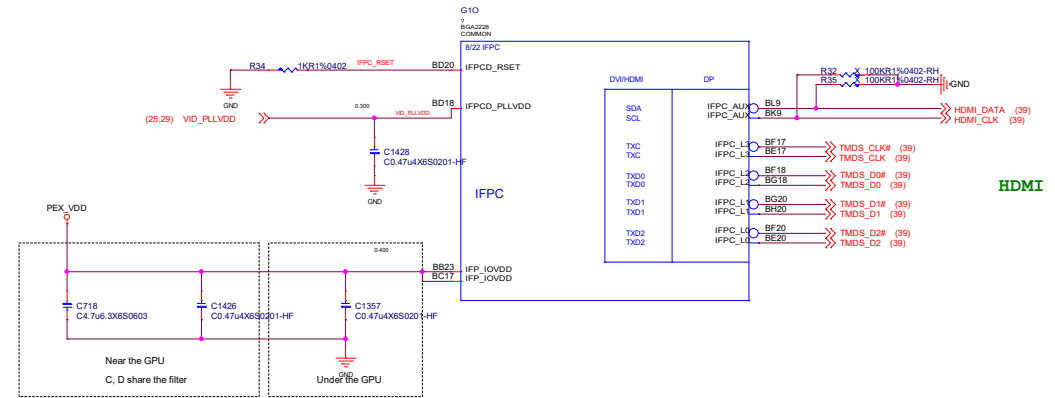
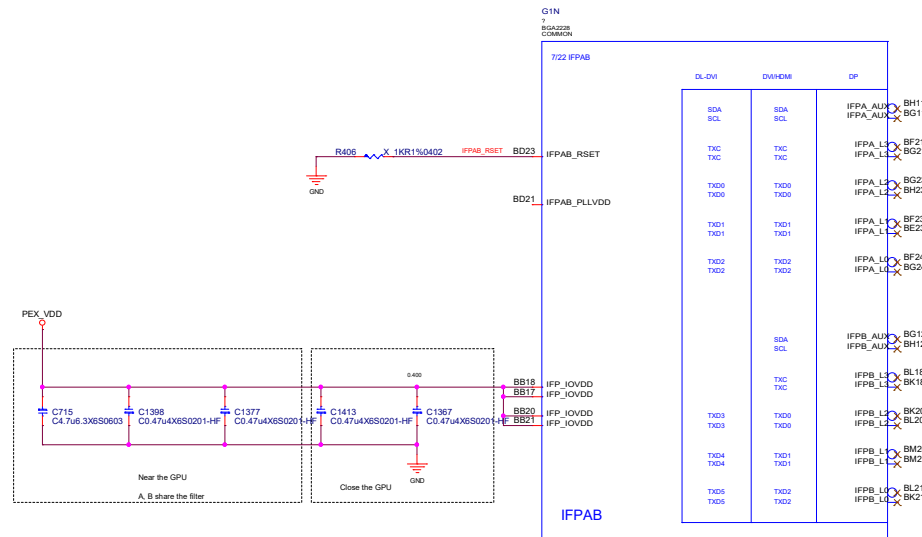
GPU DECOUPLING B

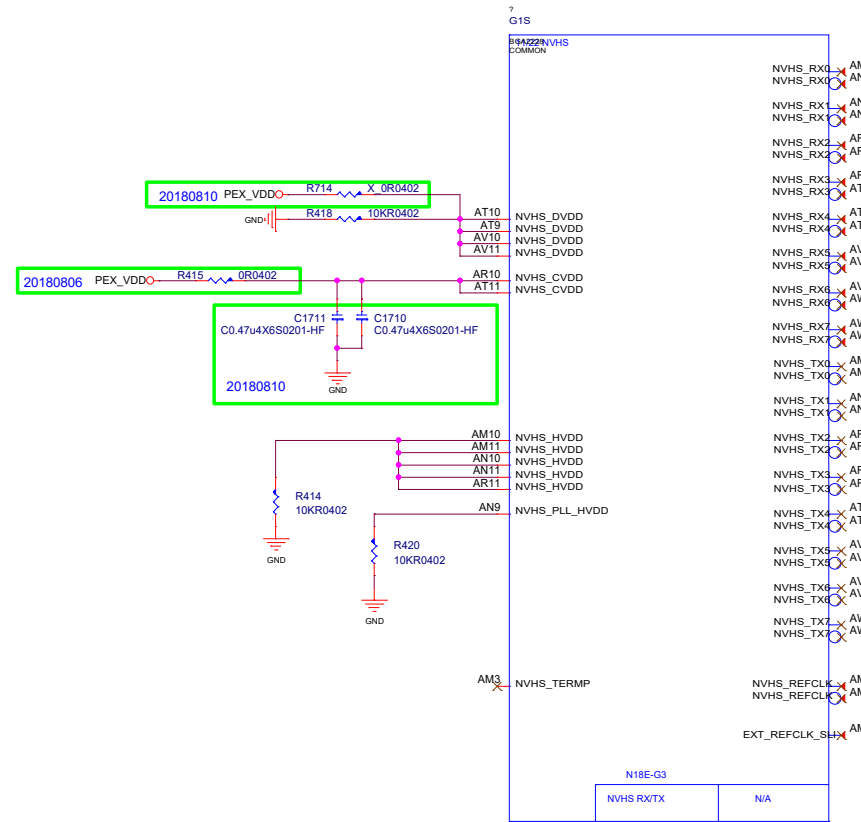
GPU Decoupling

20180730

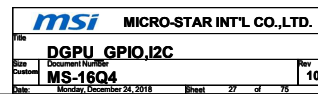
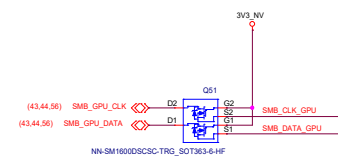


DACA,Display IF





Title			
GPU_NVLink & Framelock			
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H=High :Tied to 1.8V
M=Middle:Tied to 0.9V
L=Low :Tied to 0V

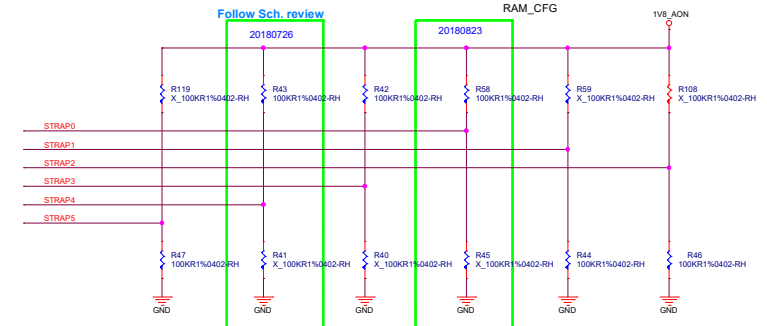
STRAP2	STRAP1	STRAP0	RAMCFG[4:0]		
L	L	L	00000	RAMCFG TBD	
L	L	H	00001	RAMCFG TBD	DEFAULT
L	H	L	00010	RAMCFG TBD	
L	H	H	00011	RAMCFG TBD	
H	H	L	00110	RAMCFG TBD	
H	H	H	00111	RAMCFG TBD	

ROM_SO	ROM_SI	ROM_SCLK	DUMMY[2:0],FS_OVERT	1:ENABLE 0:DISABLE	
L	L	L	XXX1	FS_OVERT ENABLE	DEFAULT
L	L	M	XXX0	FS_OVERT DISABLE	

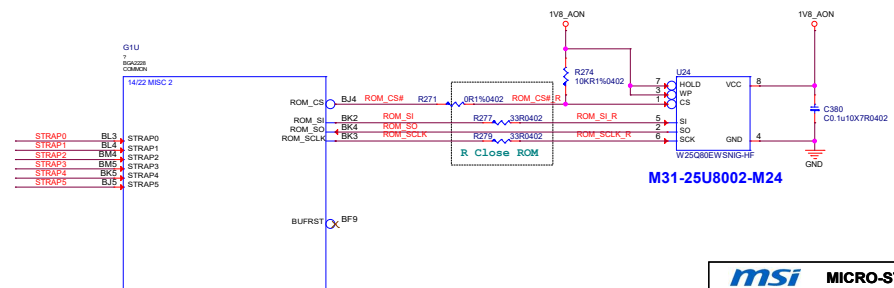
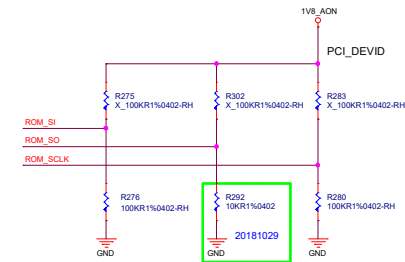
STRAP5	STRAP4	STRAP3	SMB_ALT_ADDR	DEVID_SEL	PCIE_CFG	VGA_DEVICE
M	H	H	1	1	1	1
M	H	L	1	1	1	0
M	L	H	1	1	0	1
M	L	L	1	1	0	0
L	H	M	1	0	1	1
L	M	H	1	0	1	0
L	M	L	1	0	0	1
L	L	M	1	0	0	0
H	H	H	0	1	1	1
H	H	L	0	1	1	0
H	L	H	0	1	0	1
H	L	L	0	1	0	0
L	H	H	0	0	1	1
L	H	L	0	0	1	0
L	L	H	0	0	0	1
L	L	L	0	0	0	0

RAMCFG[4:0]	DENSITY	WIDTH	VENDOR
00000	8Gb	256-bit	Samsung
00001	8Gb	256-bit	Micron
00010	8Gb	256-bit	Hynix
00110	16Gb	256-bit	Hynix
00111	16Gb	256-bit	Samsung
01000	16Gb	256-bit	Micron

X_SAMSUNG_8G_GDDR6
M12-80325J5-S02

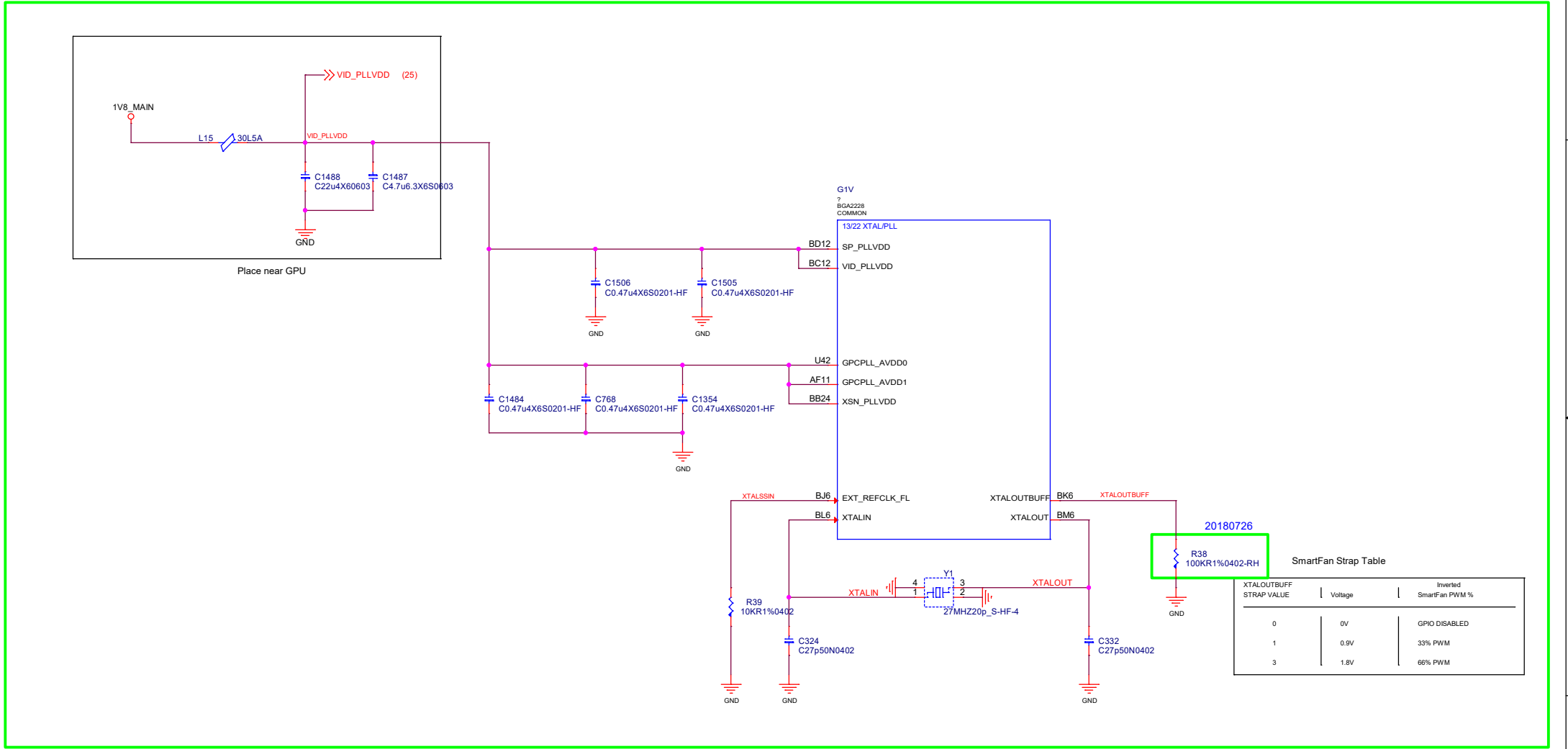


- 1:SMB_ALT_ADDR ENABLE
- 0:SMB_ALT_ADDR DISABLE
- 1:DEVID_SEL REBRAND
- 0:DEVID_SEL ORIGINAL
- 1:PCIE_CFG LOW POWER
- 0:PCIE_CFG HIGH POWER
- 1:VGA_DEVICE ENABLE
- 0:VGA_DEVICE DISABLE

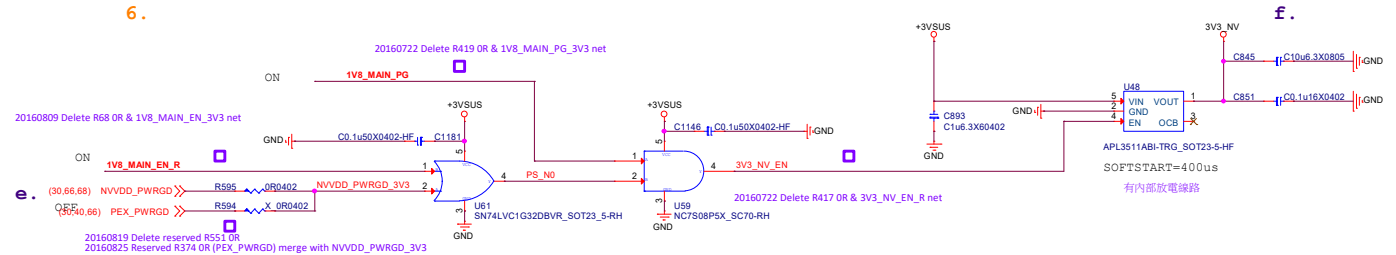
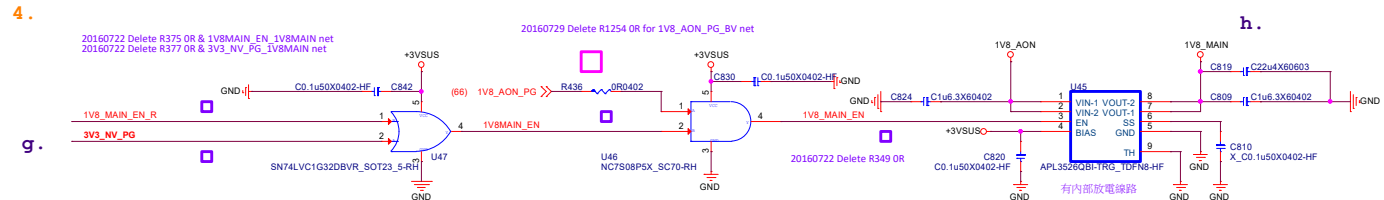
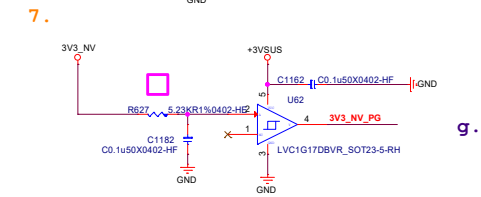
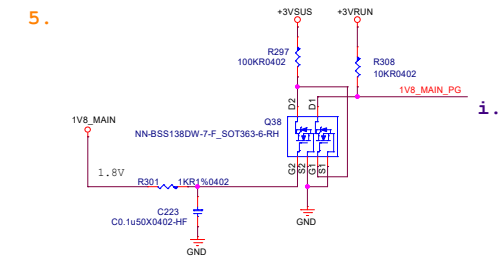
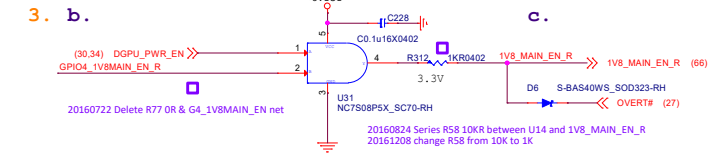
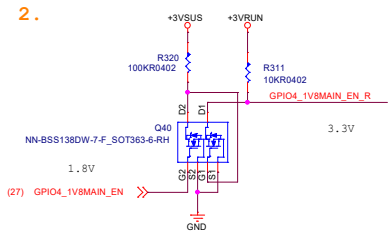


M31-25U8002-M24

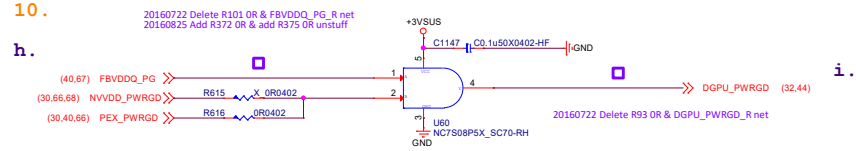
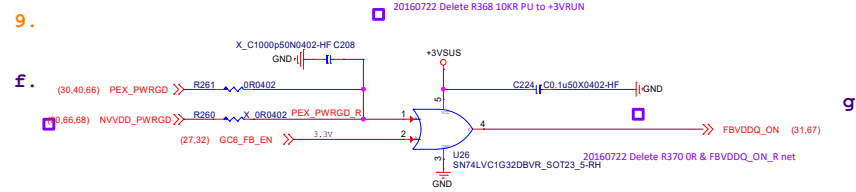
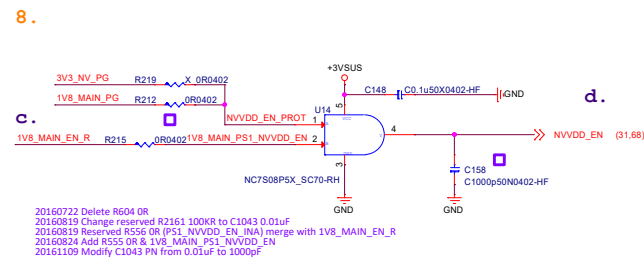
Check!!!!!!



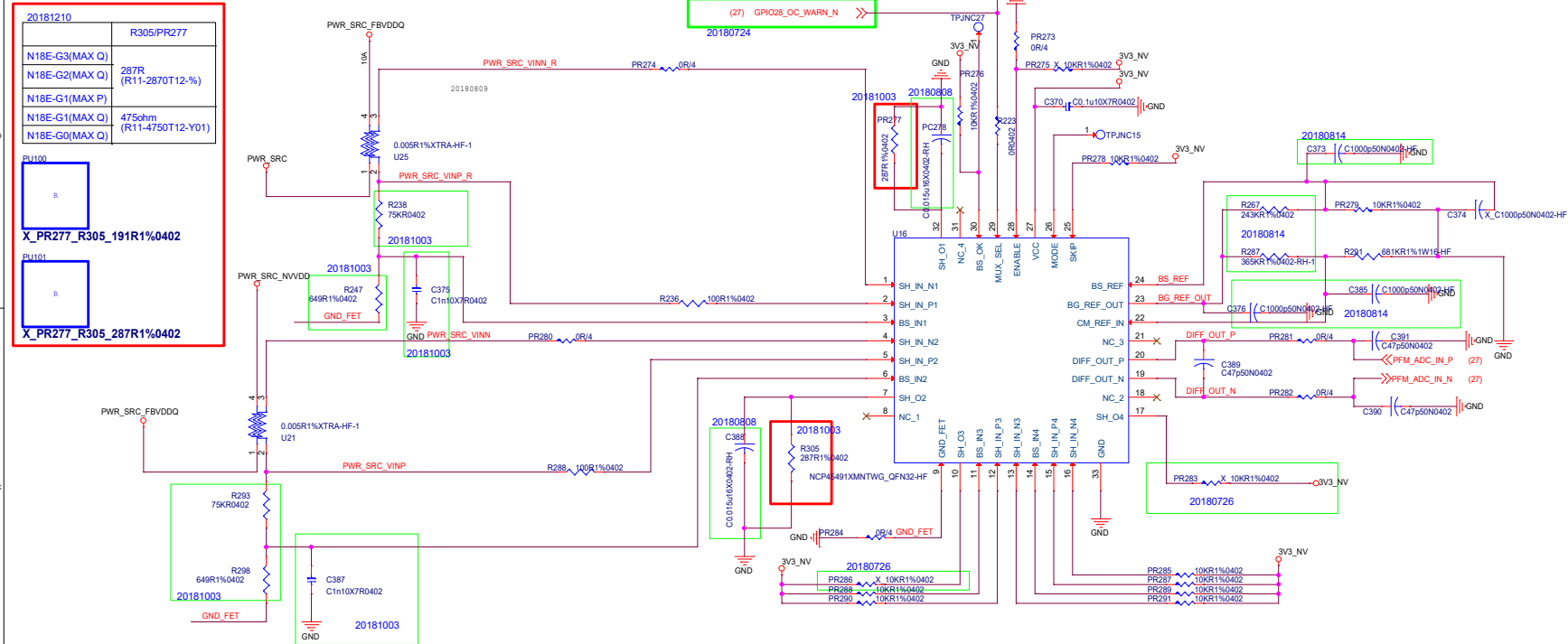
The ramp time for any rail must be more than 40us and is recommended to be less than 2ms
From 1V8_MAIN_EN to PEX_VDD must NOT exceed 4ms



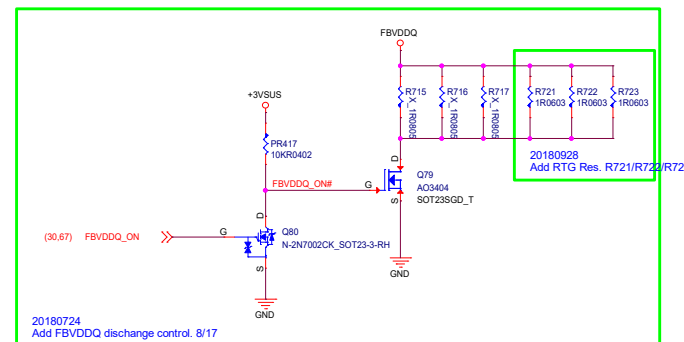
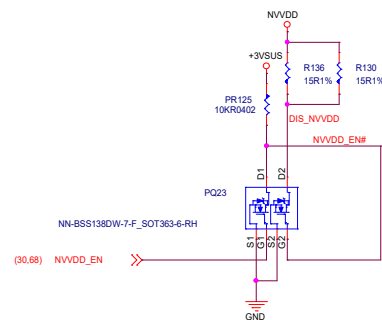
The propagation delay between 1V8_MAIN_EN and the NVVDD_EN needs to be less than 300us during both power up and power down



DGPU_Power Control

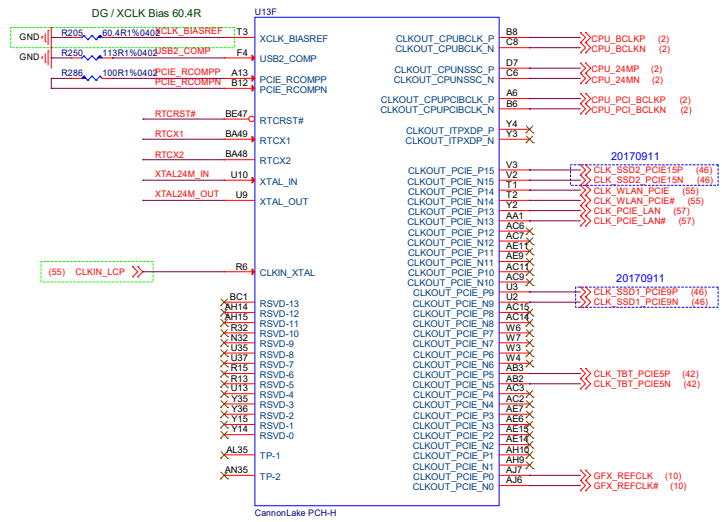


Discharge



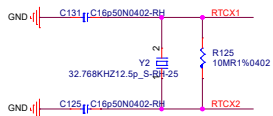
PEX_VDD 内部放電4ms
3V3_AON内部放電 2ms
1V8AON内部放電2ms
1V8 MAIN内部放電320us

HM370 (RTC/PCIE_Clock/Clock/RSVD)

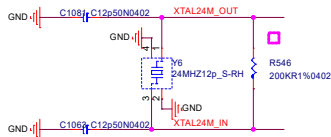


20170828 R2175 change to 200K to follow DG and CRB

RTC Block(Close to PCH)

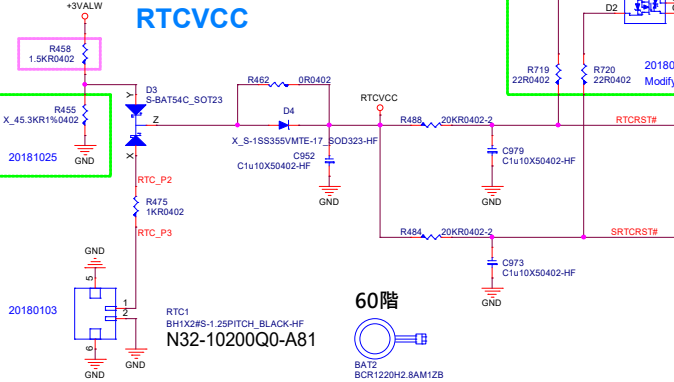


24MHz Clock



20170731 change R2185 to 1.5K to follow DG

RTCVCC



60階

RTCT1
BH1X2S-1.25PITCH_BLACK-HF
N32-10200Q0-A81
BAT2
BCR1220H2.8AM1ZB
D06-0105701-K26

Functional Strap Definitions

SPKR / GPP_B14

The signal has a weak internal pull-down.
0 = Disable Top Swap mode. (Default)

GSPID_MOSI / GPP_B18

The signal has a weak internal pull-down.
0 = Disable No Reboot mode. (Default)
1 = Enable No Reboot mode.

GSPID_MOSI / GPP_B22

This Signal has a weak internal pull-down.
Bit 6 Boot BIOS Destination
0 SPI (Default)
1 LPC

SML1ALERT# / PCHHOT# / GPP_B23

This signal has an internal pull-down.

GPP_H12

This signal has a weak internal pull-down.

GPP_H15

External pull-up is required. Recommend 100K if pulled up to 3.3V or 75K if pulled up to 1.8V.

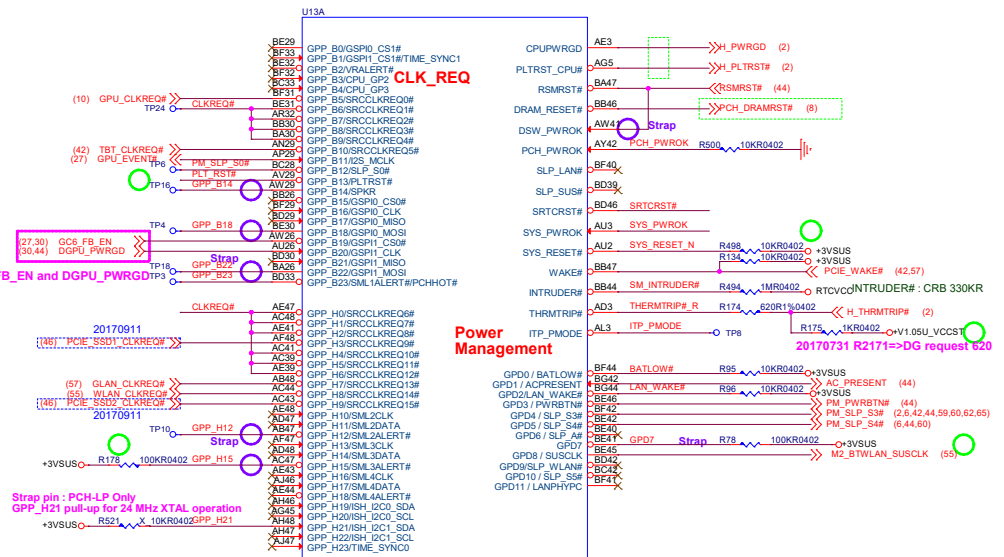
GPPD7

External pull-up is required. Recommend 100K. This strap should sample HIGH. There should NOT be any on-board device driving it to opposite direction during strap sampling

DG/ RTC Well Input Strap

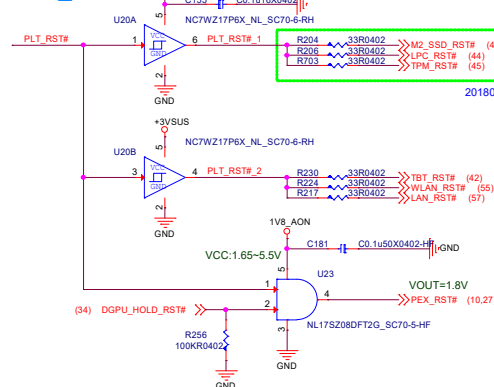
RSMRST# & DSW_PWROK, PCH_PWROK : PD
RTCRST#, SRTCST#, INTRUDER# : PU

HM370 (CLKREQ/ACPI)

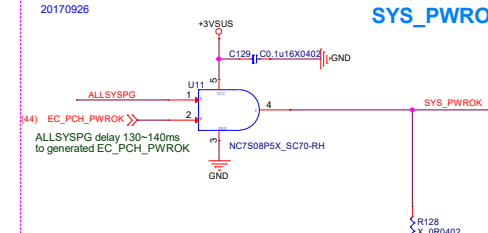


Power Management

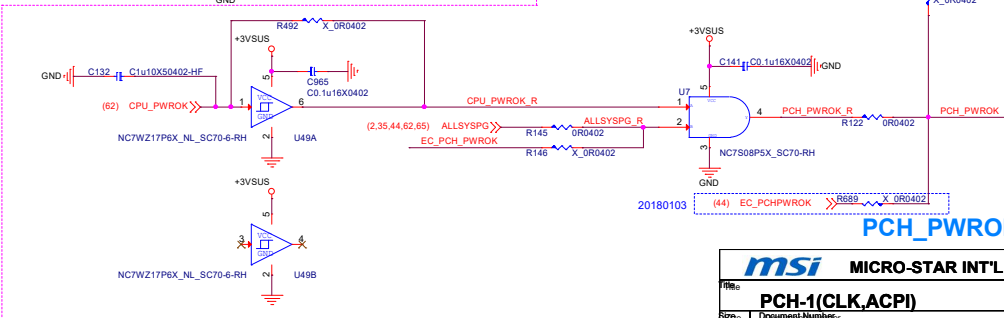
PLT_RST#



SYS_PWROK



PCH_PWROK



HM370 (DMI/PCIE/USB3.1/USB2.0/CNVi)

Figure 14-1. High Speed I/O (HSIO) Lane Multiplexing in PCH-H

Flex I/O Lane	0	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	21	22	23	24	25	26	27	28	29
High Speed I/O (HSIO) Type and Lane	USB3.1 Gen1/Gen2 #1	USB3.1 Gen1/Gen2 #2	USB3.1 Gen1/Gen2 #3	USB3.1 Gen1/Gen2 #4	USB3.1 Gen1/Gen2 #5	USB3.1 Gen1/Gen2 #6	USB3.1 Gen1/Gen2 #7	USB3.1 Gen1/Gen2 #8	USB3.1 Gen1/Gen2 #9	USB3.1 Gen1/Gen2 #10	PCIe* #5	PCIe* #6	PCIe* #7	PCIe* #8	PCIe* #9	PCIe* #10	PCIe* #11	PCIe* #12	PCIe* #13	PCIe* #14	PCIe* #15	PCIe* #16	PCIe* #17	PCIe* #18	PCIe* #19	PCIe* #20	PCIe* #21	PCIe* #22	PCIe* #23	PCIe* #24
Intel® RST Support											No Support	No Support			Yes	Yes	Yes	Yes	Yes	No Support	No Support	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes

SKU	USB3.1 Gen1/Gen2 #1	USB3.1 Gen1/Gen2 #2	USB3.1 Gen1/Gen2 #3	USB3.1 Gen1/Gen2 #4	USB3.1 Gen1/Gen2 #5	USB3.1 Gen1/Gen2 #6	USB3.1 Gen1/Gen2 #7	USB3.1 Gen1/Gen2 #8	USB3.1 Gen1/Gen2 #9	USB3.1 Gen1/Gen2 #10	PCIe* #5	PCIe* #6	PCIe* #7	PCIe* #8	PCIe* #9	PCIe* #10	PCIe* #11	PCIe* #12	PCIe* #13	PCIe* #14	PCIe* #15	PCIe* #16	PCIe* #17	PCIe* #18	PCIe* #19	PCIe* #20	PCIe* #21	PCIe* #22	PCIe* #23	PCIe* #24
HM370	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	LAN	LAN	LAN	LAN	LAN	LAN	LAN	LAN	LAN	LAN	LAN	LAN	LAN	LAN	LAN	LAN	LAN	LAN	LAN	LAN
QM370	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	LAN	LAN	LAN	LAN	LAN	LAN	LAN	LAN	LAN	LAN	LAN	LAN	LAN	LAN	LAN	LAN	LAN	LAN	LAN	LAN
CM246	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	LAN	LAN	LAN	LAN	LAN	LAN	LAN	LAN	LAN	LAN	LAN	LAN	LAN	LAN	LAN	LAN	LAN	LAN	LAN	LAN

- Added 4 new PCIe 3.0 lanes versus KBL-H platform.
- GbE LAN removed from lane 10 and SATA #0/#1 option moved from lanes 15/16 to 19/20 to better balance PHY clocking.

PCIE 9-12(M2)

USB 3.1 CNT-2 USB 3.1 CNT-1

USB 3.1 CNT-3

Ref DG Section 18.6
- use Port 14 with CNVi Solution

BT

FP FOR WS

Webcam

FP FOR 16Q4

Multi-Color KB

USB 3.1 CNT-2

USB 3.1 CNT-3

USB 3.1 CNT-1

USB 2.0

USB 3.1

CNVi

CannonLake PCH-H

U13C



This signal has a weak internal pull-down.
0 = Port F is not detected. (Default)
1 = Port F is detected.

HM370 (HDA/GPIO/TJAG)

Functional Strap Definitions

SMBALERT# / GPP_C2

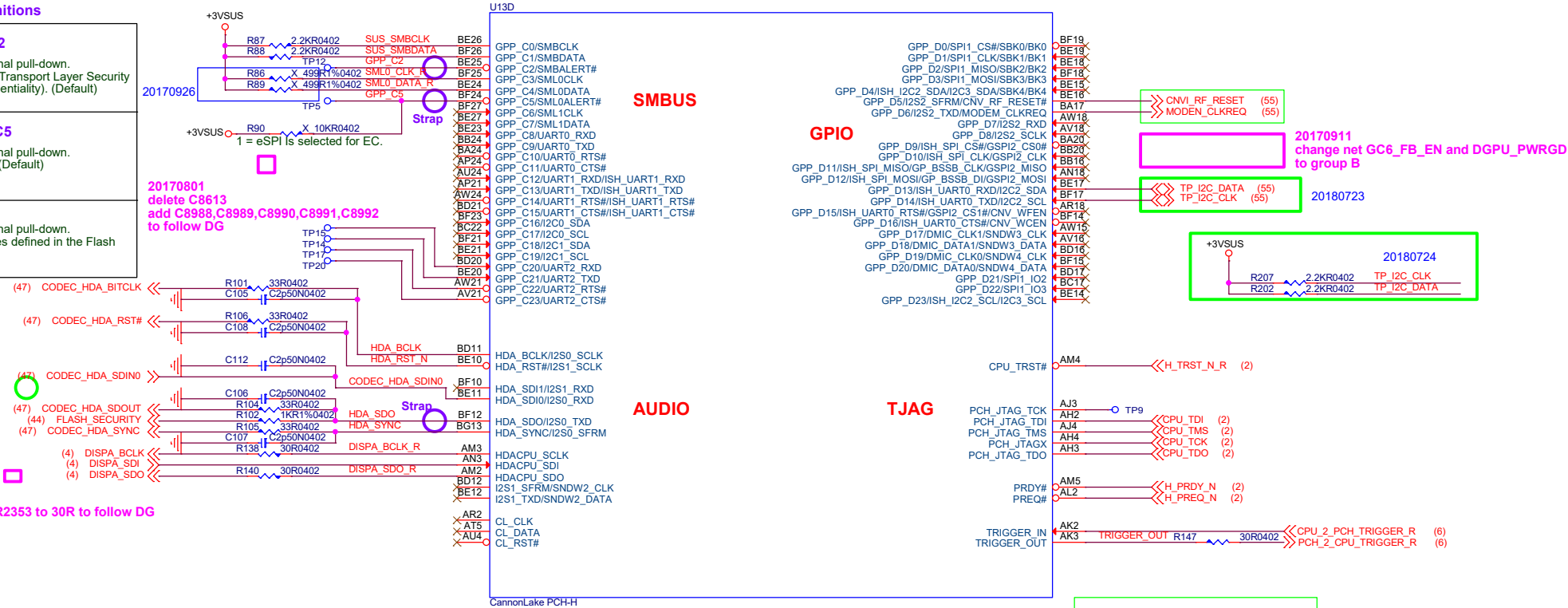
This signal has a weak internal pull-down.
0 = Disable Intel ME Crypto Transport Layer Security (TLS) cipher suite (no confidentiality). (Default)
1 = eSPI is selected for EC.

SML0ALERT# / GPP_C5

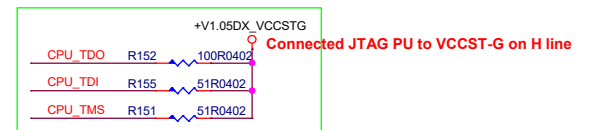
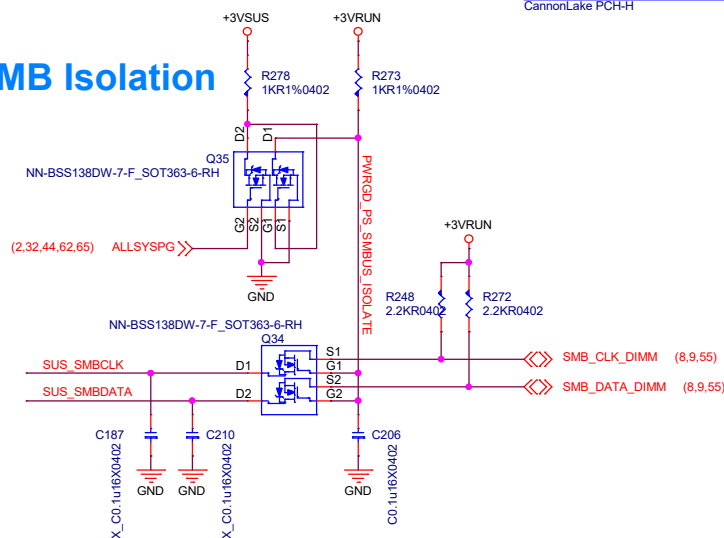
This signal has a weak internal pull-down.
0 = LPC is selected for EC. (Default)
1 = eSPI is selected for EC.

HDA_SDO

This signal has a weak internal pull-down.
0 = Enable security measures defined in the Flash Descriptor. (Default)
1 = Disable security measures defined in the Flash Descriptor.

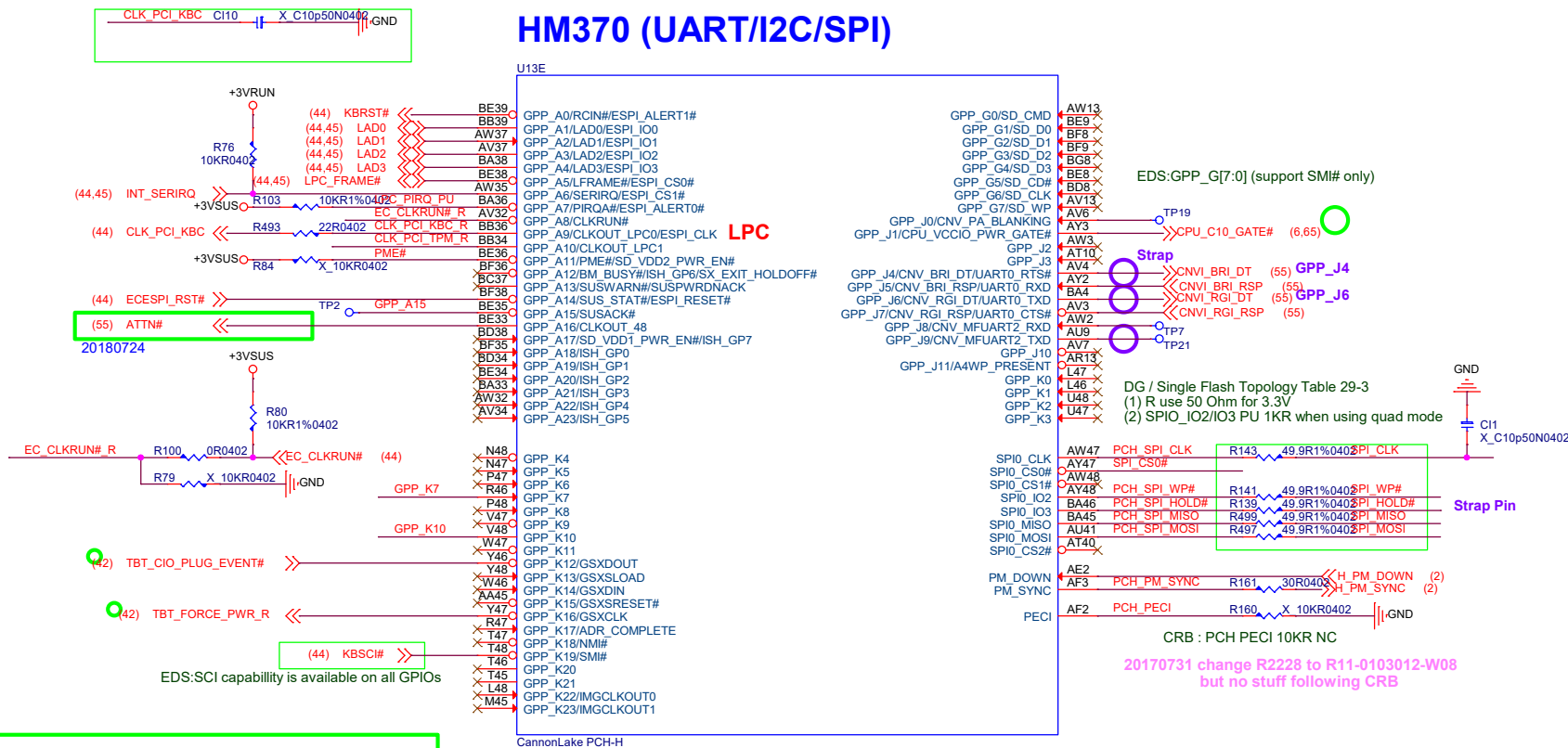


SMB Isolation

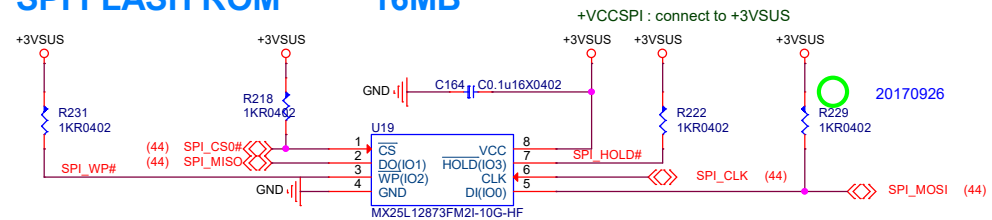


ref DG / Chapter Platform and Test Hooks
CPU_TDO : PU 100R Near CPU (DG : R1)
PU 100R Near PCH (DG : R3)
CPU_TDI : PU 51R Near PCH (DG : R4)
CPU_TMS : PU 51R Near PCH (DG : R5)
CPU_TCK : 51R to GND Near CPU (DG : R2)

20170731 change R2226 unstuff to gollow CRB



SPI FLASH ROM 16MB



M31-2512893-W03
M-IC FLASH,128M(16Mx8bit),10ms,SOIC-8pin(208mil),WINBOND/W25Q128JVSIQ,2.7V,3.6V,SPI,,HALOGEN FREE

M31-2512832-M24
M-IC FLASH,128M(16Mx8bit),40ms,SOP-8pin,MXICMX25L12873FM2I-10G(T),2.7V,3.6V,SPI,,HALOGEN FREE

msi MICRO-STAR INT'L CO.,LTD.		
Title		
PCH-5(UART/I2C/SPI)		
Size	Document Number	Rev
	MS-16Q4	10
Date:	Monday, December 24, 2018	Sheet 36 of 75

ref DG / Table 50-6 Decoupling Requirements

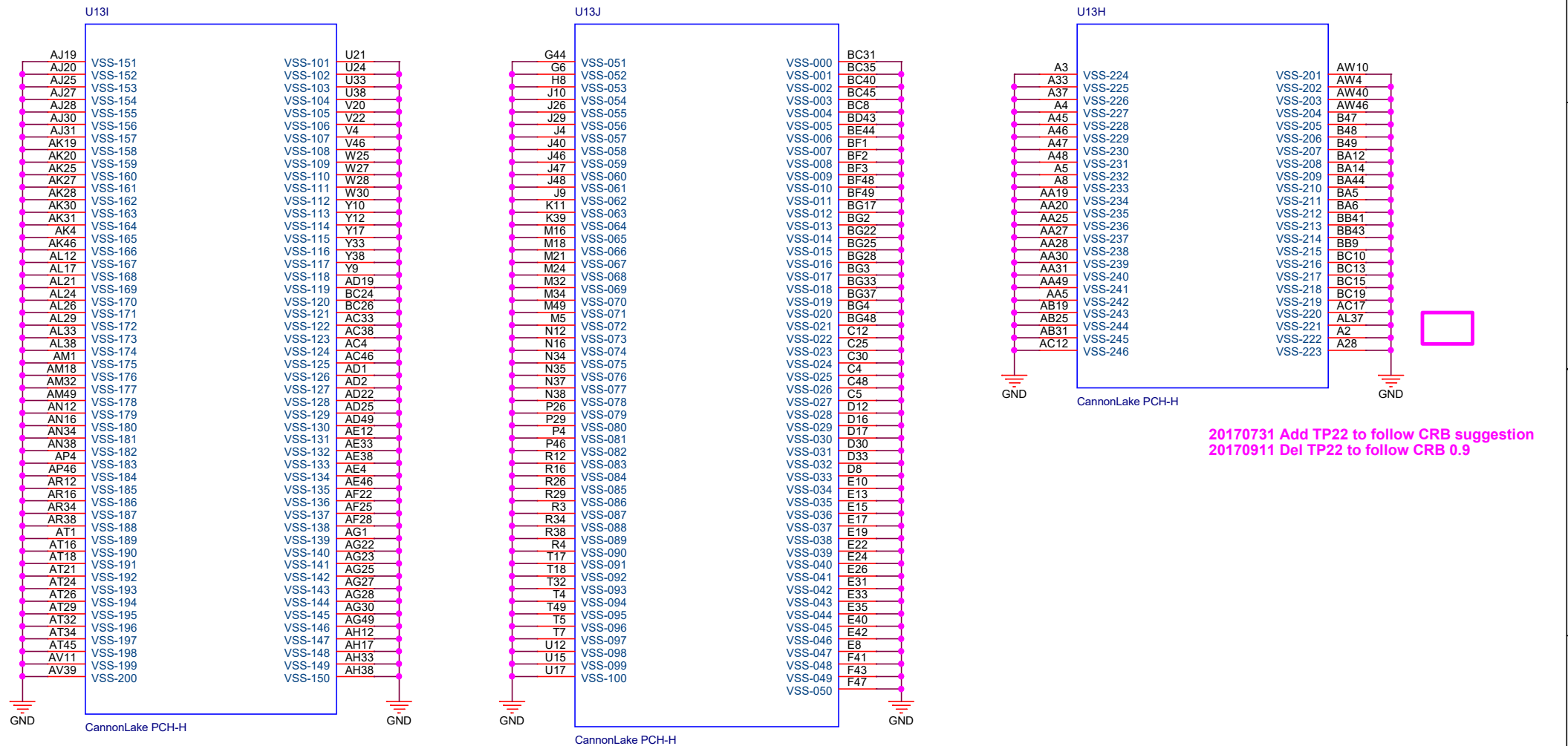


GPIO Group	Power Pins	Voltage
Primary Well Group A (GPP_A)	VCCPGPPA	1.8V or 3.3V
Primary Well Group B (GPP_B)	VCCPGPPBC	1.8V or 3.3V
Primary Well Group C (GPP_C)	VCCPGPPD	1.8V or 3.3V
Primary Well Group D (GPP_D)	VCCPGPPD	1.8V or 3.3V
Primary Well Group E (GPP_E)	VCCPGPPF	1.8V or 3.3V
Primary Well Group F (GPP_F)	VCCPGPPF	1.8V or 3.3V
Primary Well Group G (GPP_G)	VCCPGPPG_3P3 or VCCPRIM_1P8	1.8V or 3.3V
Primary Well Group H (GPP_H)	VCCPGPPHK	1.8V or 3.3V
Primary Well Group K (GPP_K)	VCCPGPPHK	1.8V or 3.3V
Primary Well Group I (GPP_I)	VCCPRIM_3P3	3.3V Only
Primary Well Group J (GPP_J)	VCCPRIM_1P8	1.8V Only
Deep Sleep Well Group (GPD)	VCCDSW_3P3	3.3V Only

Note: Except for GPP_G group, the operating voltage of a GPIO group having voltage configurability (3.3V or 1.8V) is selected by both connecting the corresponding power pin and setting the group-voltage-selection soft strap to the desired voltage. GPP_G group voltage is selected by setting the corresponding soft strap only.

Name	Description
VCCA_BCLK_1P05	Analog supply for BCLK circuitries: 1.05V
VCCA_SRC_1P05	Analog supply for PCIe clock circuitries: 1.05V
VCCA_XTAL_1P05	Analog supply for XTAL circuitries: 1.05V
VCCDUSB_1P05	Supply for USB digital logic: 1.05V
VCCAPLL_1P05	Analog supply for BCLK/DMI/Audio PLLs: 1.05V. This rail can be derived from the VCCPRIM_1P05 rail with the proper isolation. Refer to the Platform Design Guide for implementation detail.
VCCPRIM_1P05	Primary Well: 1.05V. For PCIe//USB3/SATA MPHY logic, I/O blocks, SRAM, JTAC, CNVI.
VCCDSW_1P05	Deep Sx Well: 1.05V. This rail is generated by on die DSW low dropout (LDO) linear regulator to supply DSW core logic. Board needs to connect a 1uF capacitor to this rail and power should NOT be driven from the board.
VCCPRIM_MPHY_1P05	Mod PHY Primary: 1.05V. Primary supply for PCIe/USB3/SATA MPHY logic and PCIe/USB PLL dividers.
VCCAMPHYPLL_1P05	Analog supply for USB3, PCIe Gen 2/Gen 3, and SATA3 PLLs: 1.05V. Refer to the Platform Design Guide for filtering and decoupling recommendations.
VCCPRIM_1P8	1.8V Primary Well.
VCCPRIM_3P3	3.3V Primary Well.
VCCSPI	SPI Primary Well 3.3V or 1.8V, for SPI interface.
VCCHDA	HDA Audio Power 3.3V, 1.8V, or 1.5V, for Intel® High Definition Audio.
VCCDSW_3P3	3.3V Deep Sx Well.
VCCRTC	<p>RTC Well Supply. This rail can drop to 2.0V if all other planes are off. This power is not expected to be shut off unless the RTC battery is removed or drained.</p> <p>Note: VCCRTC nominal voltage is 3.0V. This rail is intended to always come up first and always stay on. It should NOT be power cycled regularly on non-chip battery designs. Refer to the Platform Design Guide, RTC Design Guidelines chapter for latest design recommendations.</p> <p>Note: Implementation should not attempt to clear CMOS by using a jumper to pull VCCRTC low. Clearing CMOS can be done by using a jumper on RTCRST# or GPI.</p>
DCPRTC	RTC decoupling capacitor only. This rail should NOT be driven.
VCCDPHY_1P24	1.24V for CNVI logic. This rail is generated internally with a LDO and needs to be routed to the motherboard so that the rail can be supplied back to the SoC. Refer to the Platform Design Guide for implementation details.
VCCDPHY_EC_1P24	For decoupling capacitor only. This rail should NOT be driven from the motherboard. This rail can optionally be connected to VCCDPHY_1P24 on the motherboard.
VCCPHVLD0_1P8	1.8V Primary Well. On the motherboard, this power pin must be connected to VCCPRIM_1P8 rail in Internal 1.8 V VRM Mode and (LDO) and connect in External 1.8V VRM Mode.
VCCGPAPA	1.8V or 3.3V for GPP_A group.
VCCGPAPBC	1.8V or 3.3V for GPP_B and GPP_C groups.
VCCGPAPD	1.8V or 3.3V for GPP_D group.
VCCGPAPFE	1.8V or 3.3V for GPP_E and GPP_F groups.
VCCGPAPG_3P3	3.3V for GPP_G group.
VCCGPAPHK	1.8V or 3.3V for GPP_H and GPP_K groups.
VCCMPHY_SENSE	1.05V Sense Line.
VSSMPHY_SENSE	0V (Ground) Sense Line.
VSS	Ground.

PCH-H(GND)

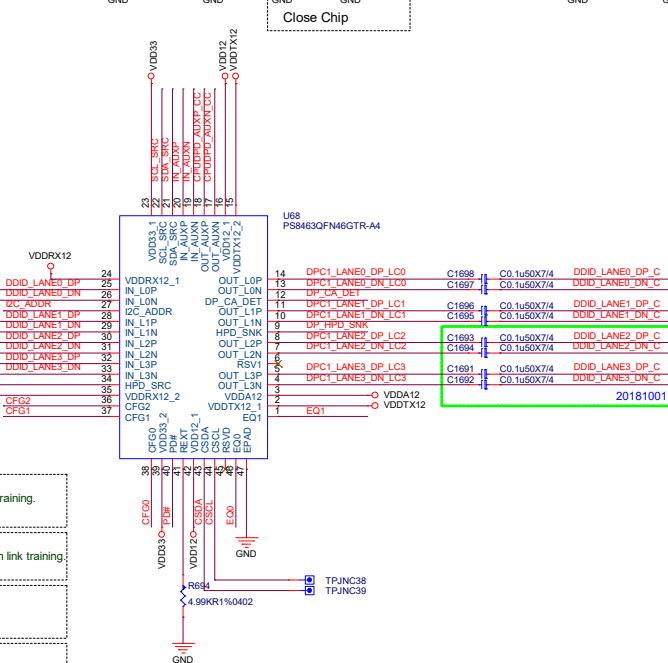
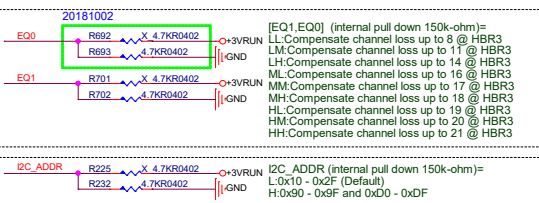
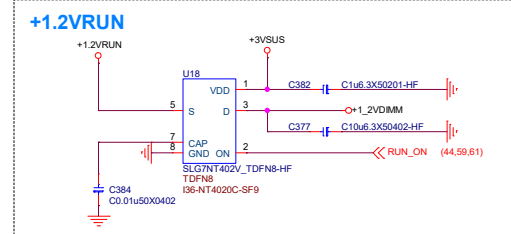
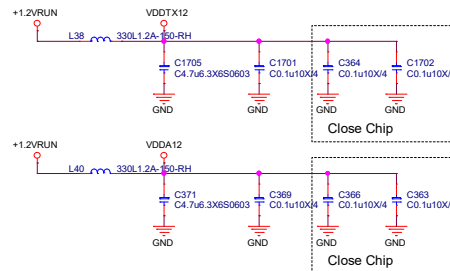
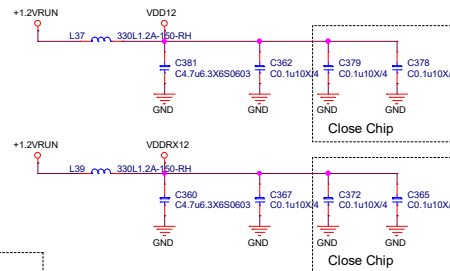
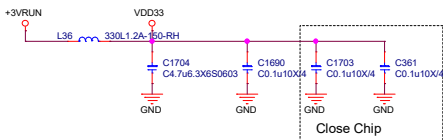


msi

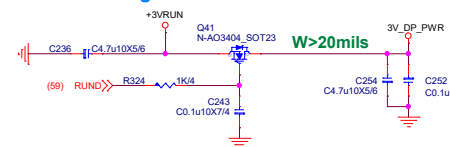
MICRO-STAR INT'L CO.,LTD.

Title			PCH-7(GND)
Size	Document Number	Rev	
Custom	MS-16Q4	10	
Date:	Monday, December 24, 2018	Sheet	38 of 75

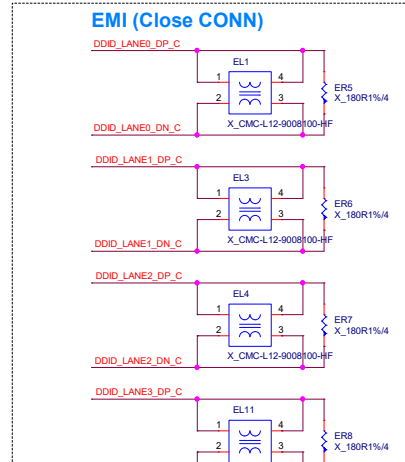
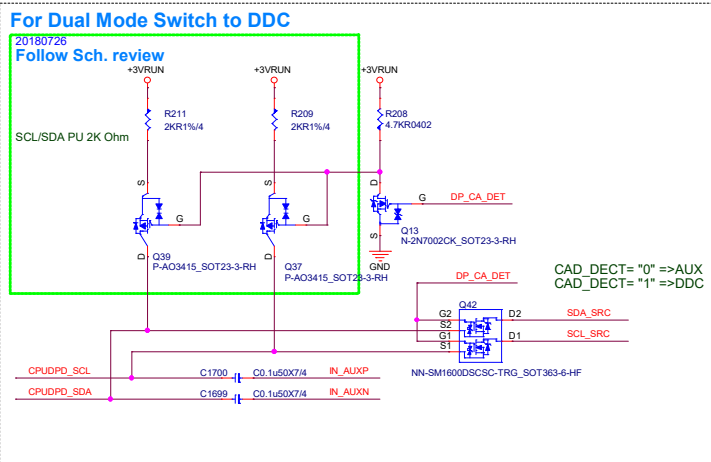
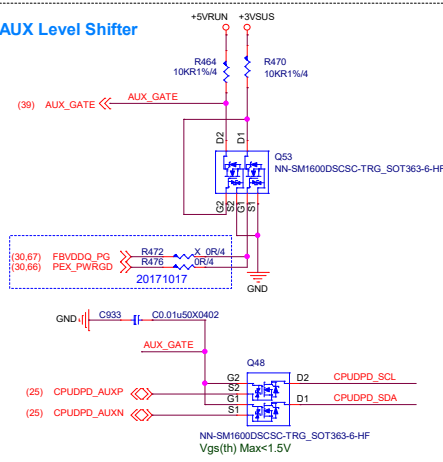
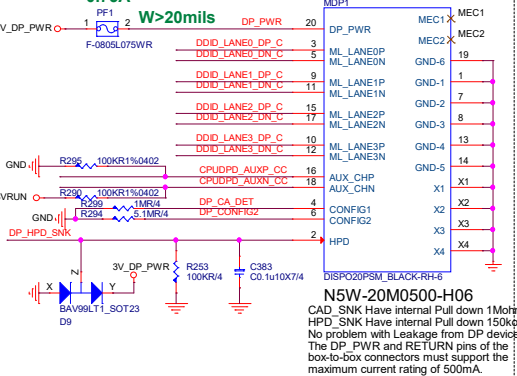
DP 1.4 Retimer (PS8463)

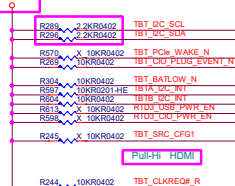
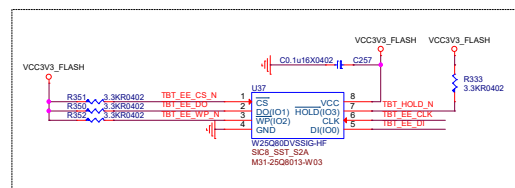
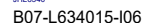


Avoid DP Leakage

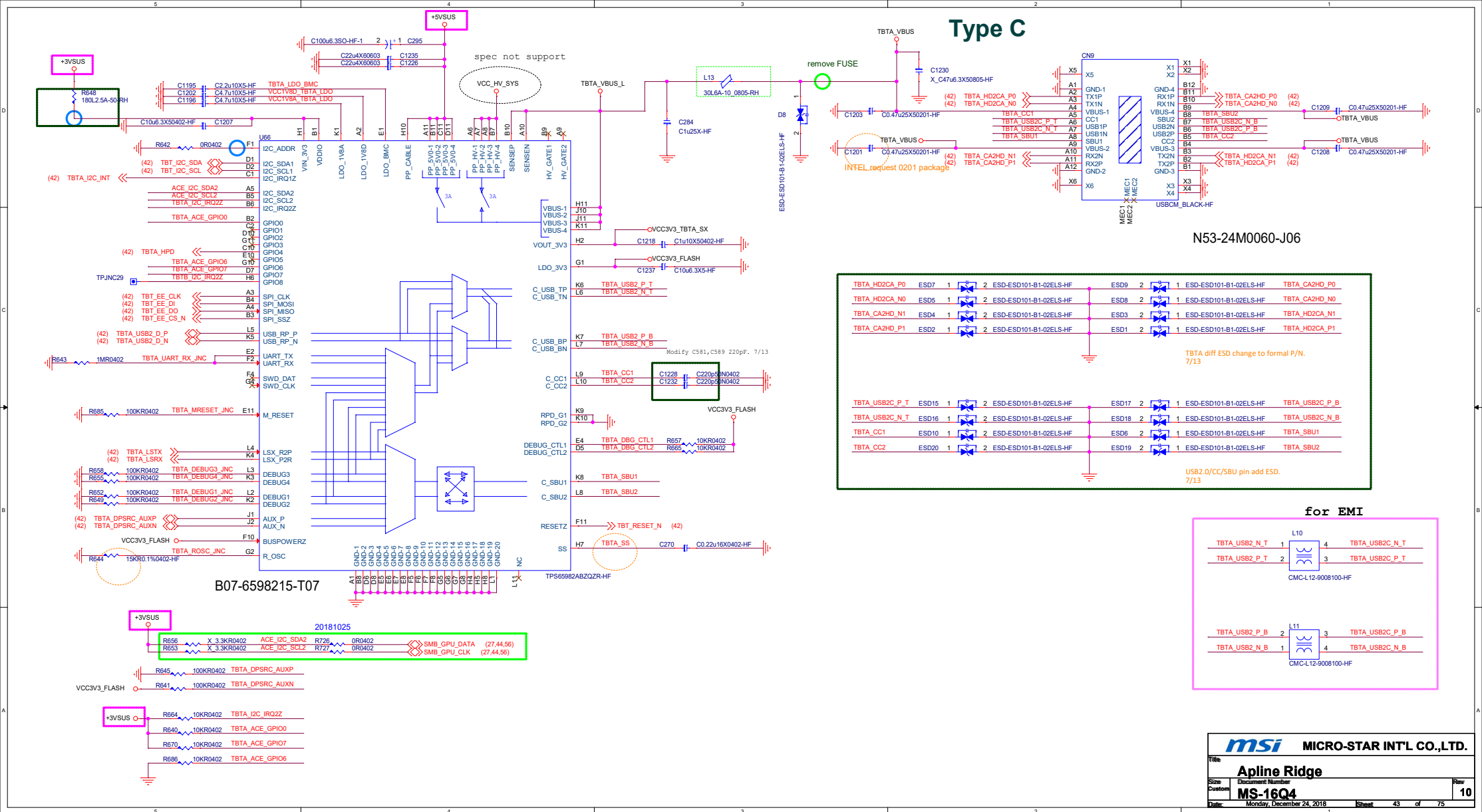


Mini Display Port 0.75A





GPIO	TERMINATION	Power Rail
GPIO_0	10K PU	VCC3V3_LC
GPIO_1	10K PU	VCC3V3_LC
GPIO_2	100K PD	
GPIO_3	100K PD	
GPIO_4	10K PU	VCC3V3_LC
GPIO_5	10K PU	VCC3V3_LC
GPIO_6	100K PD	
GPIO_7	100K PD	
GPIO_8	100K PD	
PCC_GPIO_0	10K PU	VCC3V3_TBT_S
PCC_GPIO_1	10K PU	VCC3V3_TBT_S
PCC_GPIO_2	100K PD	
PCC_GPIO_3	100K PD	
PCC_GPIO_4	10K PU	VCC3V3_TBT_S
PCC_GPIO_5	10K PU	VCC3V3_TBT_S
PCC_GPIO_6	100K PD	

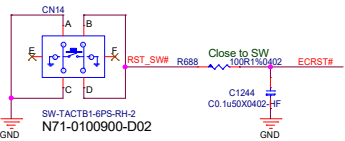


KBC/EC/uP (ENE9028)

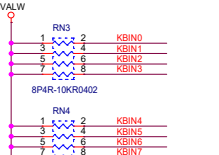
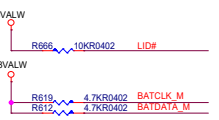
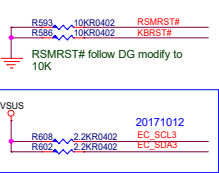
ENE9028 & 9048 Power Notes :

pin9 VCC_LPC;
3.3V for ENE9028's LPC mode.
1.8V for ENE9048's eSPI mode.
pin11 VCC0;
3.3V for ENE9028's PLC function
3.3V for ENE9048's eSPI operation with Pre-Driver.

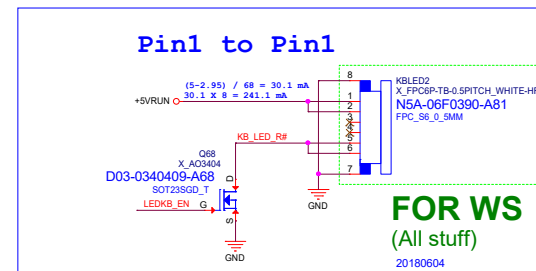
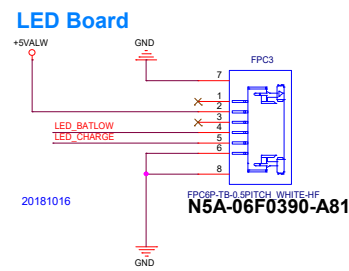
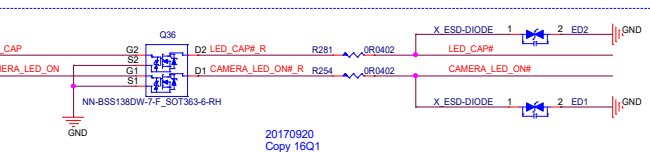
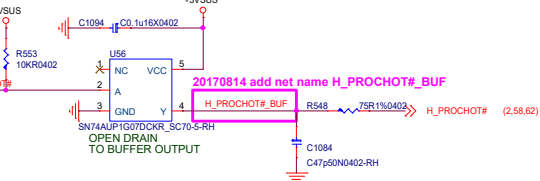
Hardware Reset



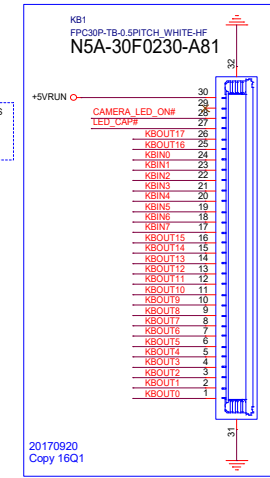
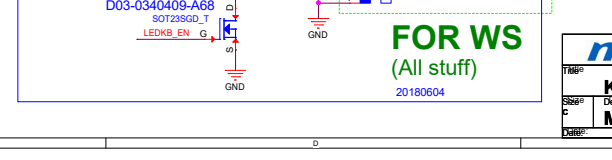
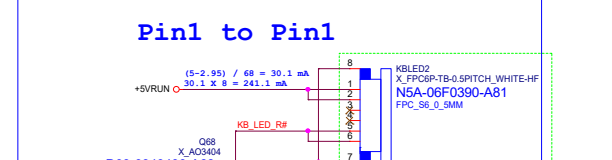
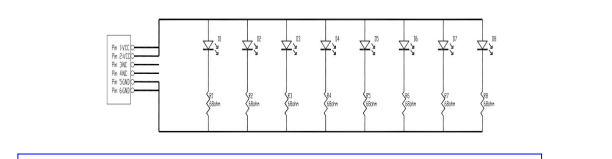
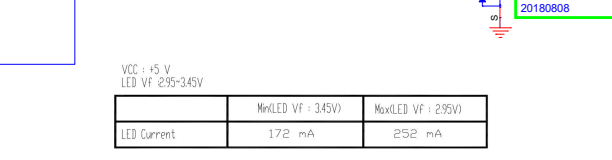
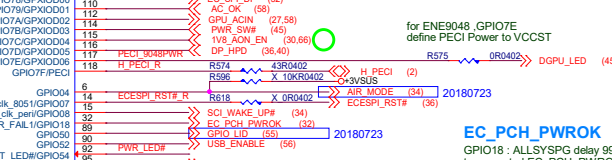
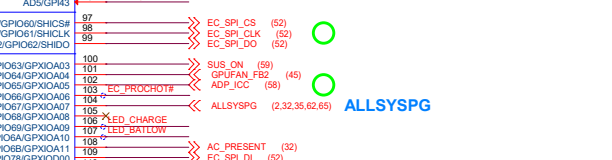
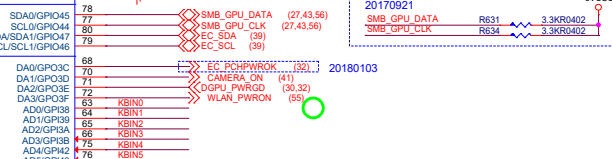
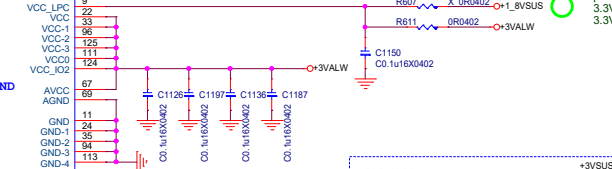
PU/PD



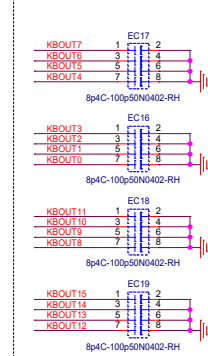
EC_PROCHOT#



When use ENE9048 eSPI mode
PCH's VCCPGPA must be 1.8V

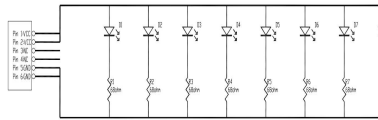


For EMI

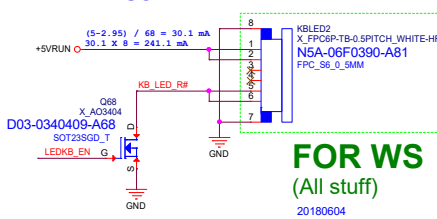


VCC : +5 V
LED VF : 2.95-3.45V

	MxILED VF : 3.45V	MxILED VF : 2.95V
LED Current	172 mA	252 mA

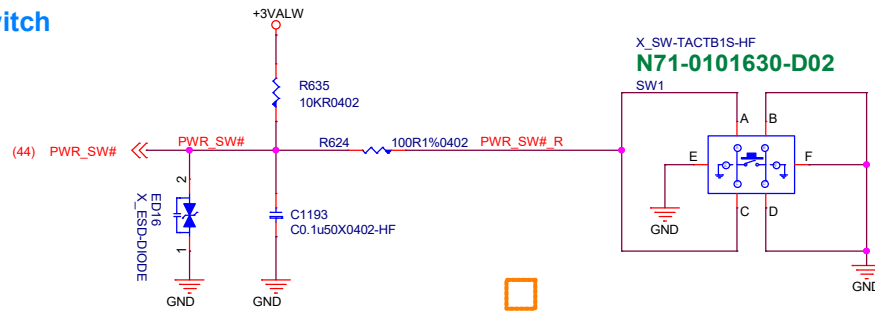


Pin1 to Pin1

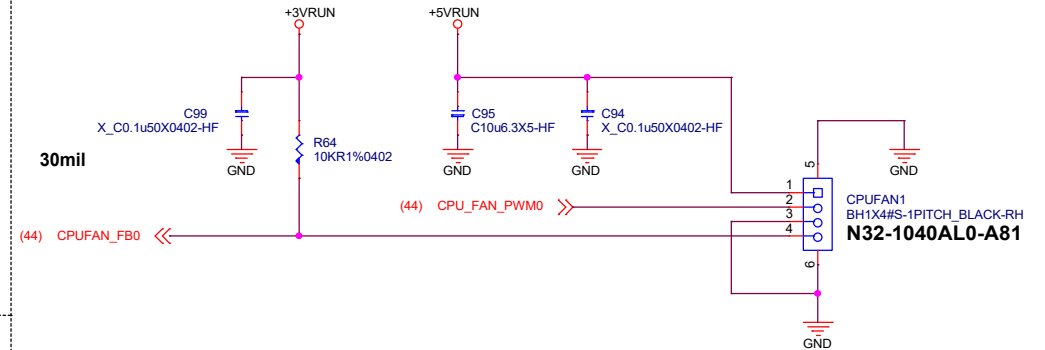


PWR SW/CPU FAN/BTB CONN/ LED CONN

Power Switch

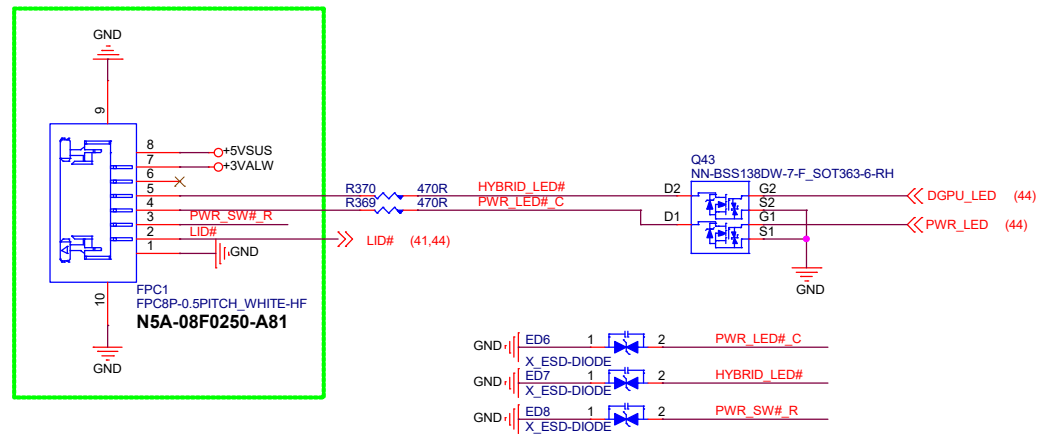


CPU FAN

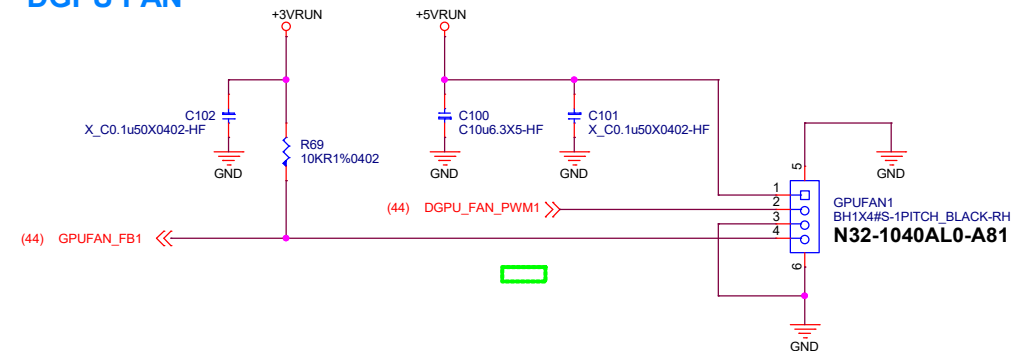


Power LED+SW+FP

20181016

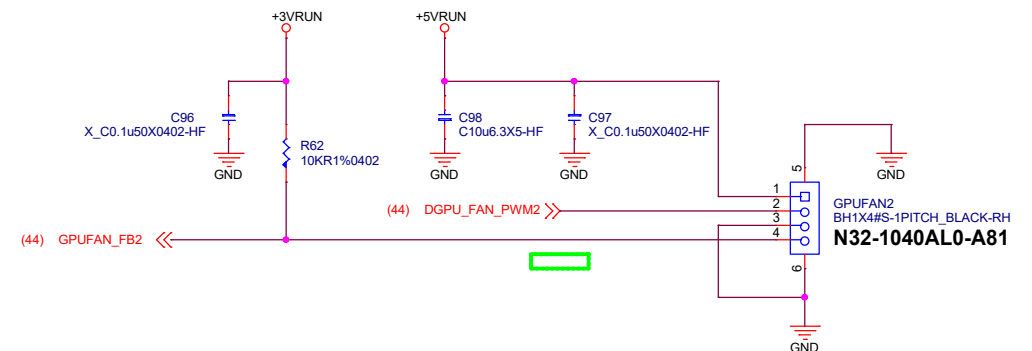
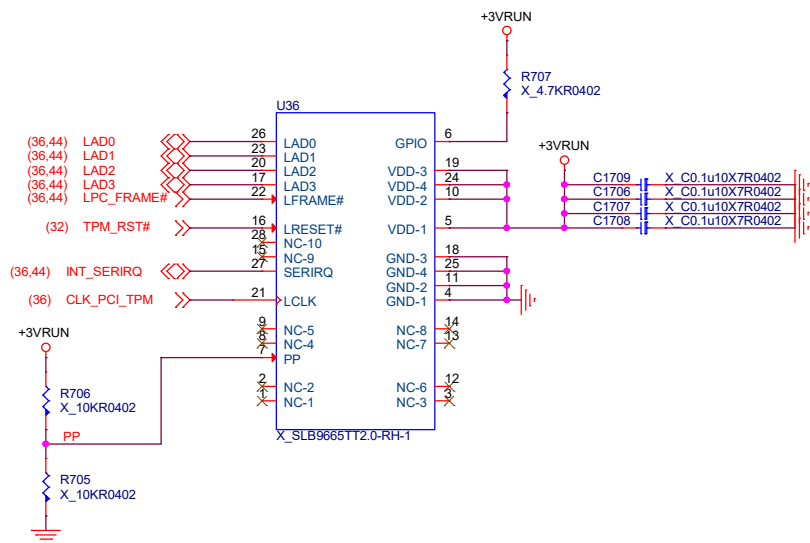


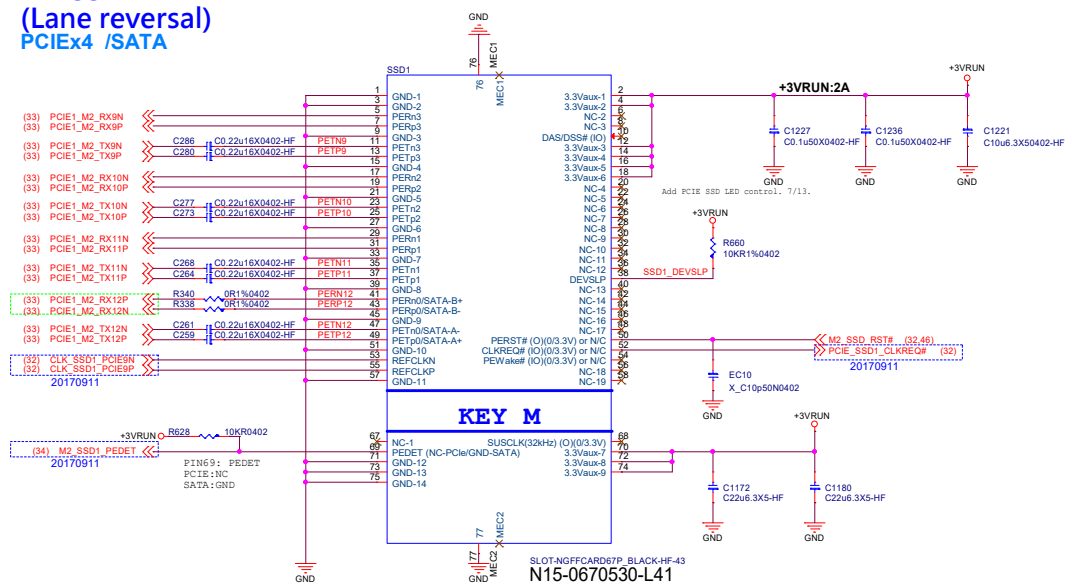
DGPU FAN



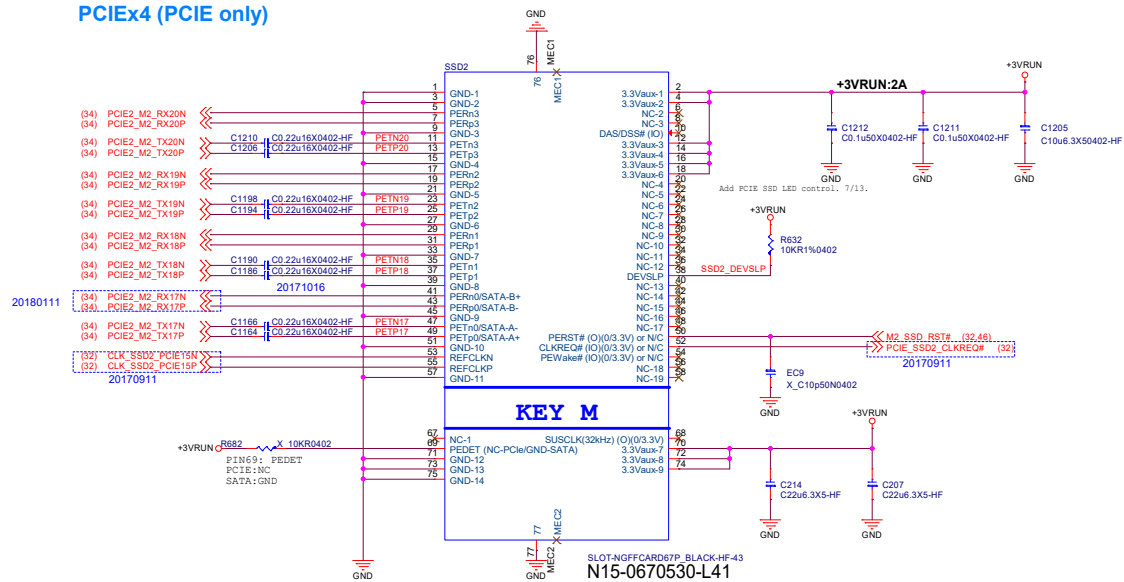
TPM

20180802





M2 SSD -2
PCIEx4 (PCIe only)



AUDIO(ALC1220)

ALC1220	AZ_GPIO3_DSD
PCM	H
DSD	L

To EC
To EC

Internal Mic

To EC

DIGITAL

Analog

To Mux

MIC In

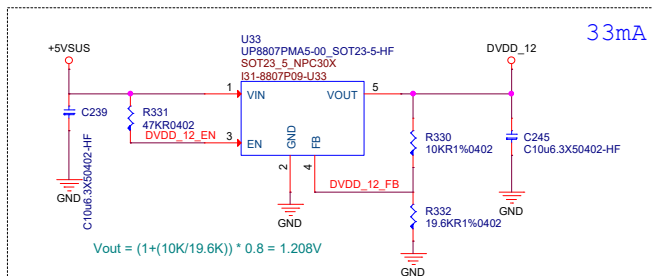
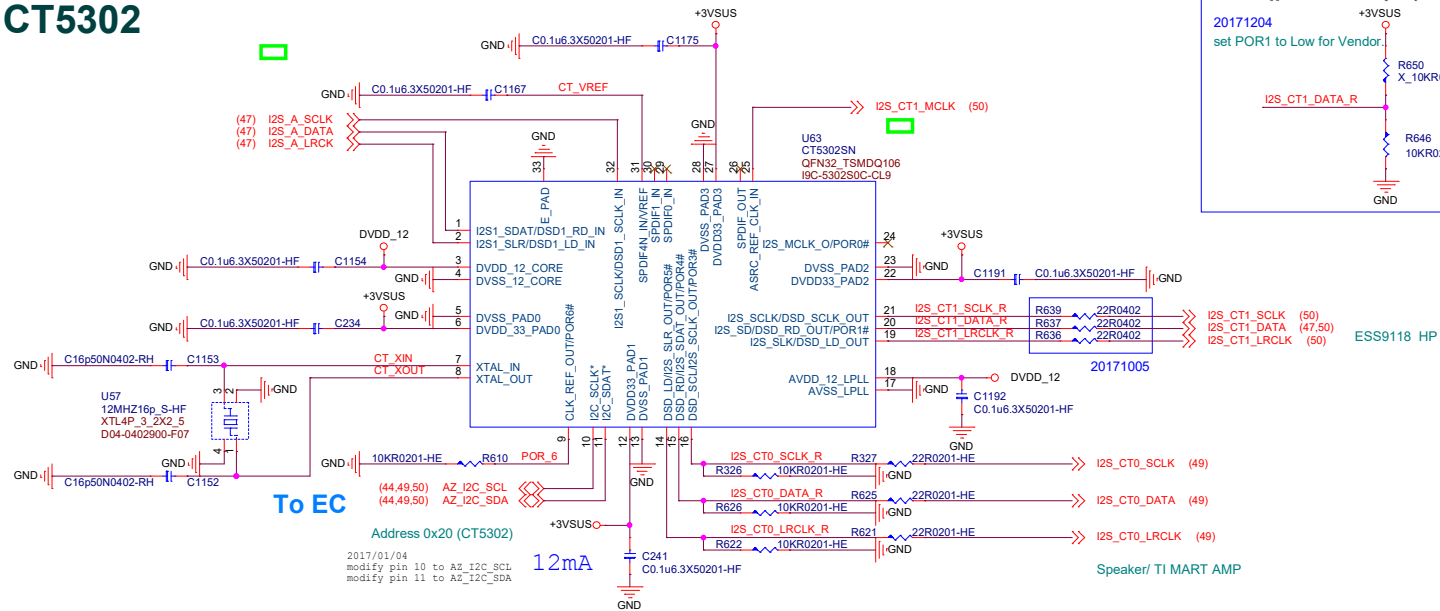
EMI
Close Codec

20170809 EMI remove C8176

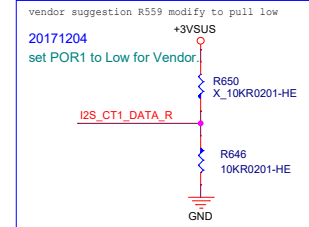
msi MICRO-STAR INT'L CO.,LTD.

Title: Audio(ALC1220-VB2)			
Size: Custom	Document Number: MS-16Q4	Rev: 10	
Date: Monday, December 24, 2018	Sheet: 47	of: 75	

CT5302



Pin Name	Description	Function Table
POR_IN_1	POWER_ON_LATCH_DC[1] = SEL_I2S_TX_SLAVE_MODE	Select I2S1 output port is master or slave mode
POR_IN_3	POWER_ON_LATCH_DC[4:3] = SEL_XTAL[1:0]	Select Crystal frequency
POR_IN_4		
POR_IN_5	POWER_ON_LATCH_DC[6:5] = I2C_ID[1:0]	I2C serial interface device ID selection
POR_IN_6		



I2S output slave mode:

Select I2S1 output port

No.	POR1	Definition
0	0	I2S output master mode
1	1	I2S output slave mode

Hardware Crystal:

Select current external crystal frequency

No	POR4	POR3	Definition
0	0	0	12.0000MHz
1	0	1	11.2896MHz
2	1	0	12.2880MHz
3	1	1	14.3180MHz

I2C Slave ID

Define chip I2C slave address

No	POR6	POR5	Definition
0	0	0	0x20
1	0	1	0x22
2	1	0	0x24
3	1	1	0x26

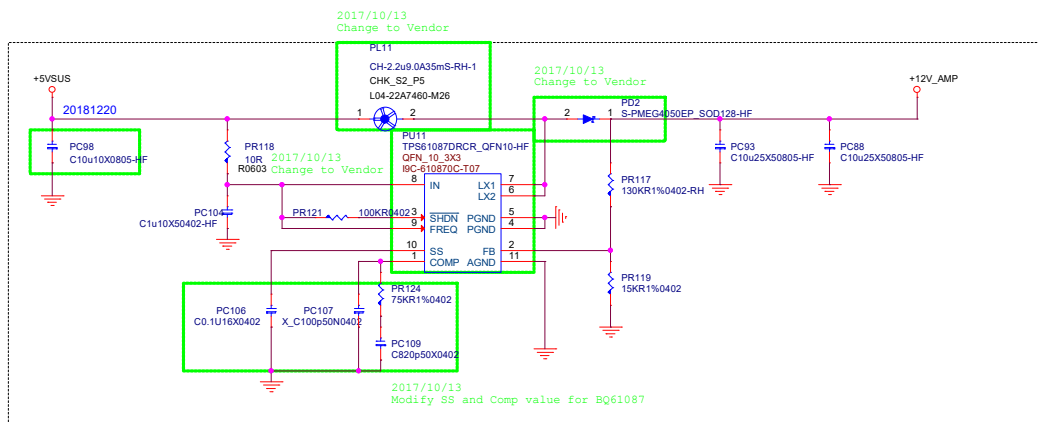
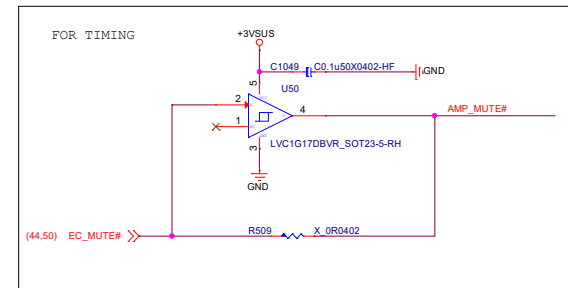
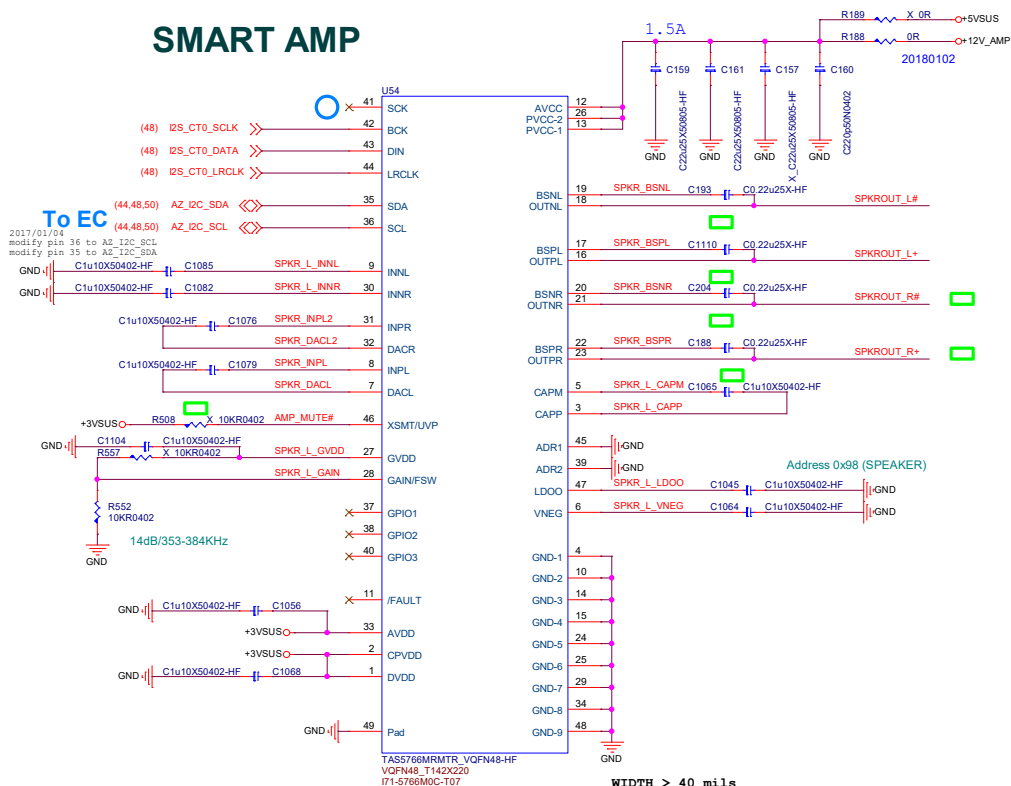
HW SETTING

HW SETTING

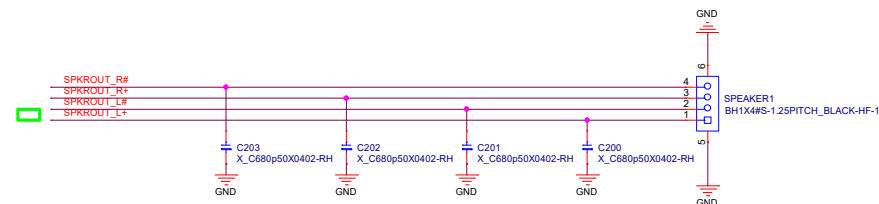
HW SETTING

SMART AMP

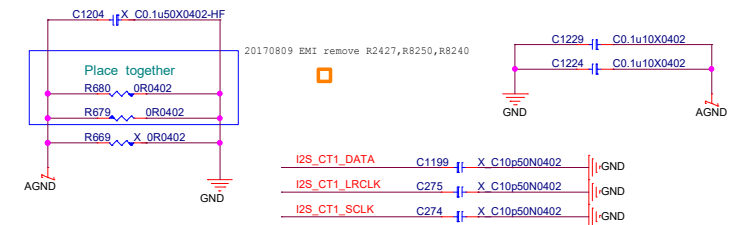
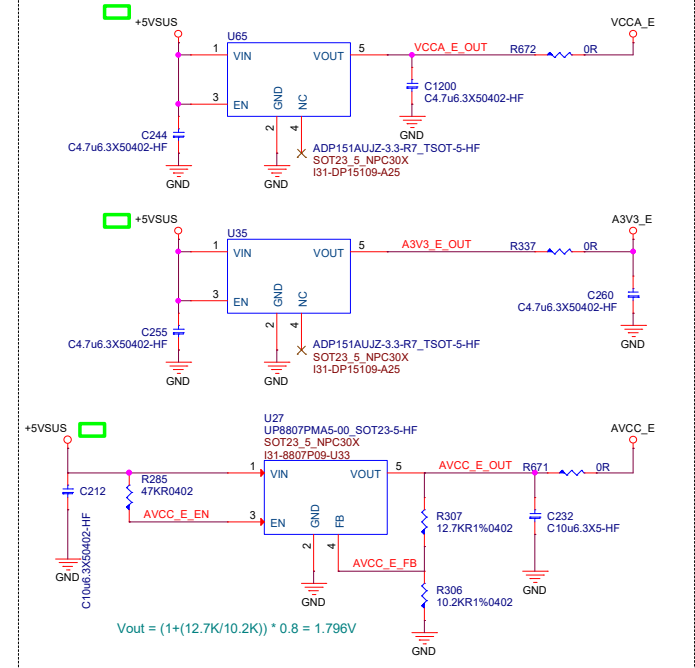
WIDTH > 40 mils



CON TO BE CONFIRM
SPK Conn



Power

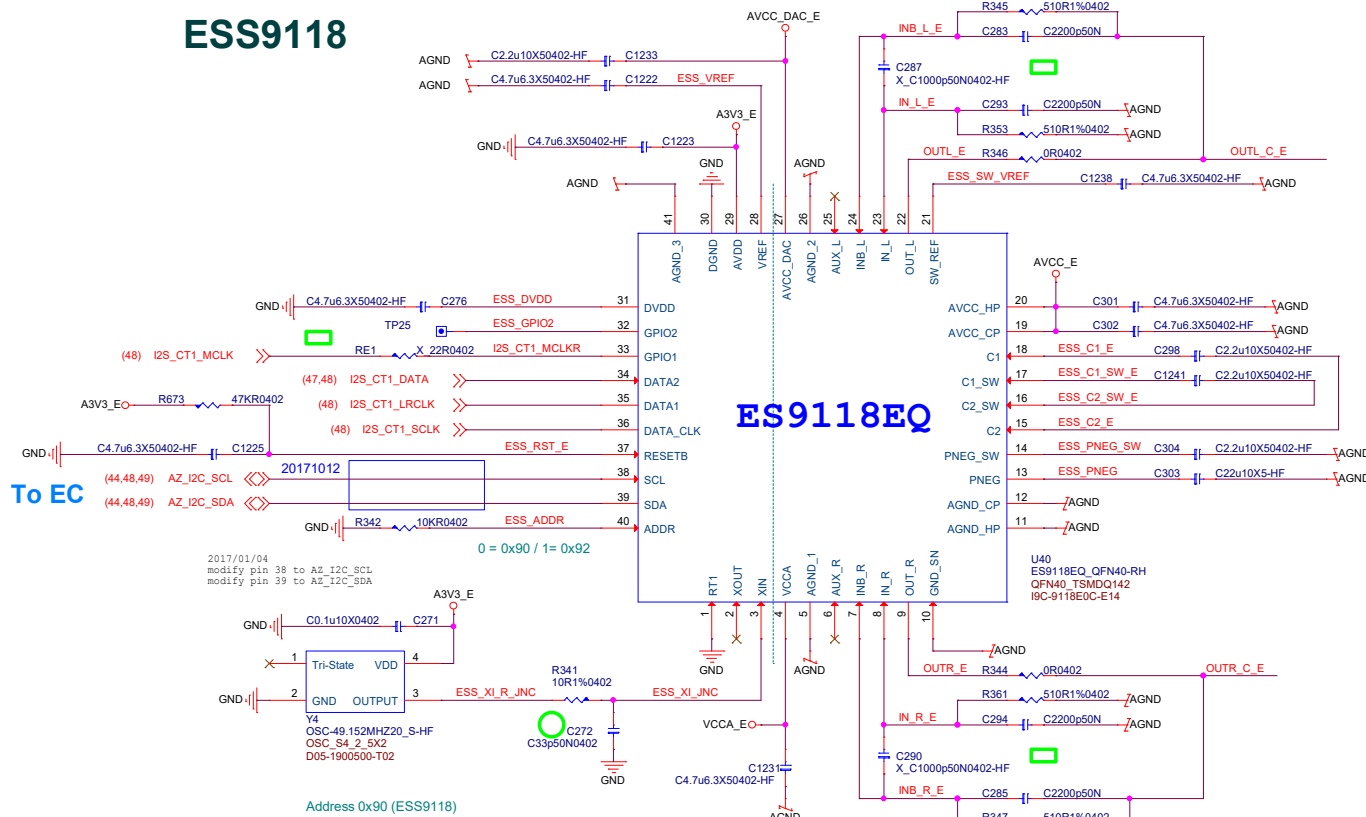


Truth Table

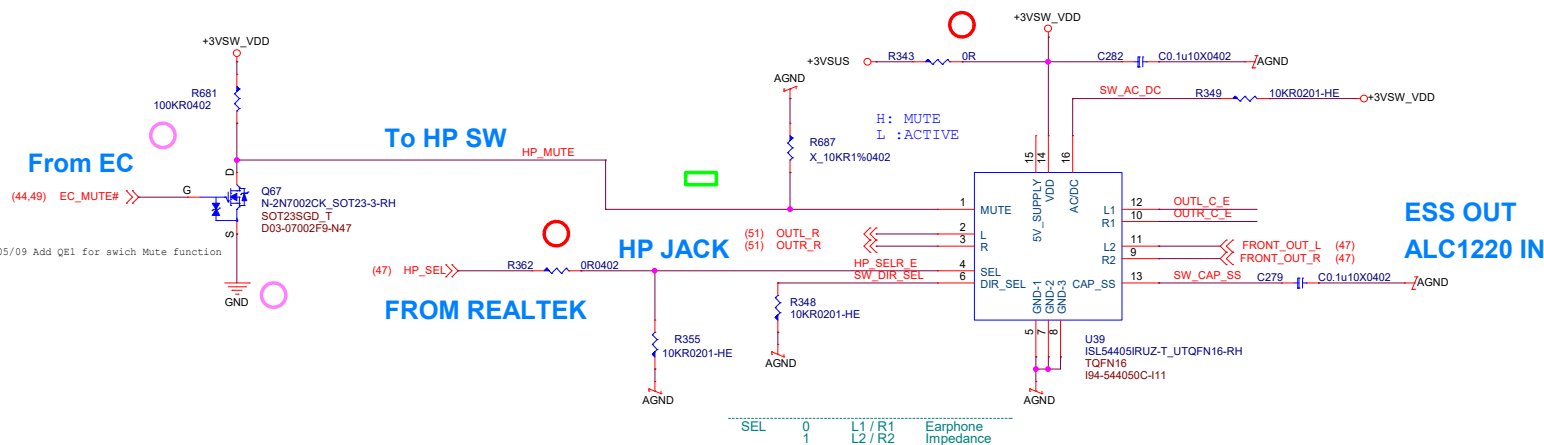
INPUTS				OUTPUTS				
AC/DC	DIR	MUTE	SEL	L1, R1	L2, R2	COM (L,R) CIP Shunts	L1, R1 CIP Shunts	L2, R2 CIP Shunts
0	X	0	0	ON	OFF	OFF	OFF	OFF
0	X	0	1	OFF	ON	OFF	OFF	OFF
0	X	1	X	OFF	OFF	OFF	OFF	OFF
1	0	0	0	ON	OFF	OFF	OFF	ON
1	0	0	1	OFF	ON	OFF	ON	OFF
1	0	1	X	OFF	OFF	OFF	ON	ON
1	1	0	0	ON	OFF	OFF	OFF	OFF
1	1	0	1	OFF	ON	OFF	OFF	OFF
1	1	1	X	OFF	OFF	ON	OFF	OFF

NOTE: MUTE, AC/DC, DIR: Logic "0" $\leq 0.5V$, Logic "1" $\geq 1.4V$ or Float with a 3.3V Supply or 5V supply.
SEL: Logic "0" $\leq 0.5V$, Logic "1" $\geq 1.4V$ with a 3.3V Supply or 5V supply.
X = Don't Care

ESS9118

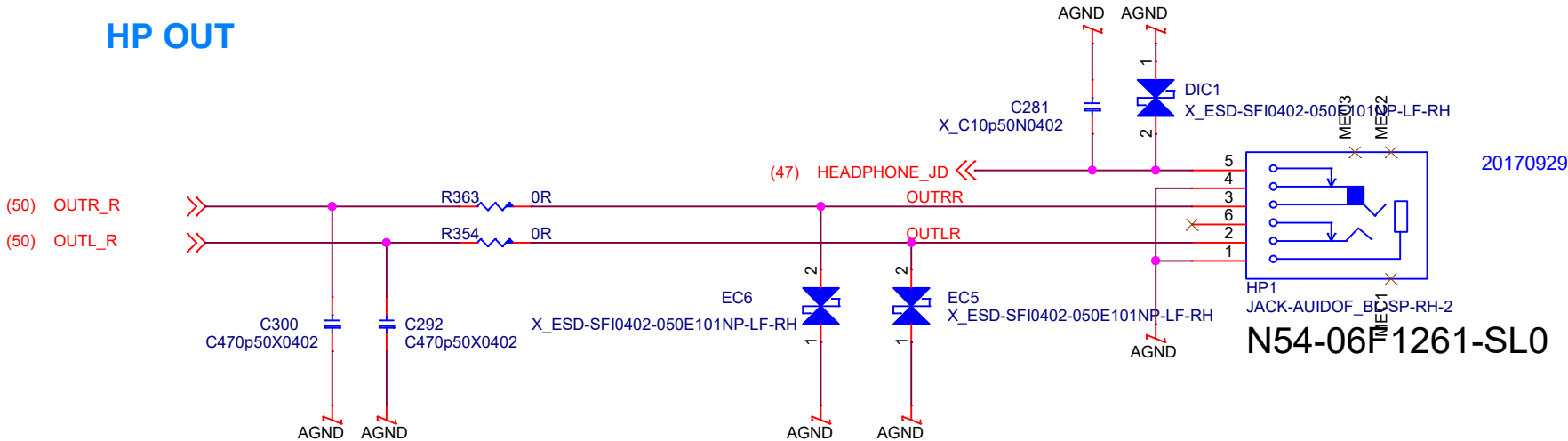


Audio MUX

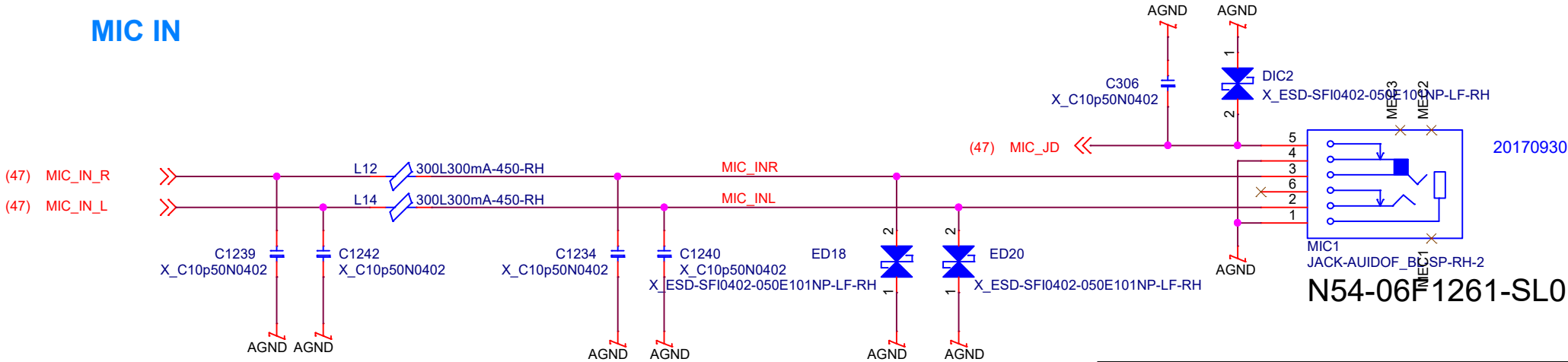



Audio CONN

HP OUT



MIC IN



		MICRO-STAR INT'L CO.,LTD.	
Title			
Audio Jack			
Size	Document Number		Rev
Custom	MS-16Q4		10
Date:	Monday, December 24, 2018	Sheet	51 of 75

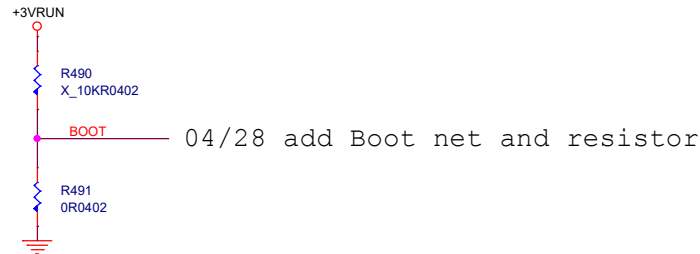
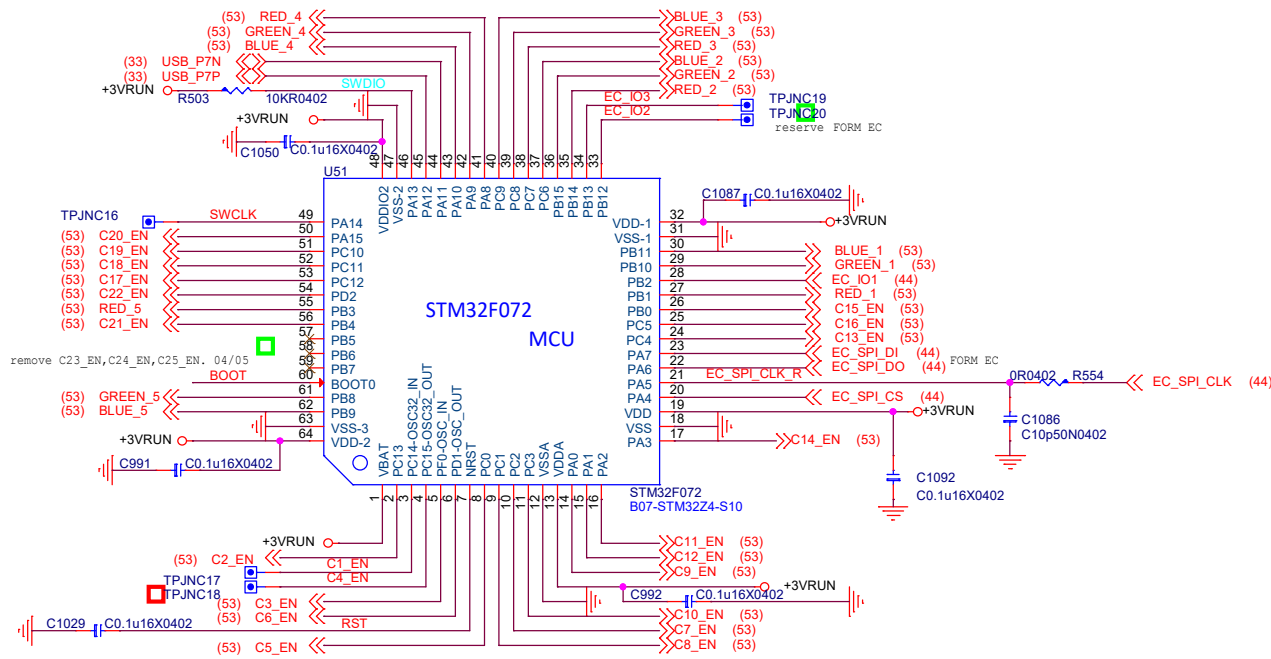
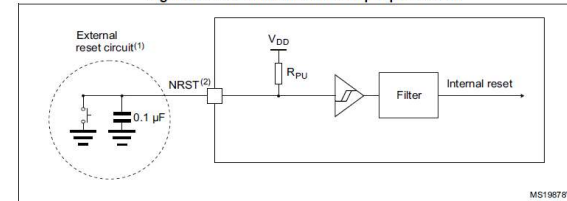
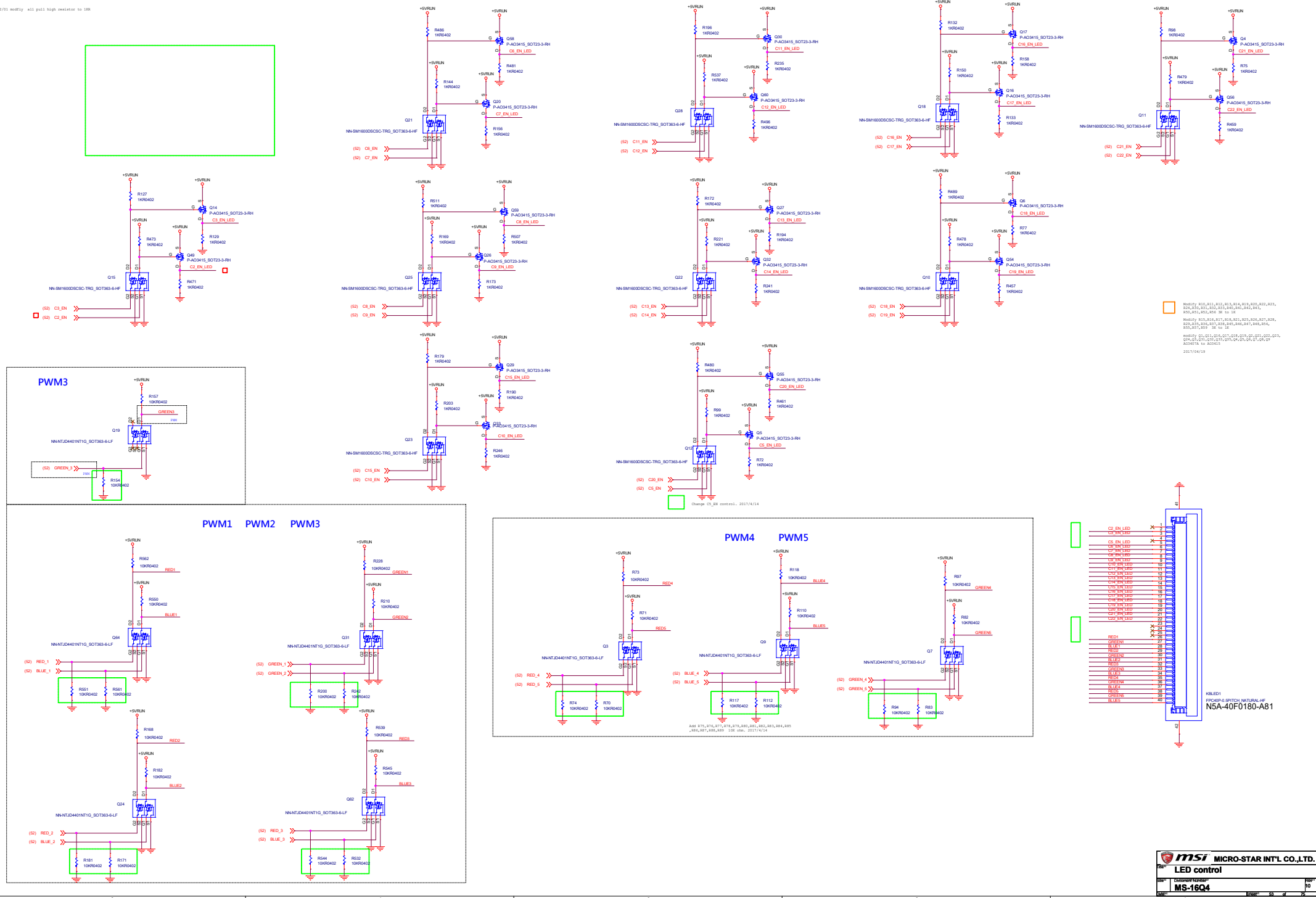


Figure 25. Recommended NRST pin protection



1. The external capacitor protects the device against parasitic resets.
2. The user must ensure that the level on the NRST pin can go below the $V_{IL(NRST)}$ max level specified in Table 56: NRST pin characteristics. Otherwise the reset will not be taken into account by the device.

		MICRO-STAR INT'L CO.,LTD.	
Title		MCU/Matrix	
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	PWM1	PWM2	PWM3	PWM4	PWM5
MCU_C1_EN					
MCU_C2_EN		P			F3
MCU_C3_EN			PgUp	F4	INS
MCU_C4_EN					
MCU_C5_EN		RIGHT	UP	DOWN	LEFT
MCU_C6_EN		F5	PgDn	F6	DEL
MCU_C7_EN	F8	CAP	A	S	D
MCU_C8_EN	F9	TAB	Q	W	E
MCU_C9_EN	F10	CTRL_L	WIN_L	ALT_L	K131
MCU_C10_EN	F11	SHI_L	\\ (K45)	Z	X
MCU_C11_EN	V	B	N	M	<,
MCU_C12_EN	F12	SPACE	3#	K132	C
MCU_C13_EN	>.	/?	K56	SHI_R	ENT
MCU_C14_EN	K133	ALTR	SS (Fn)	2@	CTR_R
MCU_C15_EN	F	G	H	J	K
MCU_C16_EN	L	::	""	K42	\\ (K29)
MCU_C17_EN	O	F7	{[}]	BACK
MCU_C18_EN	R	T	Y	U	I
MCU_C19_EN	9(0)	_	+=	k14
MCU_C20_EN	4\$	5%	6^	7&	8*
MCU_C21_EN	`~	1!	ESC	F1	F2
MCU_C22_EN	PAUSE	SCR	PRT		
MCU_C23_EN					
MCU_C24_EN					
MCU_C25_EN					

Mapping to
KBC's KBIN & KBOUT



KBIN_3,KBOUT_9	KBIN_6,KBOUT_5	KBIN_7,KBOUT_5	KBIN_7,KBOUT_4	KBIN_6,KBOUT_9
KBIN_3,KBOUT_5		KBIN_4,KBOUT_9	KBIN_5,KBOUT_9	
KBIN_1,KBOUT_12	KBIN_2,KBOUT_5	KBIN_6,KBOUT_12	KBIN_4,KBOUT_12	KBIN_2,KBOUT_12
KBIN_2,KBOUT_9	KBIN_4,KBOUT_5	KBIN_5,KBOUT_5	KBIN_5,KBOUT_4	KBIN_7,KBOUT_9
KBIN_6,KBOUT_4	KBIN_4,KBOUT_4	KBIN_1,KBOUT_4	KBIN_2,KBOUT_4	KBIN_0,KBOUT_4
KBIN_3,KBOUT_4		KBIN_7,KBOUT_12	KBIN_5,KBOUT_12	KBIN_3,KBOUT_12
	KBIN_0,KBOUT_13	KBIN_4,KBOUT_0	KBIN_5,KBOUT_0	KBIN_4,KBOUT_1
	KBIN_1,KBOUT_3	KBIN_2,KBOUT_0	KBIN_3,KBOUT_0	KBIN_2,KBOUT_1
	KBIN_3,KBOUT_3	KBIN_7,KBOUT_13	KBIN_4,KBOUT_3	KBIN_2,KBOUT_13
	KBIN_2,KBOUT_3	KBIN_0,KBOUT_9	KBIN_6,KBOUT_0	KBIN_7,KBOUT_0
KBIN_7,KBOUT_1	KBIN_6,KBOUT_2	KBIN_7,KBOUT_2	KBIN_6,KBOUT_6	KBIN_7,KBOUT_6
	KBIN_5,KBOUT_3		KBIN_5,KBOUT_13	KBIN_6,KBOUT_1
KBIN_6,KBOUT_7	KBIN_7,KBOUT_7	KBIN_6,KBOUT_8	KBIN_7,KBOUT_8	KBIN_1,KBOUT_5
KBIN_6,KBOUT_13	KBIN_6,KBOUT_3	KBIN_1,KBOUT_13	KBIN_3,KBOUT_13	KBIN_7,KBOUT_3
KBIN_5,KBOUT_1	KBIN_4,KBOUT_2	KBIN_5,KBOUT_2	KBIN_4,KBOUT_6	KBIN_5,KBOUT_6
KBIN_4,KBOUT_7	KBIN_5,KBOUT_7	KBIN_4,KBOUT_8	KBIN_5,KBOUT_8	KBIN_0,KBOUT_5
KBIN_2,KBOUT_7		KBIN_2,KBOUT_8	KBIN_3,KBOUT_8	KBIN_0,KBOUT_12
KBIN_3,KBOUT_1	KBIN_2,KBOUT_2	KBIN_3,KBOUT_2	KBIN_2,KBOUT_6	KBIN_3,KBOUT_6
KBIN_0,KBOUT_7	KBIN_1,KBOUT_7	KBIN_0,KBOUT_8	KBIN_1,KBOUT_8	KBIN_1,KBOUT_9
KBIN_1,KBOUT_1	KBIN_0,KBOUT_2	KBIN_1,KBOUT_2	KBIN_0,KBOUT_6	KBIN_1,KBOUT_6
		KBIN_0,KBOUT_10	KBIN_1,KBOUT_10	KBIN_2,KBOUT_10
	KBIN_0,KBOUT_3	KBIN_0,KBOUT_0	KBIN_1,KBOUT_0	KBIN_0,KBOUT_1
KBIN_0,KBOUT_11	KBIN_1,KBOUT_11	KBIN_2,KBOUT_11	KBIN_3,KBOUT_11	KBIN_4,KBOUT_11
KBIN_3,KBOUT_10	KBIN_4,KBOUT_10	KBIN_5,KBOUT_10	KBIN_6,KBOUT_10	KBIN_7,KBOUT_10
KBIN_3,KBOUT_7		KBIN_7,KBOUT_11	KBIN_6,KBOUT_11	KBIN_5,KBOUT_11

**msi**

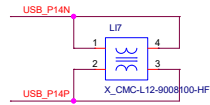
MICRO-STAR INT'L CO.,LTD.

Title
Keyboard MatrixSize
Document Number
MS-16Q4Rev
10

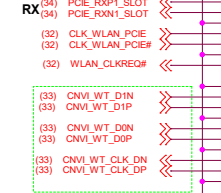
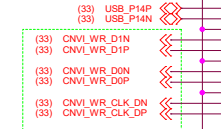
Date: Sheet 54 of 75

WLAN /ClickPad/FP

EMI

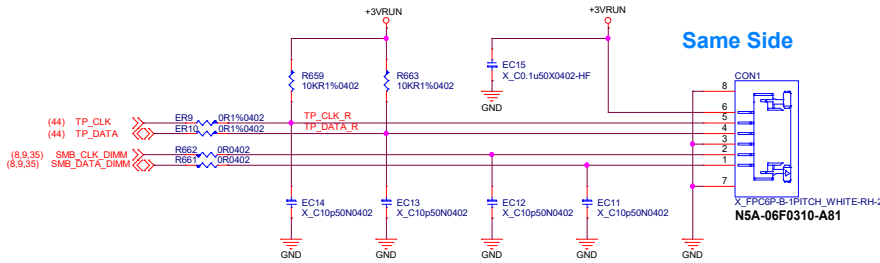


Ref DG Section 18.6
- use USB 2.0 Port 14 with CNVI Solution

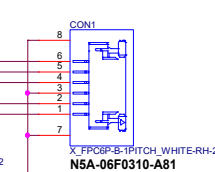


N15-0670520-L41
SLOT_NGFFCARD67_H2_15

Click Pad



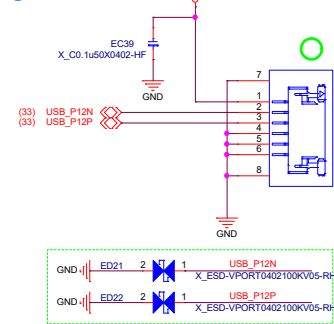
Same Side



FOR WS

(All stuff)
20180604

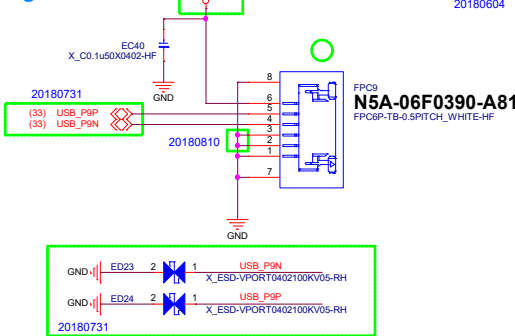
Finger Print



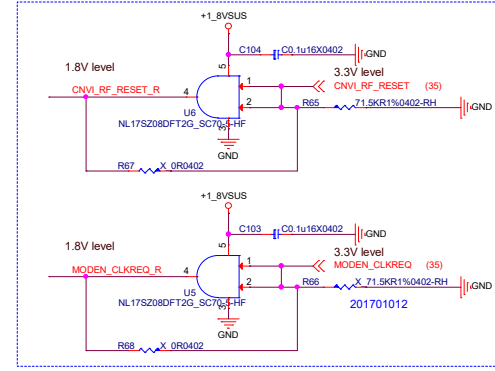
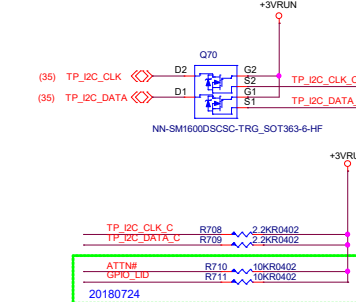
FOR 16Q4

(All stuff)
20180604

Finger Print



FOR 16Q4



20170817 change R2394 stuff and
R2397 unstuff for strap pin setting

Functional Strap Definitions

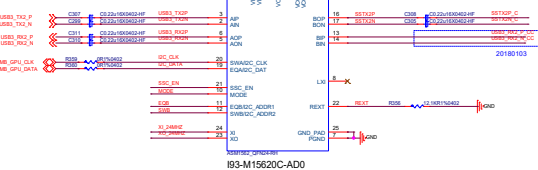
GPP_J4
This signal has a weak internal pull-down.
An external pull-up is required on this strap since 38.4
MHz XTAL is not supported on the PCH.
0 = 38.4 XTAL frequency selected. (Default)
1 = 24MHz XTAL frequency selected.

GPP_J6
An external pull-up or pull-down is required.
0 = Integrated CNVI enable.
1 = Integrated CNVI disable.

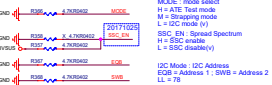
msi MICRO-STAR INT'L CO.,LTD.

File	WLAN /ClickPad/FP	Rev	10
Size	Document Number		
Custom	MS-16Q4		
Date:	Monday, December 24, 2018	Sheet	55 of 75

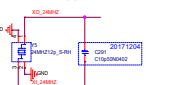
USB3.1 Gne2 Retimer



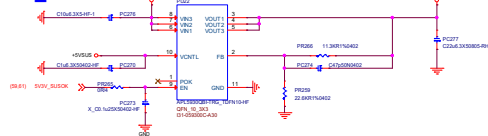
Strap



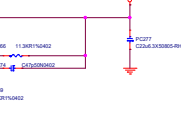
24MHz Clock



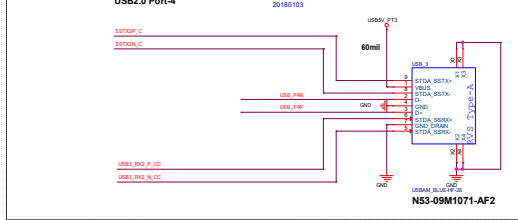
+1.2VSUS



MAX 1A

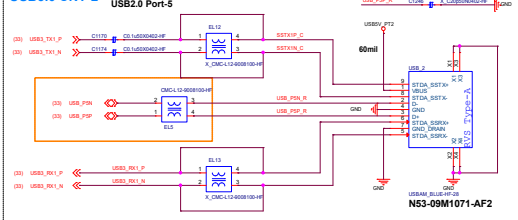


USB3.0 CNT-3

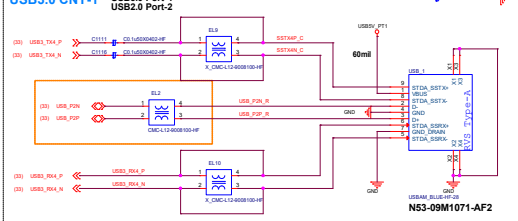


Note: CMC-L12-9008100-HF (P/N : L12-9008100-105) *s
Default Oread library and footprint FILTER_S4_1_25X1
are not match datasheet.

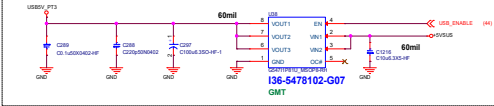
USB3.0 CNT-2



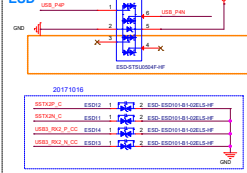
USB3.0 CNT-1



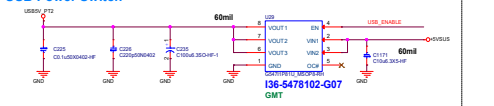
USB Power Switch



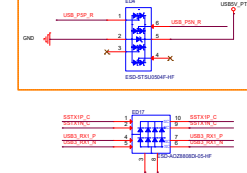
ESD



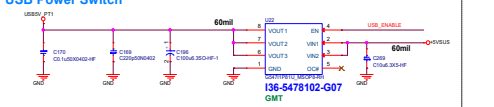
USB Power Switch



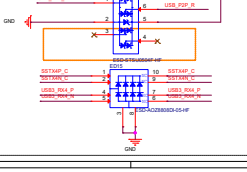
ESD



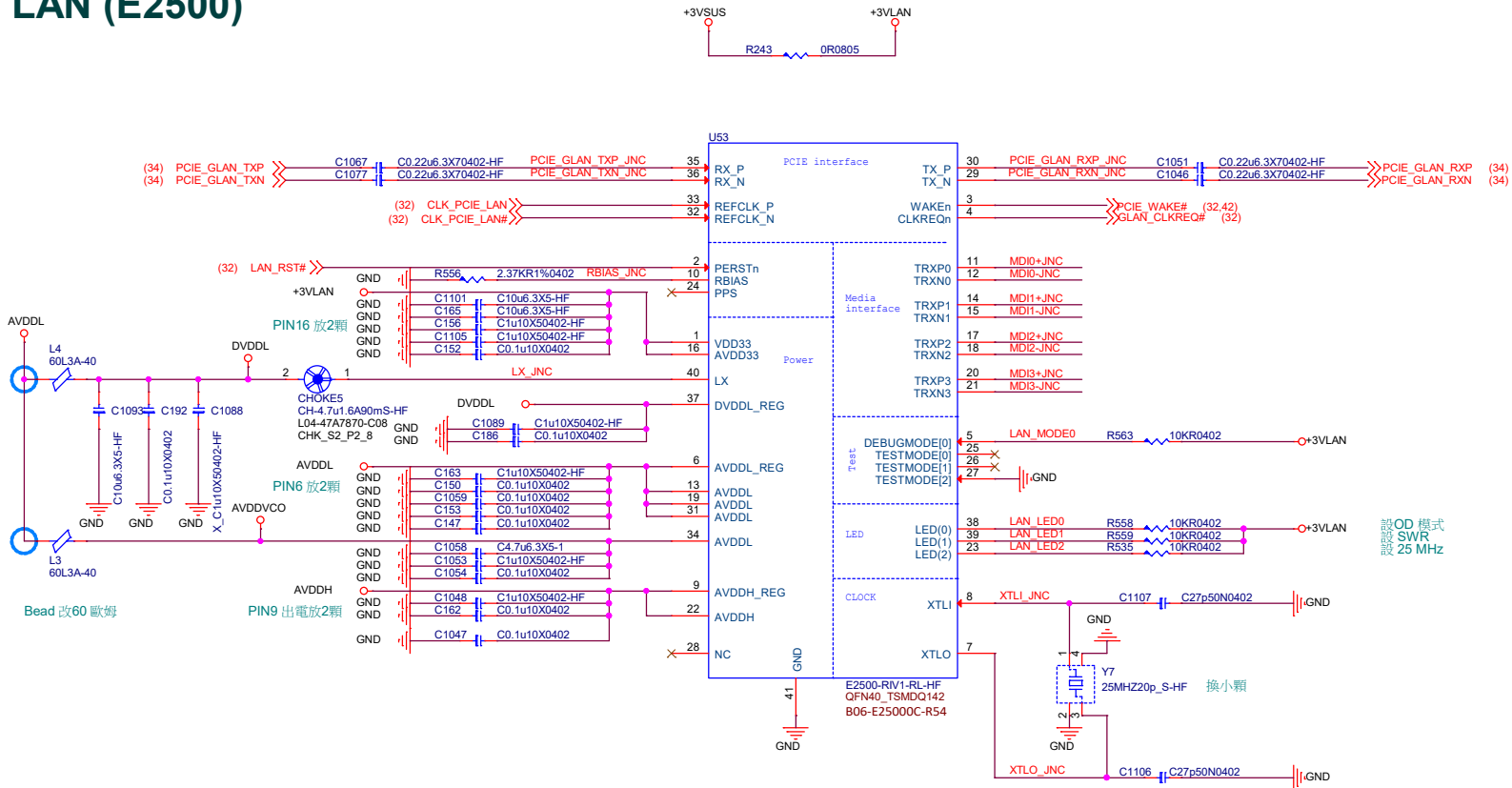
USB Power Switch



ESD



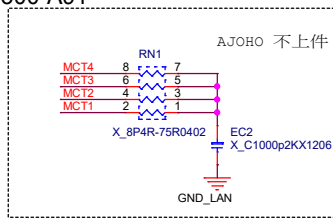
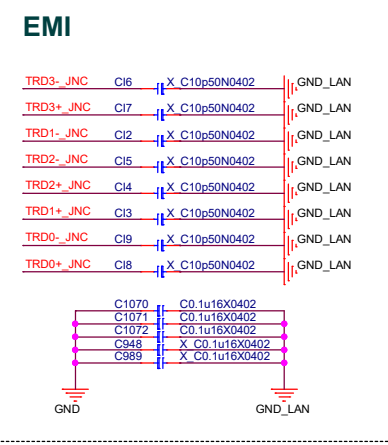
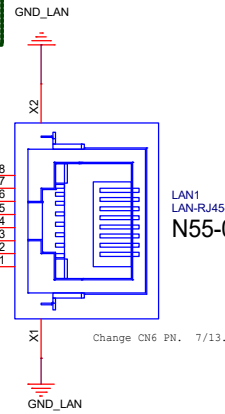
LAN (E2500)

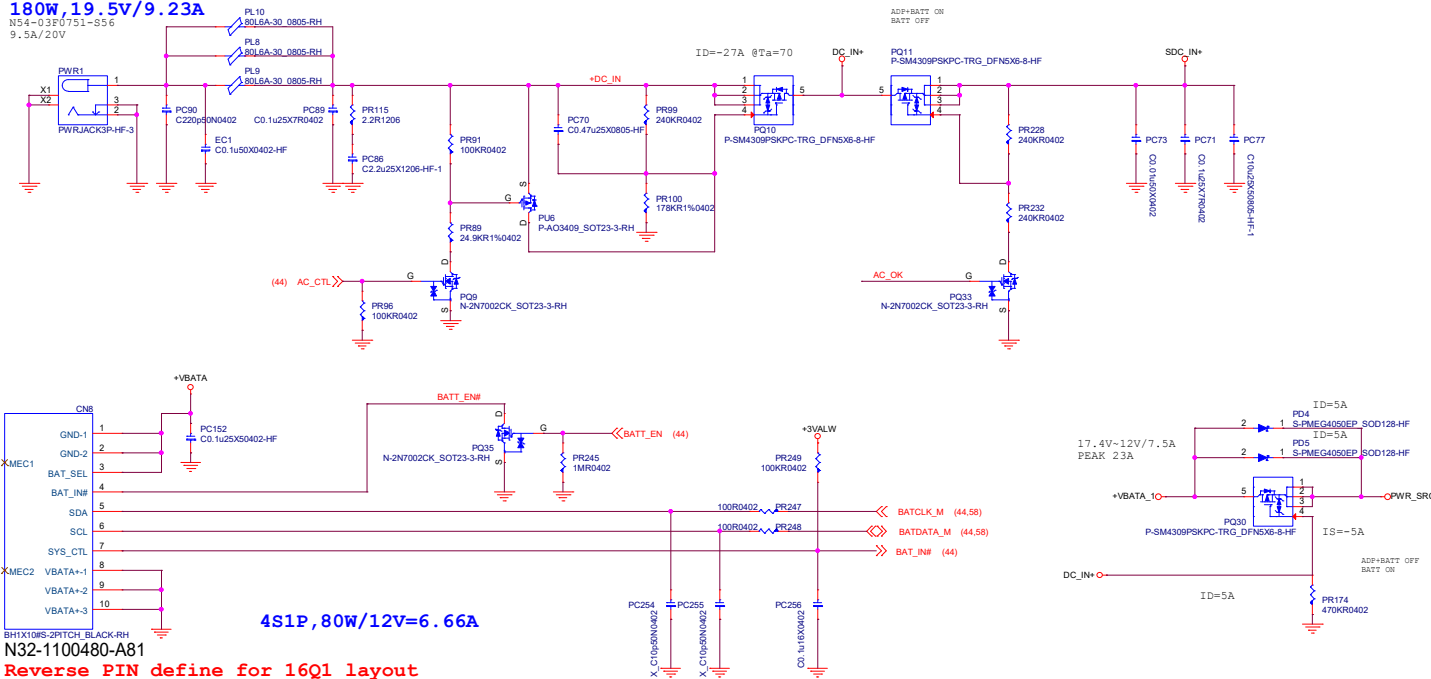


MCT1 R517 X 10L500mA-200_0603-HF GND_LAN

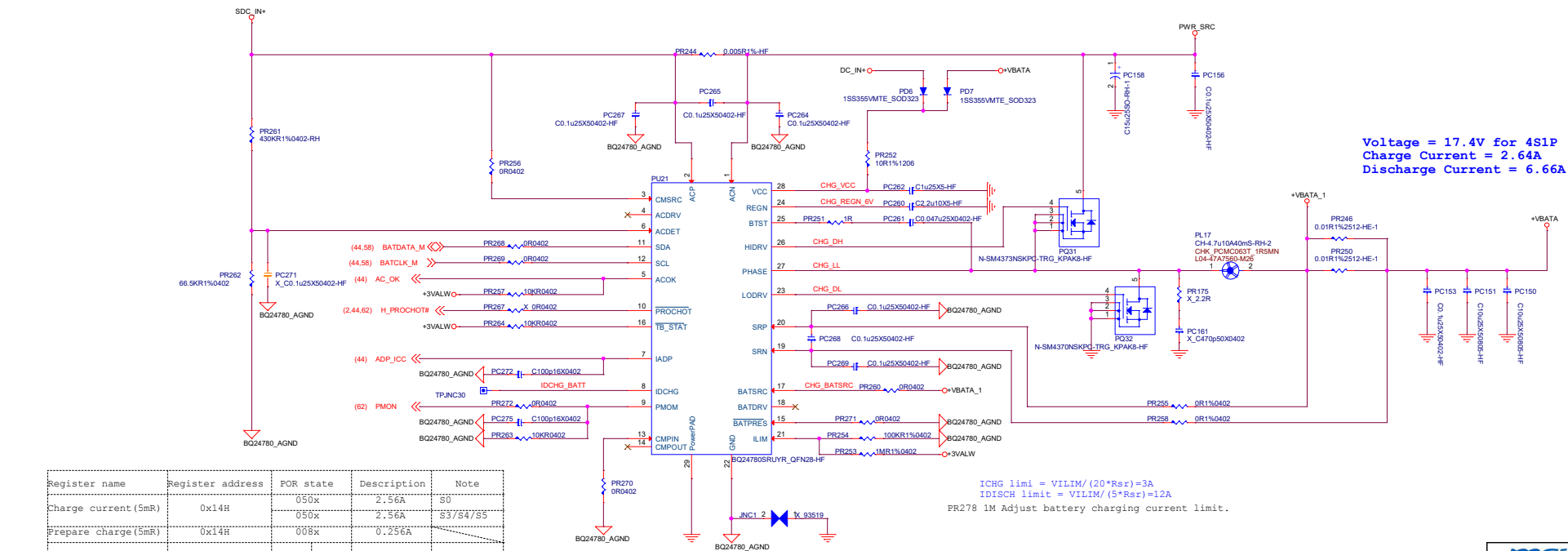
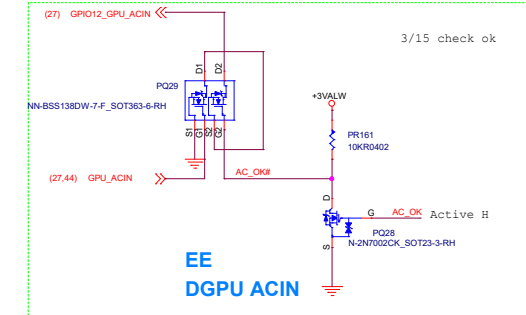
Add colay AZ N-8600GS(OL5-7966001) R866 0ohm. 5/7

Modify RD10 10L500mA for EMI.7/20





AC_OK#	GPU_ACIN (EC control)	GPIO12_GPU_ACIN
0	0	AC
0	1	AC
1	0	AC
1	1	DC



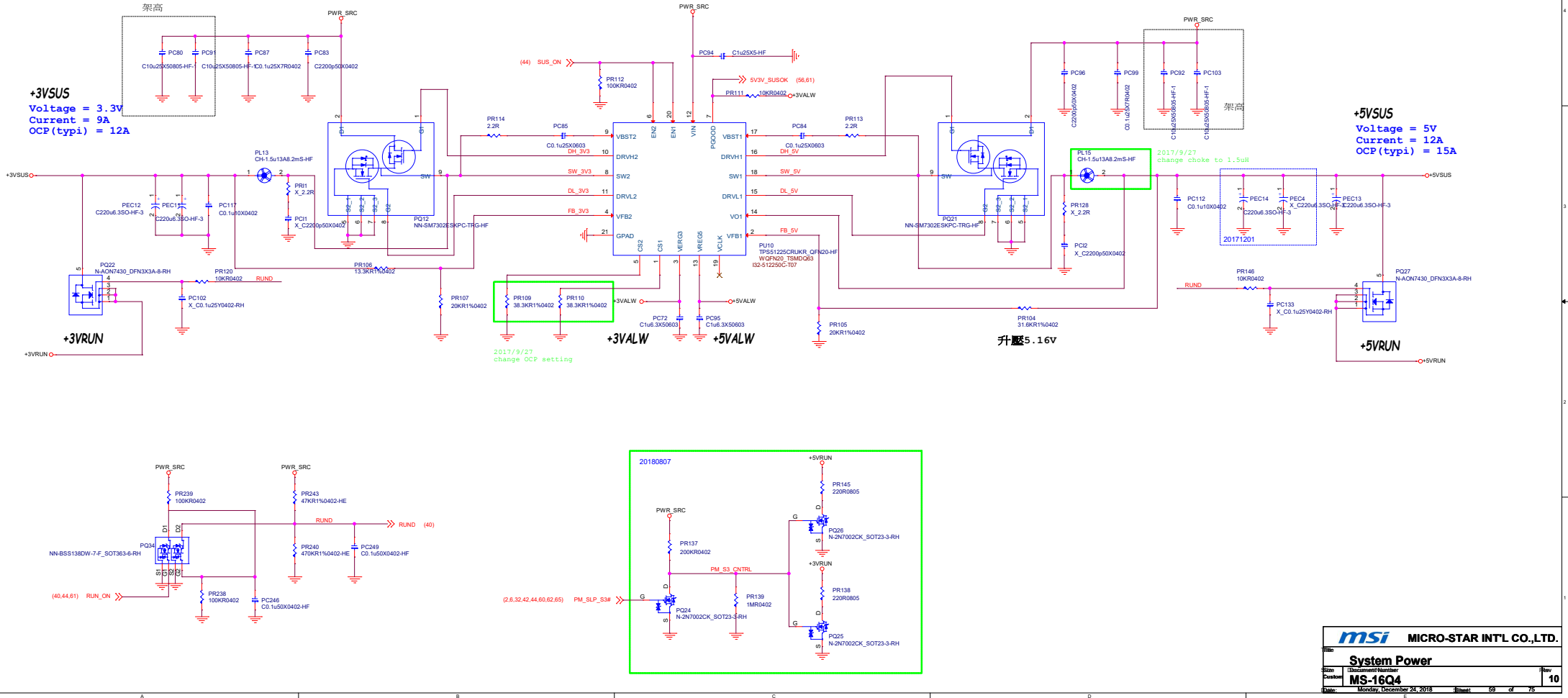
Register name	Register address	POR state	Description	Note
Charge current (5mR)	0x14H	050x	2.56A	S0
		050x	2.56A	S3/S4/S5
Prepare charge (5mR)	0x14H	008x	0.256A	
Input current (5mR)	0x3FH	19.5V	110x	8.704A
				180W
Charge voltage	0x15H	43Fx	17.392V	451P
Discharge current (5mR)	0x39H	080x	4.096A	BOOST current

```

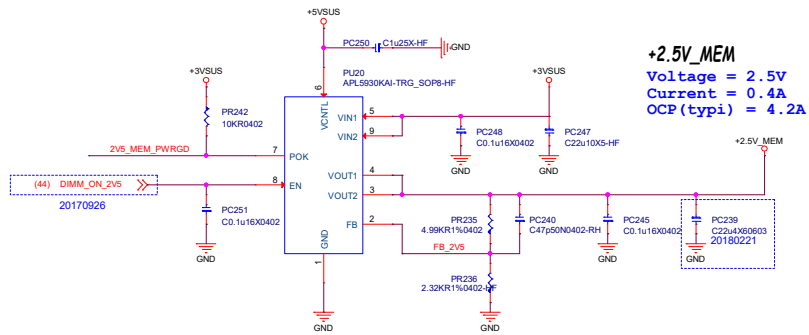
    ICHG limi = VILIM/(20*Rsr)=3A
    IDISCH limit = VILIM/(5*Rsr)=12A
PR278 1M Adjust battery charging current limit

```

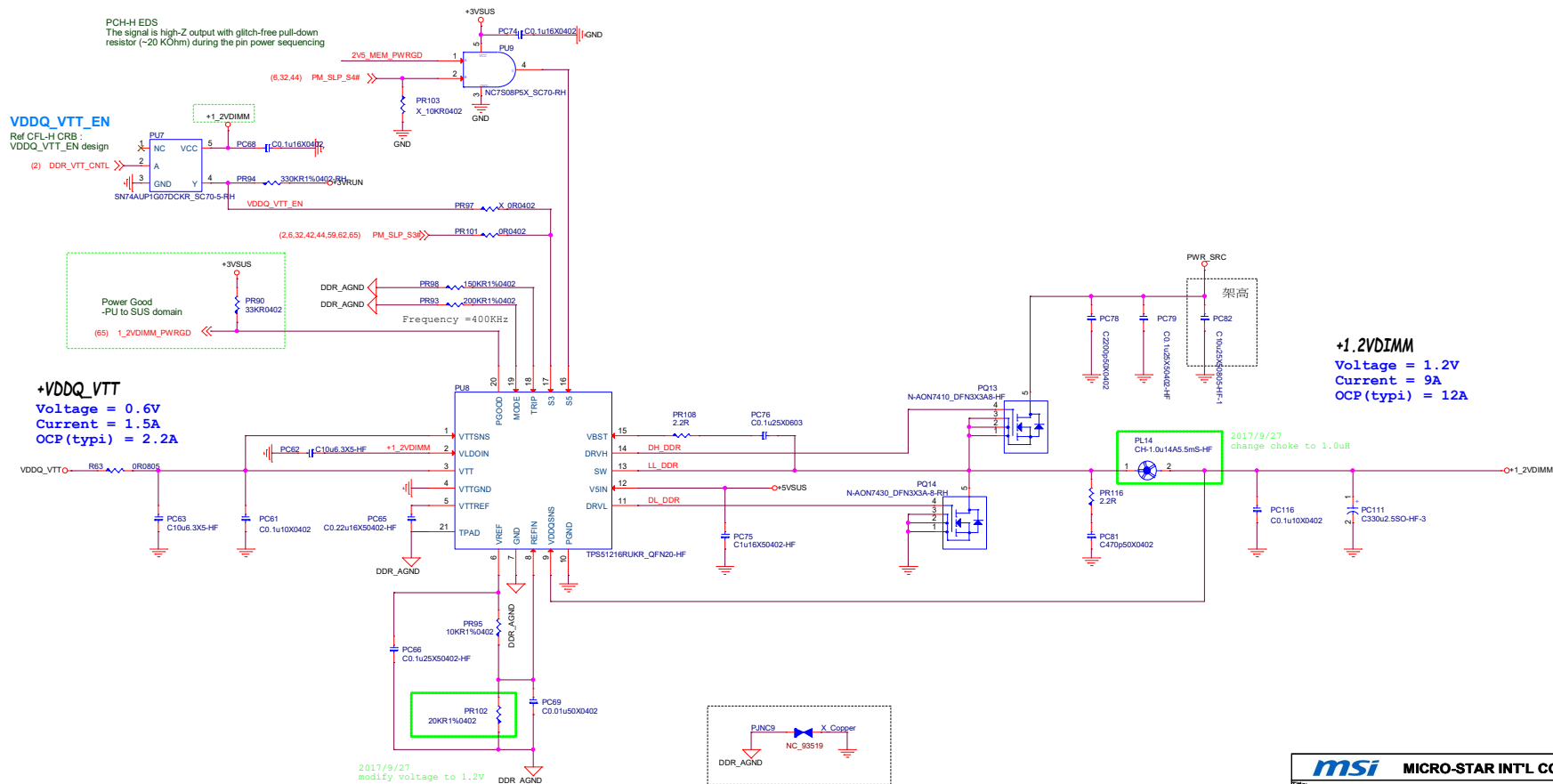
System Power



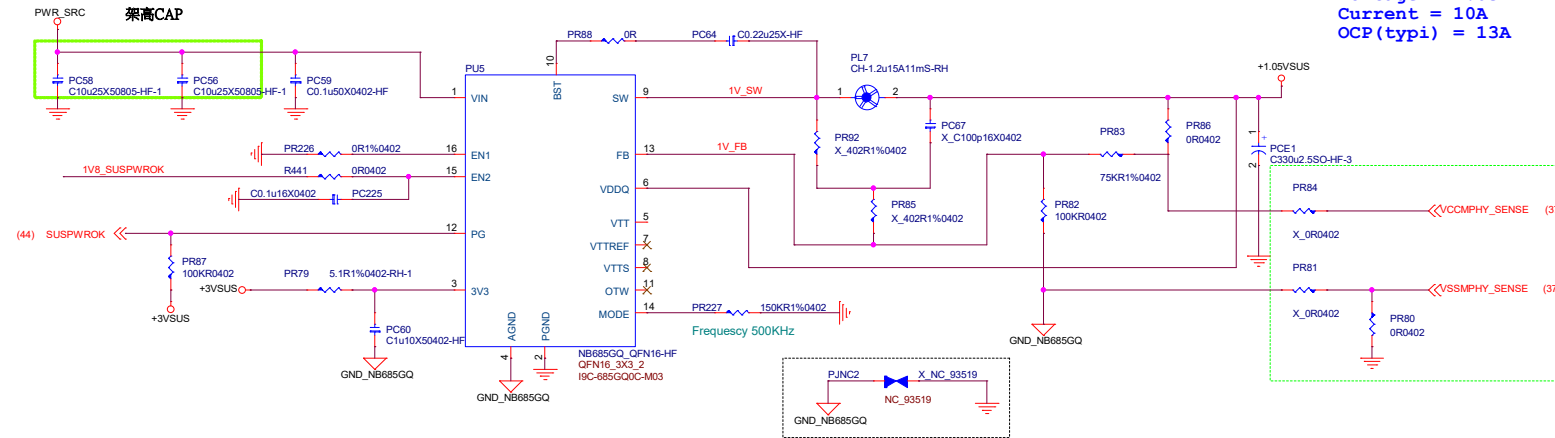
+2.5V_MEM (DDR4/V_{pp})



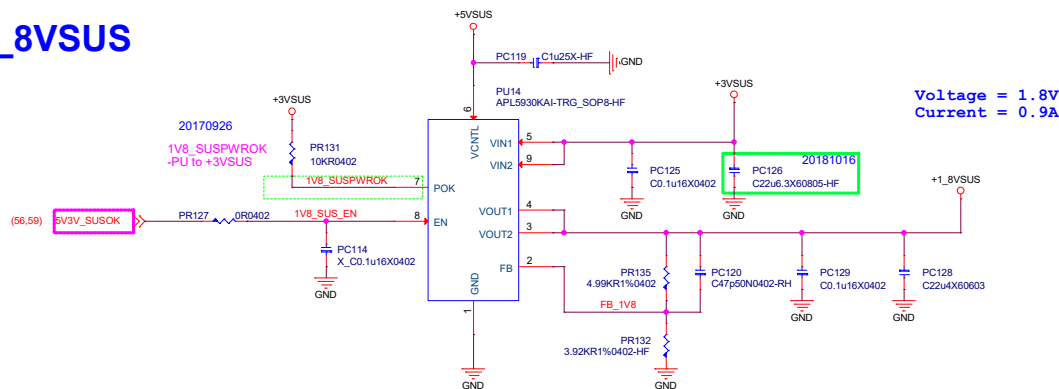
+1.2VDIMM / VDDQ_VTT(0.6V)



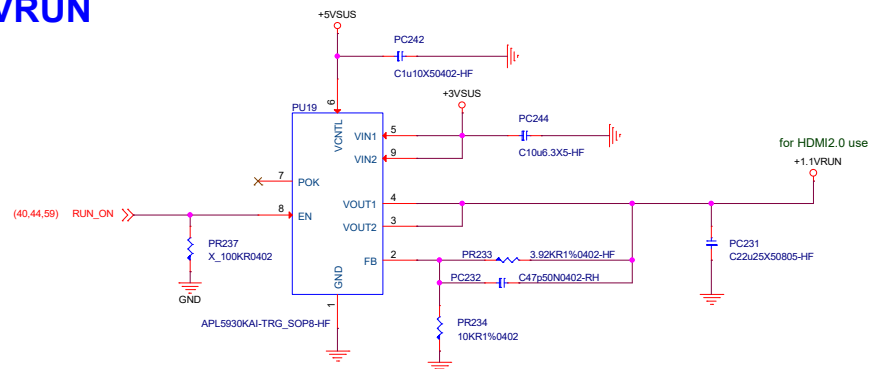
+1.05VSUS

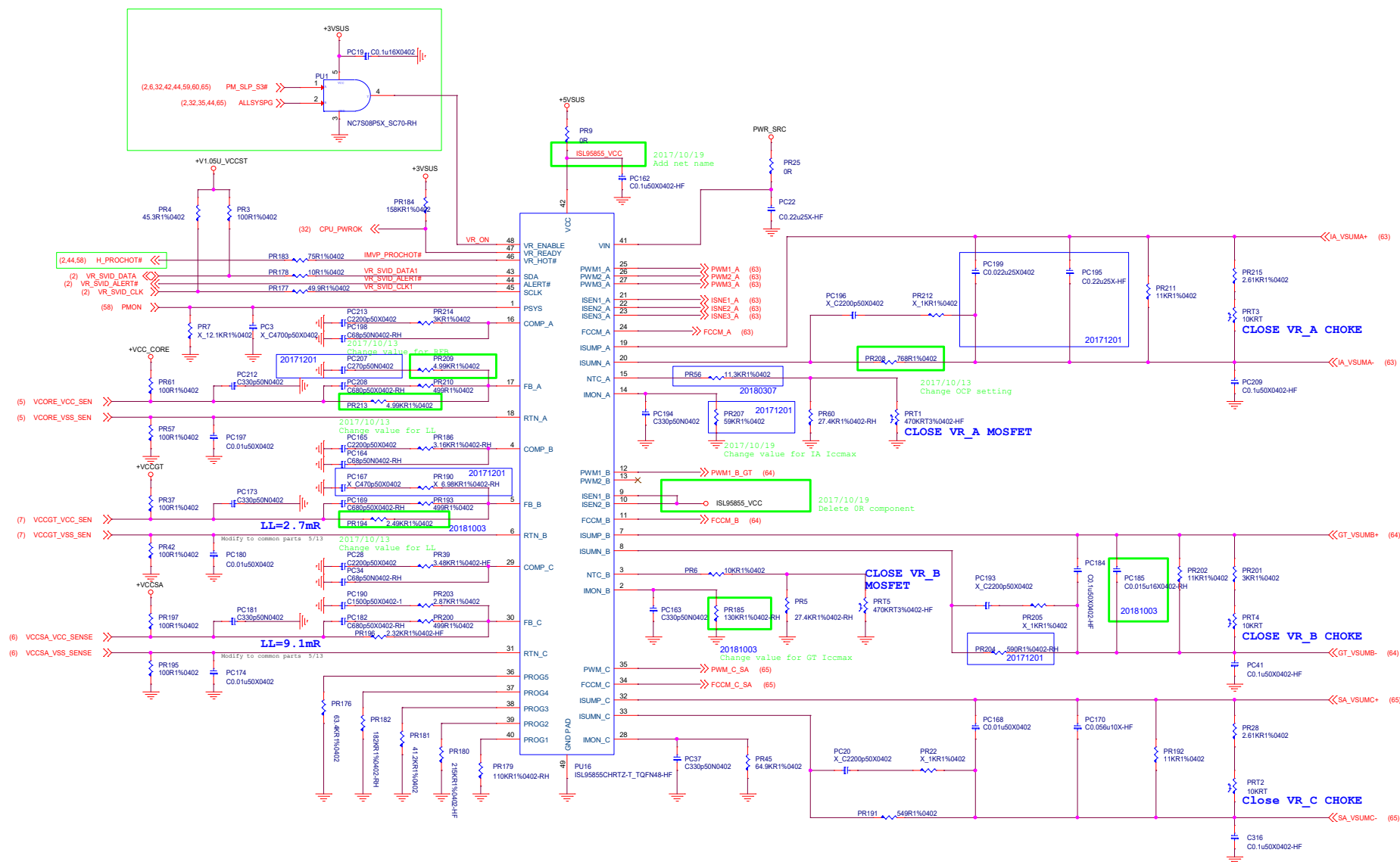


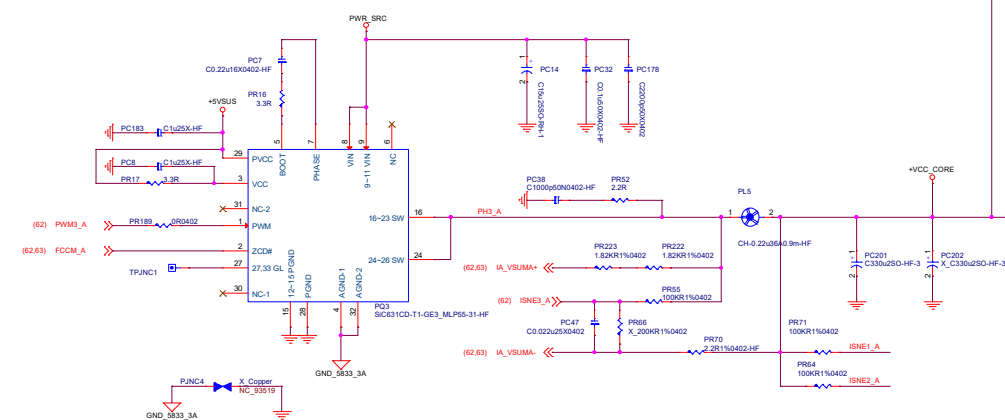
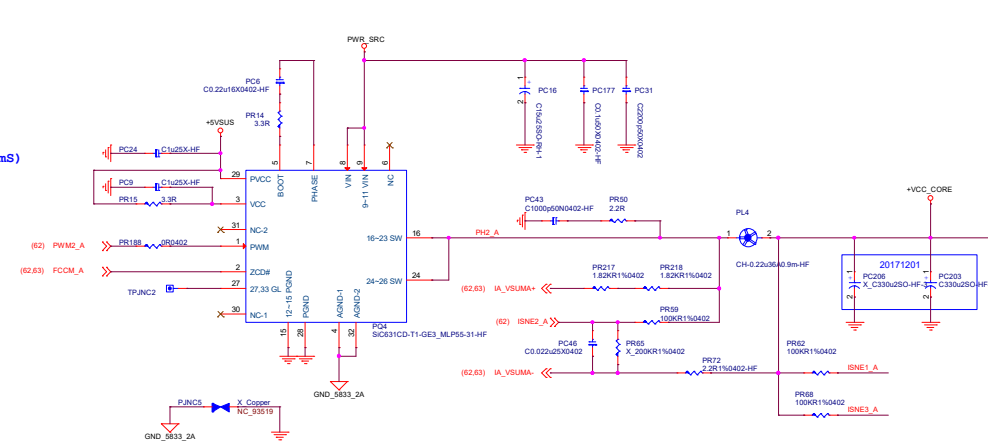
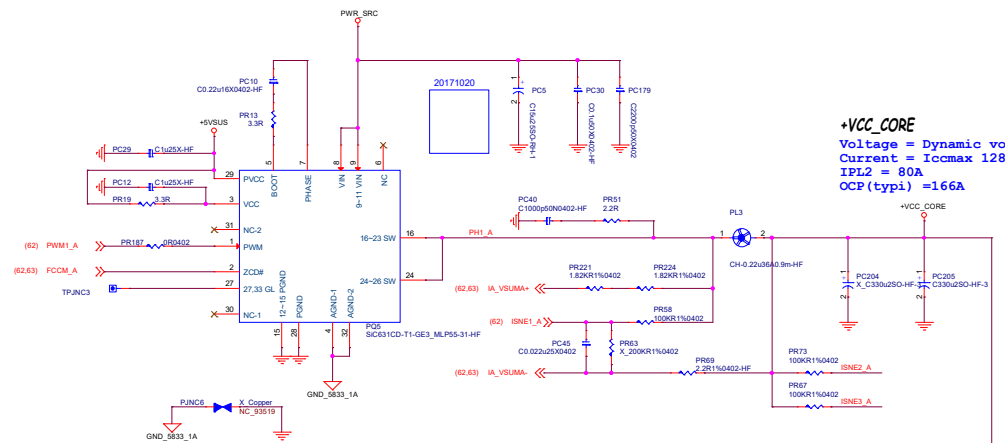
+1_8VSUS

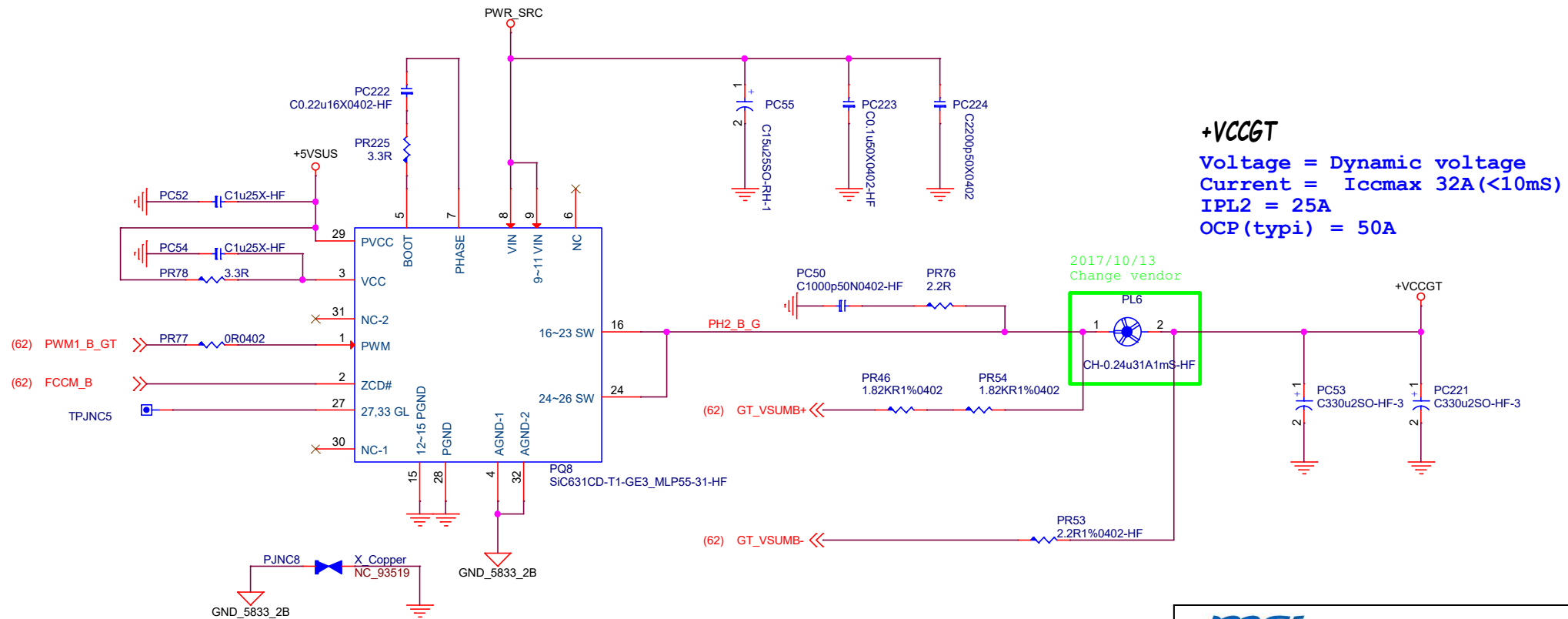


+1.1VRUN



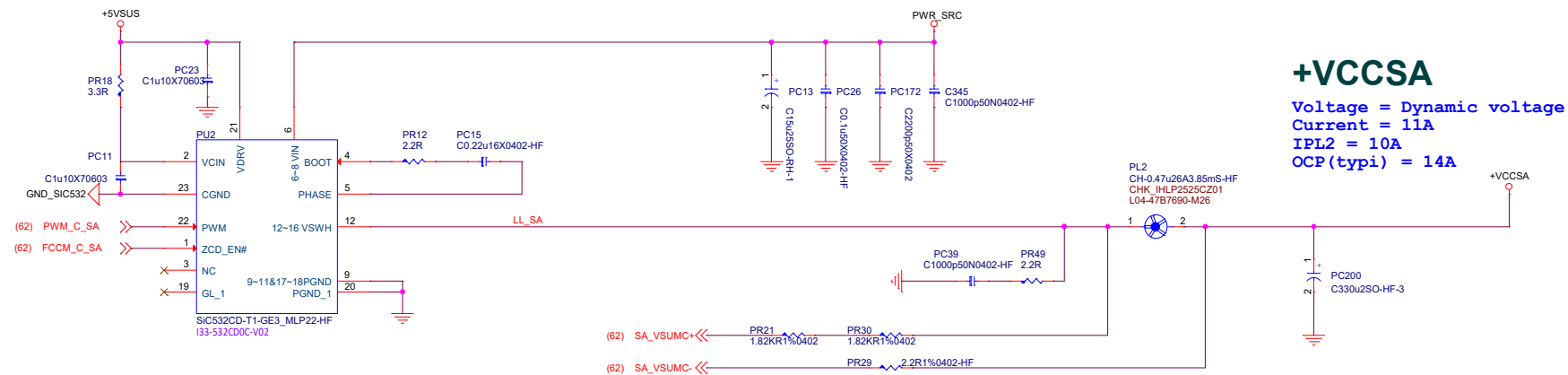




+VCCGT**msi****MICRO-STAR INT'L CO.,LTD.**

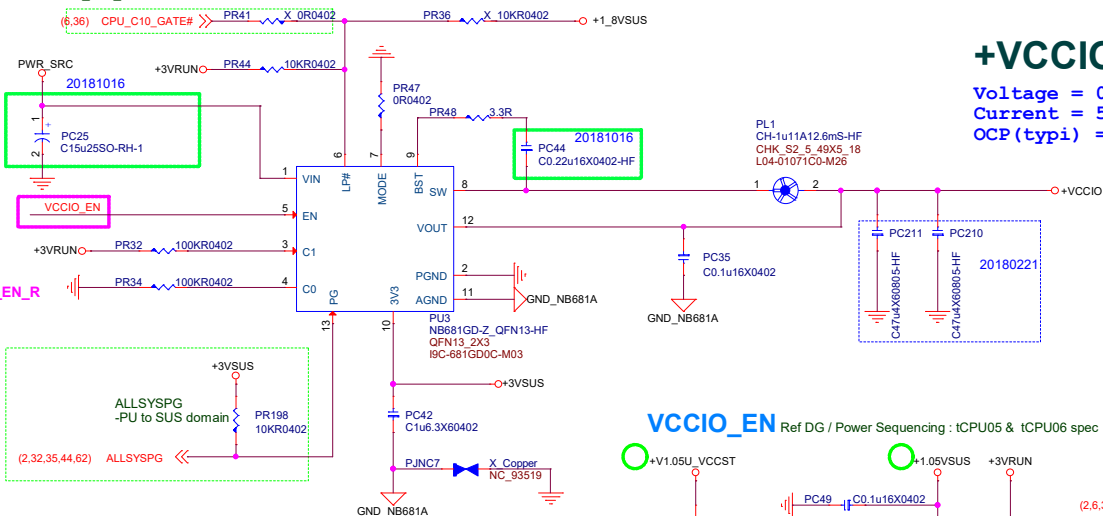
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+VCCSA

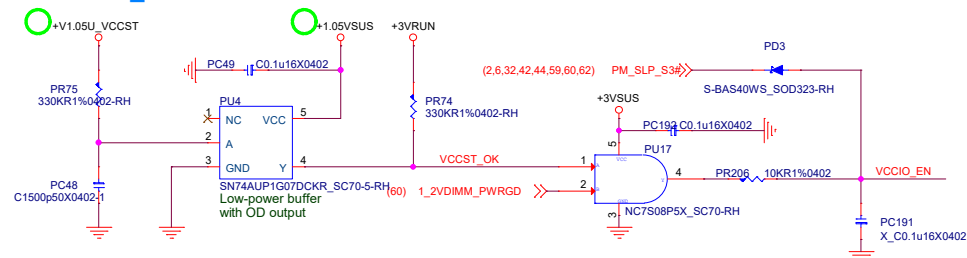


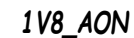
+VCCIO

Power Sequence spec tCPU27 :
 CPU_C10_GATE# de-assertion to VCCSTG stable 10 < tCPU26 < 240 us



VCCIO_EN





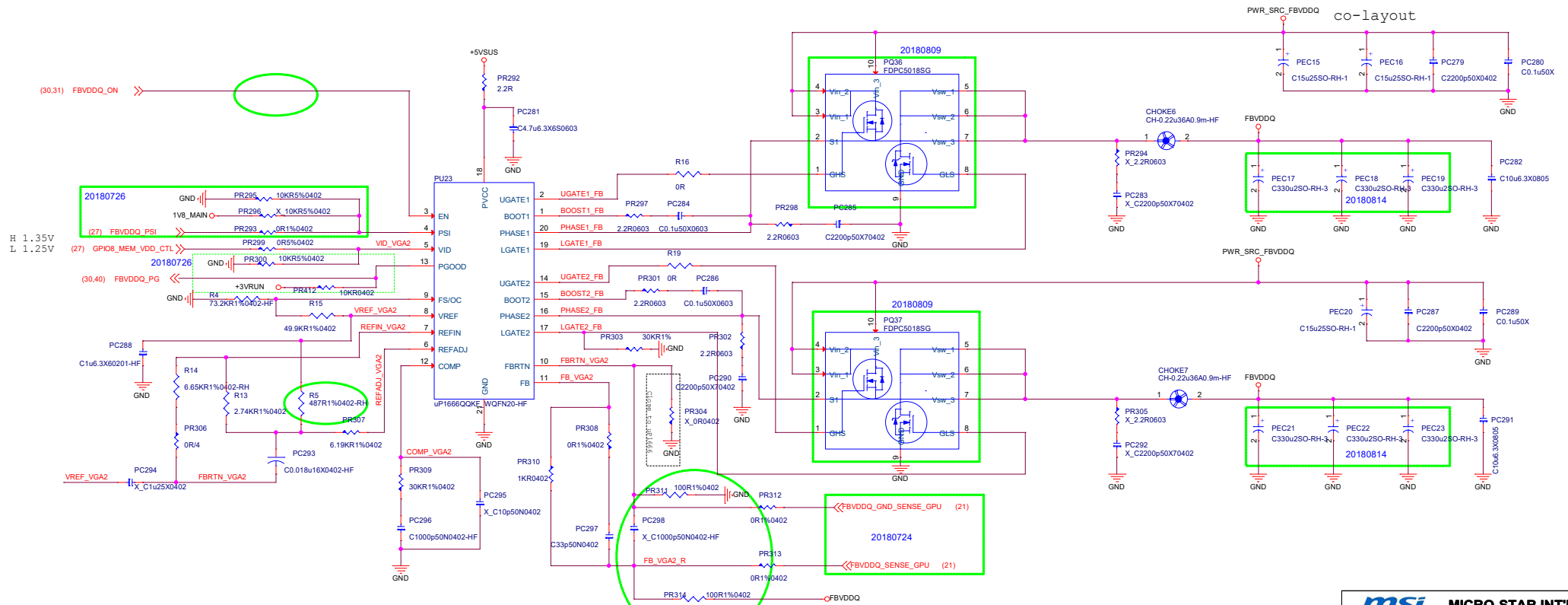
Voltage = 1.8V
Current = 2.26A
OCP (typi) = 4.8A

		MICRO-STAR INT'L CO.,LTD.	
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1V8 AON/PEX_VDD			
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N18E-G3 FBVDDQ / UP1666P

VBoot:1.35V
Vmin:1.25V / Vmax:1.35V

MAXQ-G3 EDP-Peak 54A
MAXQ-G3 EDP-Con 40A



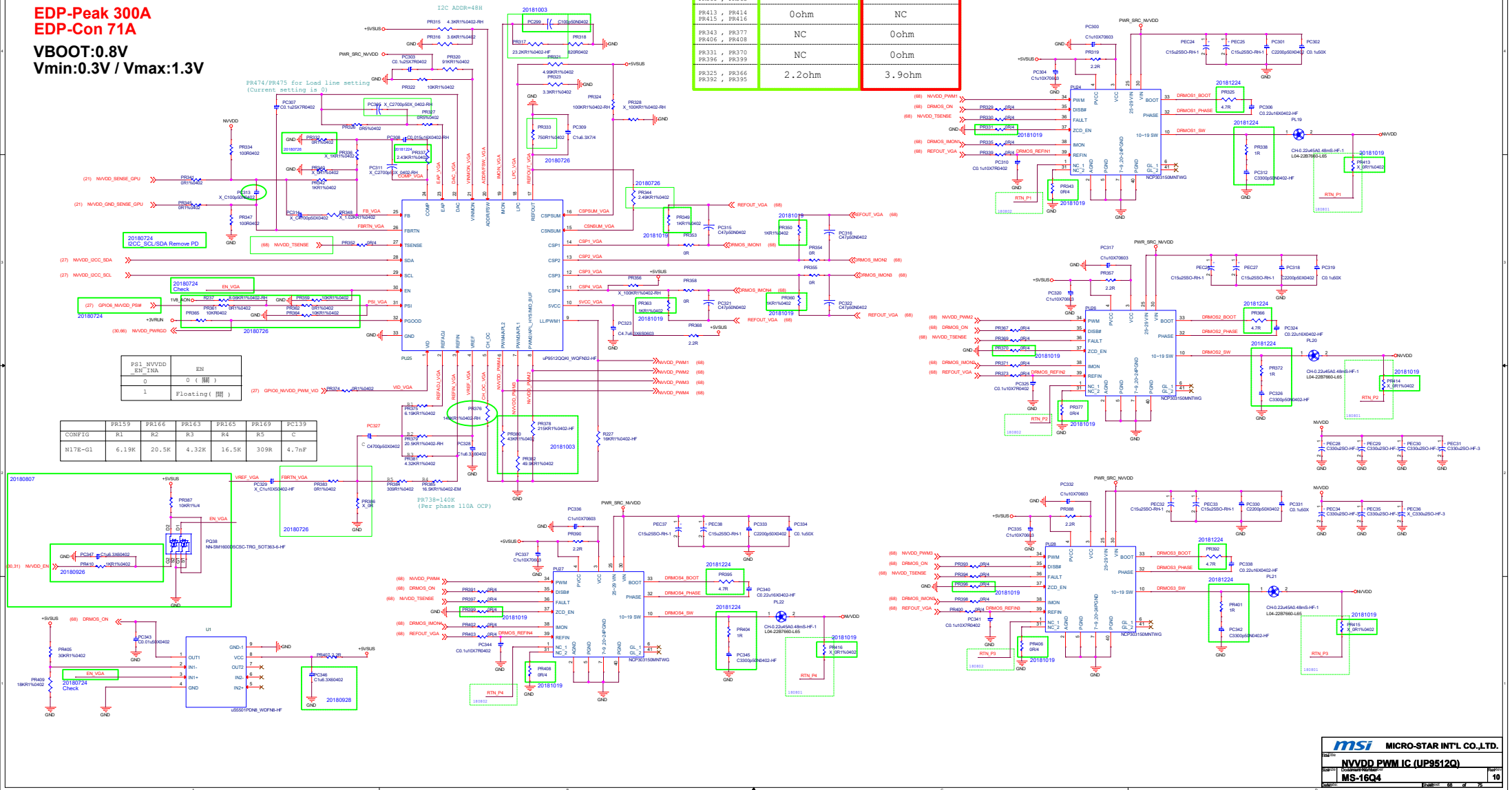
DGPU POWER NVDD UP9512Q

EDP-Peak 300A
EDP-Con 71A

VBOOT:0.8V
Vmin:0.3V / Vmax:1.3V

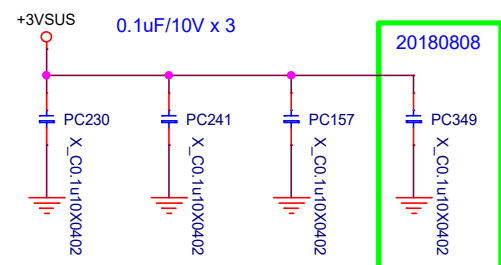
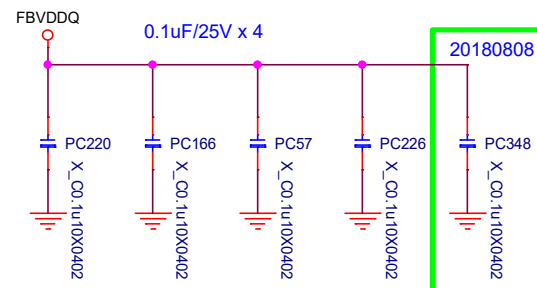
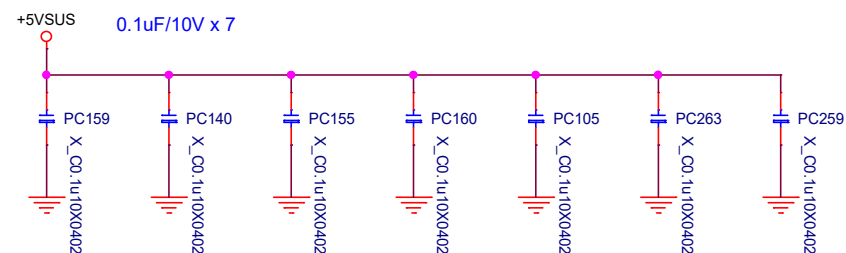
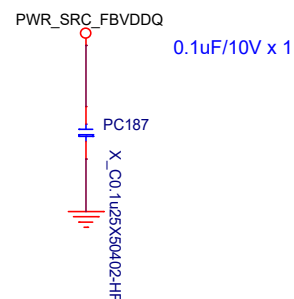
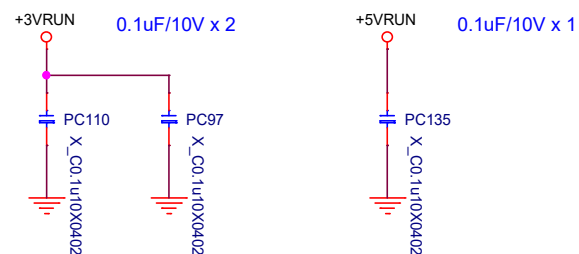
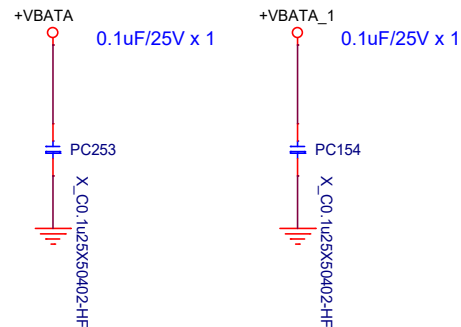
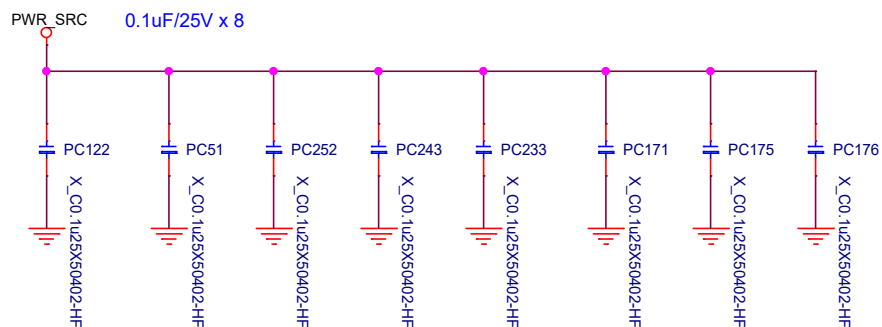
WWW.ALIFIXIT.COM


	UPI (N/A)	ON (N18E-G1/G2/G3)
PR349, PR350, PR360, PR363	NC	1Kohm
PR413, PR414, PR415, PR416	0ohm	NC
PR343, PR377, PR406, PR408	NC	0ohm
PR331, PR370, PR396, PR399	NC	0ohm
PR325, PR366, PR392, PR395	2.2ohm	3.9ohm

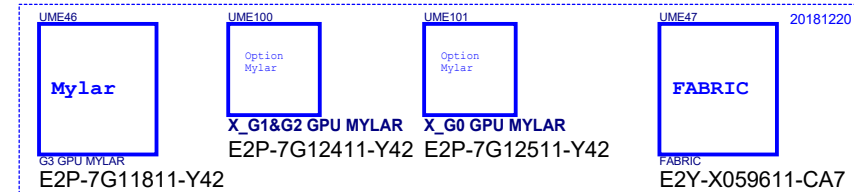
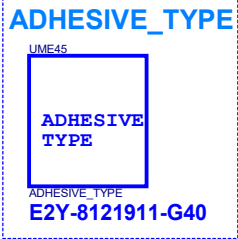
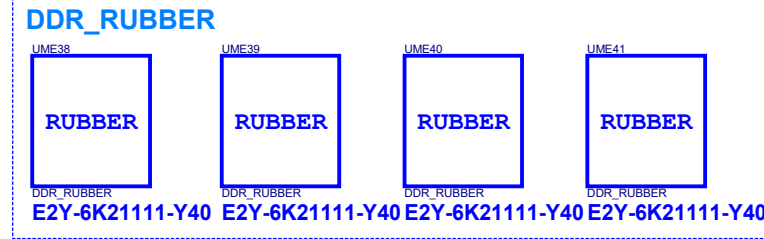
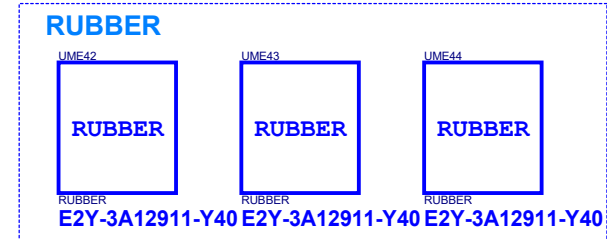
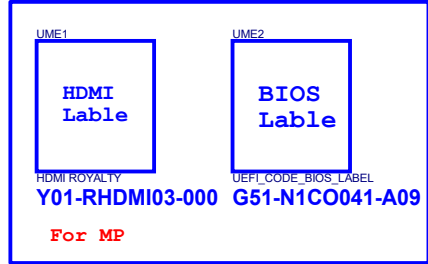
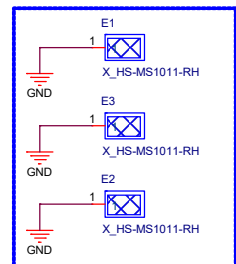
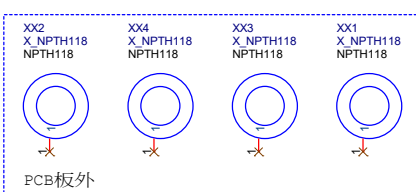
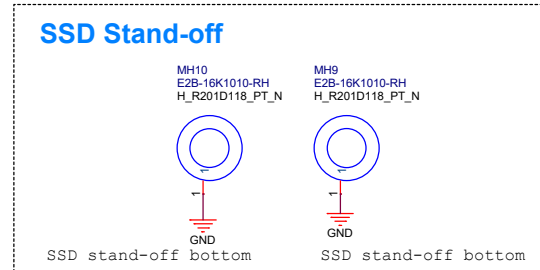
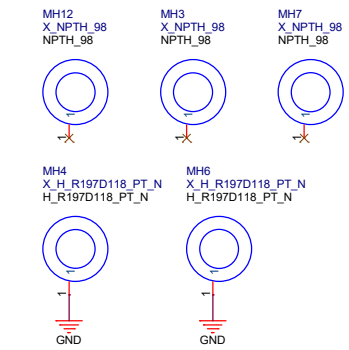
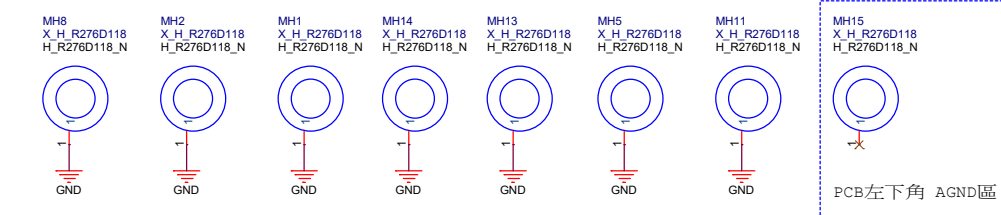
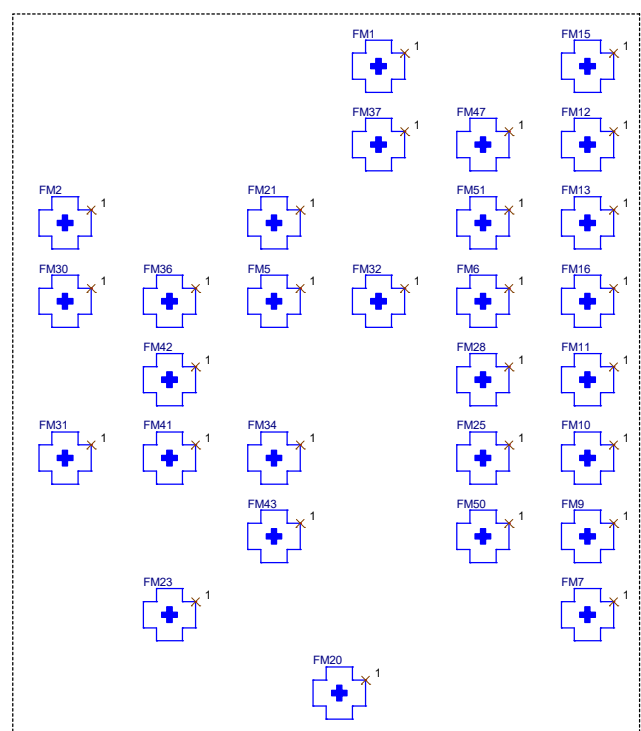
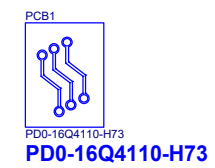
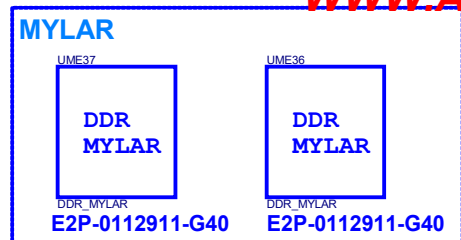
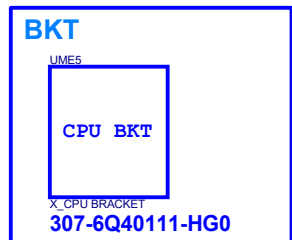
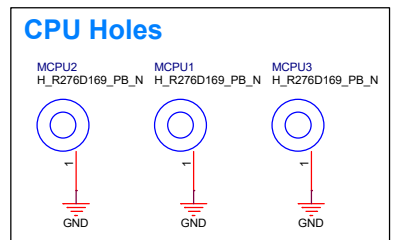
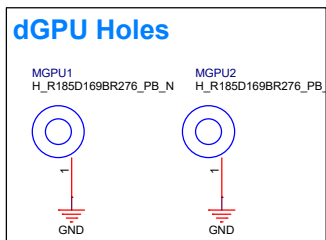


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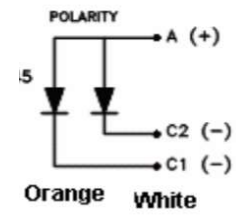
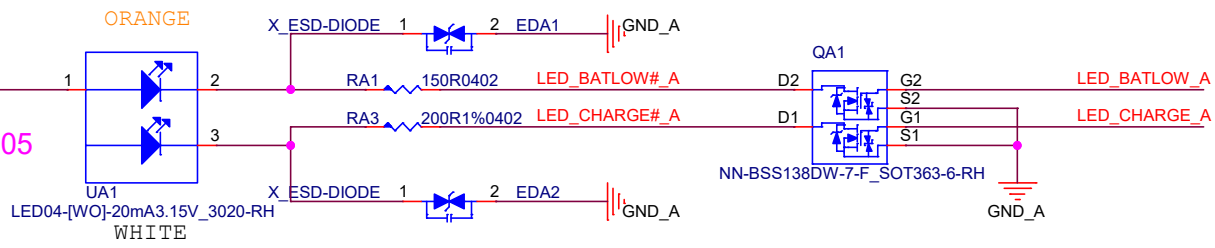


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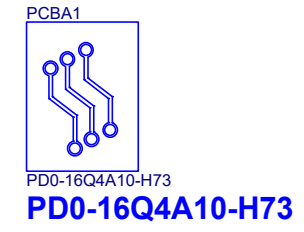
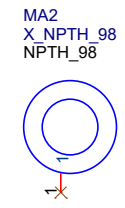
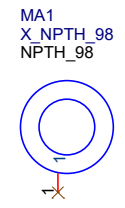
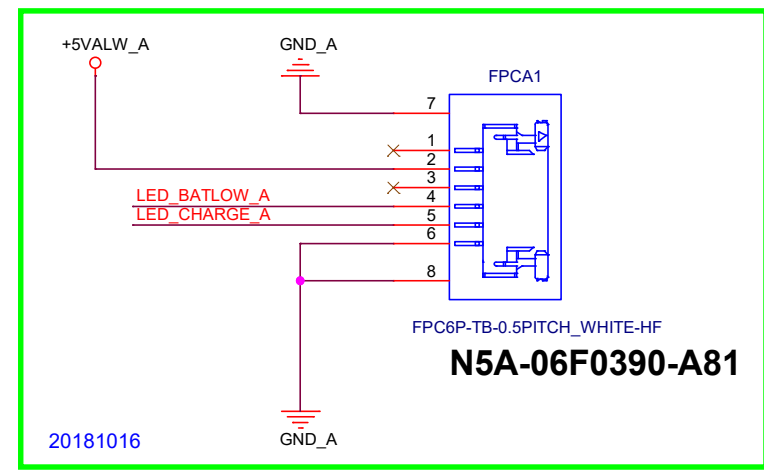


+5VALW_A

D0C-040M700-L05



Part No.	Lens	Emitted Color	Pin Assignment
LTW-326DSKF-5A	Yellow	InGaN White	C2
		AlInGaP Orange	C1



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Title

LED Board

Size

Document Number

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Date

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Rev

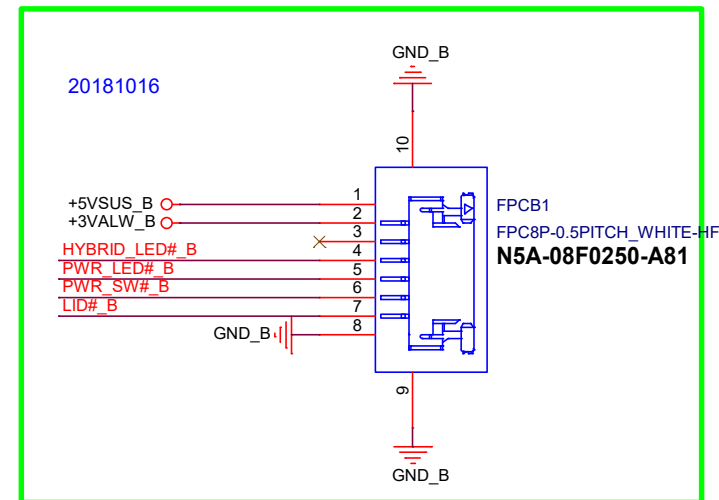
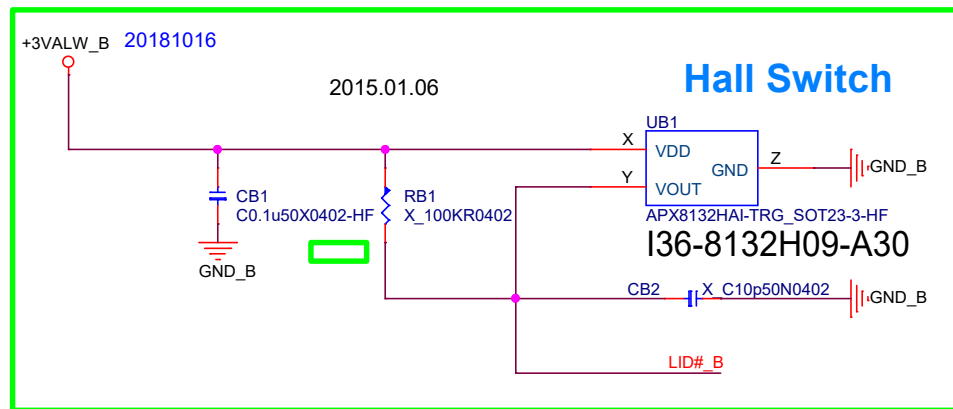
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Sheet

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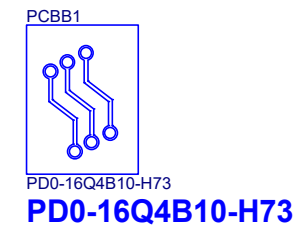
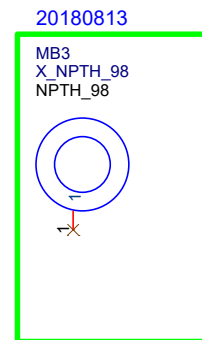
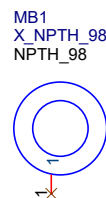
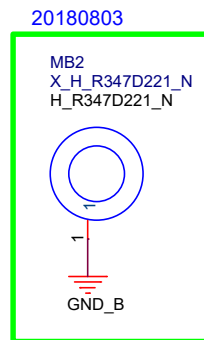
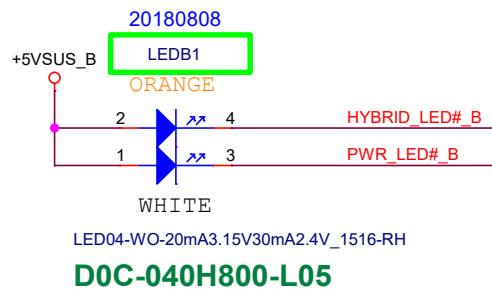
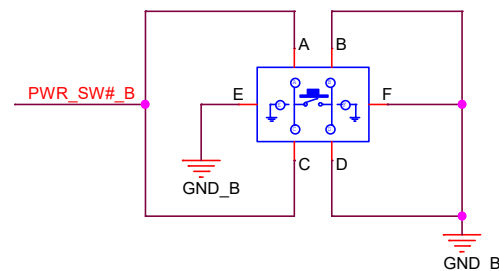
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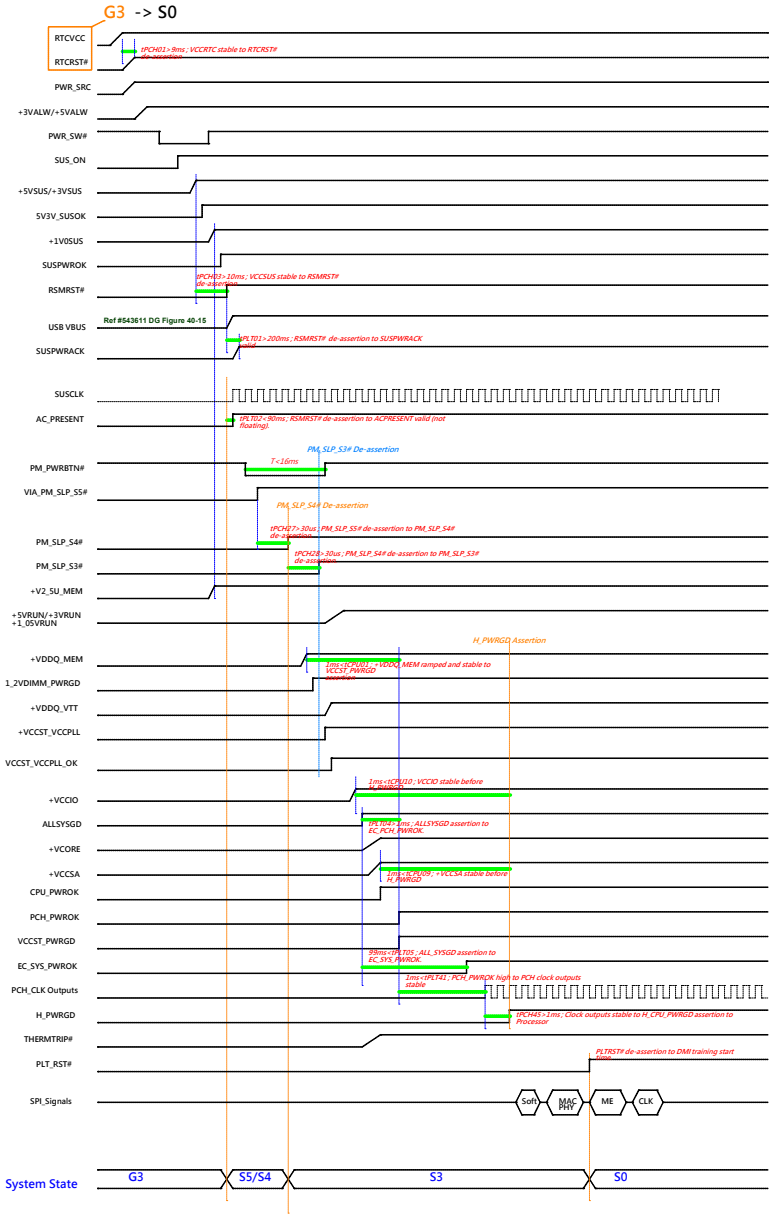
SWB1
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N71-0101630-D02



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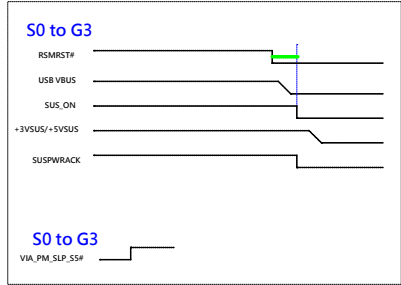
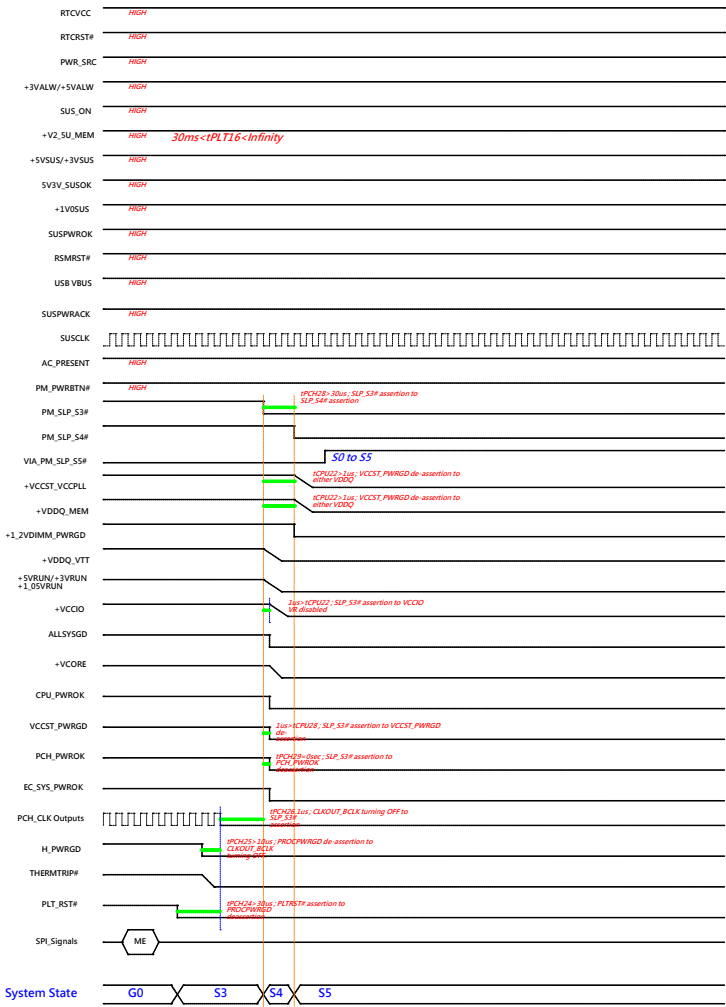
SKL-S DT Power ON Sequence G3 to S0

Ref #543611 Chapter 40
Figure 40-4, SKL-S Timing Diagram for G3 to S0/M0 (Non-Deep Sx Platform)
Table 40-5, Platform Sequencing Timing Parameters



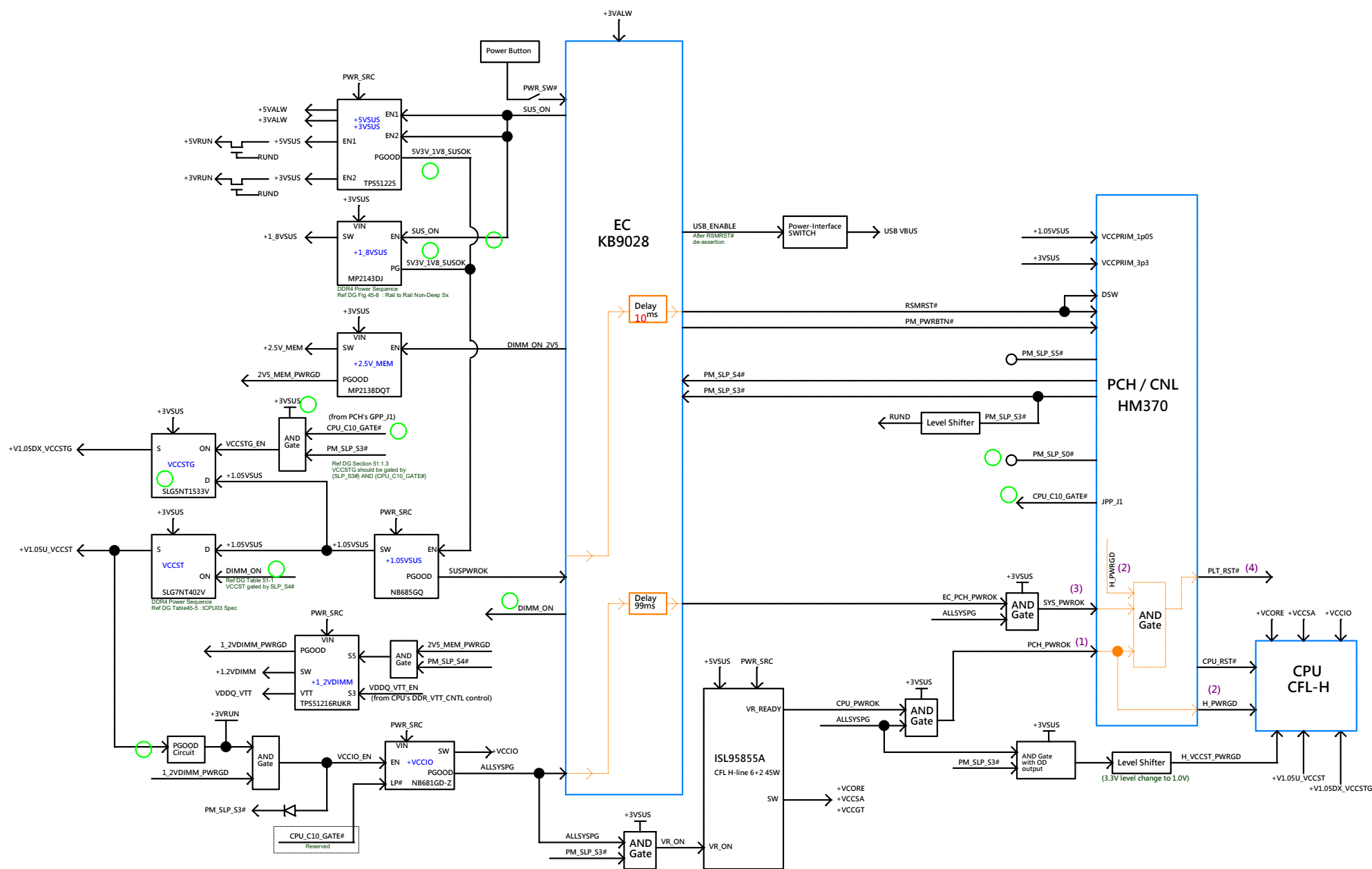
MS-1813 : SKL-S DT Power Down Sequence S0 to S5

Ref #543611 Chapter 40
Figure 40-4, SKL-S Timing Diagram for S0 to G3 (Non-Deep Sx Platform)
Table 40-5, Platform Sequencing Timing Parameters



MS-16Q4 : CFL-H Mobile Power on Block Diagram

ref DG Chapter45 Power Sequencing Spec



History

16Q4 0A

DATE	PAGE	DESCRIPTION	DATE	PAGE	DESCRIPTION	DATE	PAGE	DESCRIPTION	DATE	PAGE	DESCRIPTION
2018	ALL	first version from 16Q4									
20180918	ALL	Add CFG_5_8750H_N18EG1_E2500_SAMSUNG for New BOM Add CFG_16Q4A Add CFG_16Q48			Notice: VRAM Option: R45/R58/U200 N18E-G3/G2 > ABCD N18EG1 > ABC						
	31	Modify R305,PR277 to 287 ohm(R11-1690T12-W08) for N18E-G3 Modify R305,PR277(PU100) to 287 ohm(R11-1910T12-W08) for N18E-G2 Modify R305,PR277(Add PU101) to 287 ohm(R11-2870T12-W08) for N18E-G1 Modify G1(Add G101) to (OB3-16P7002-N08) for N18E-G1 Frame Buffer ABC (D NC) for N18E-G1			GPU Option: G1(G100/G101) GPU_ID(R724,R725) R305,PR277(PU100/PU101)						
20180926	70 55 45 68	CPU BRACKET(UMES) > NC Unstuff CON1 Modify TPM Function to NC Stuff FPC1 Modify PR410 to 1K-ohm for PD sequence			CPU Option:U4 CPU BRACKET > NC						
20180926	ALL 55 32 31 68	10 Modify FPC9 power from +5VRUN to +3VRUN Modify RTC_CTL control circuit. Add RTG Resistor R741/R722/R723 , Unstuff R715/R716/R717 Modify PC346 form 1uF/X65/0201 to 0402									
20181001	31	SWAP DP LAN2 & 3									
20181002	31	Stuff R693, unstuff R692 for Parade.									
20181003	62 68 31	Modify PR185 form 113K to 130K-ohm Modify PR194 form 2K to 2.49K-ohm Modify PC185 form 33nF to 15nF , Stuff it. Modify PC299 form 220pF to 100pF Modify PR380 form 34.8K to 43K-ohm Modify PR382 form 34.8K to 49.9K-ohm Modify PR378 form 169K to 215K-ohm Modify R238,R293 form 750K to 75K-ohm Modify R247,R298 form 6.49 to 649-ohm Modify PR277,R305 to 287-ohm for N18E-G1/G2/G3 Modify C375,C387 form 0.1uF to 1nF , Stuff it.									
20181016	65 39 44,71 45,72 72 65 61	Modify PC18 & PC25 to C71-150251G-S03 Modify R167 to 6.19K-ohm(R11-6191T12-W08) Modify FPCA1,FPC3 pin define Modify FPC1,FPCB1 pin define Move Hall sensor to PWR board Remove PC18 Modify PC44 to 0.22uF,16V,X7R(C11-2242512-W08) Modify PC126 to 22uF,6.3V,X6S(C11-226A314-M09)									
20181016	68 34	Modify PU24,PU26,PU27,PU28 to I33-9619A0C-U47 Modify PR325,PR366,PR392,PR395 to 2.2ohm (R11-022A013-W08) Stuff PR413,PR414,PR415,PR416 Unstuff PR349,PR350,PR360,PR363 Unstuff PR331,PR370,PR396,PR399 Add R724,R725 (GPU_ID) for BIOS									
20181025	43 10 32 43	Add R726,R727 for Safety Modify G1 to OB3-1W1E004-N08 (N18E-G3-A1 PS) Modify U100 to OB3-1W1E003-N08 (N18E-G2-A1 PS) Modify U101 to OB3-16P7003-N08 (N18E-G1-KD-A1 PS) Unstuff R455 Unstuff R653,R656									
20181029	29	Modify R292 to 10K-ohm for NV Spec(ROM_SO).									
20181101	70	Modify UME5(CPU BKT) to 307-6Q40111-HG0									
20181118	28	Modify U200(VRAM) to M12-80325K5-S0N									
20181118	68	PU24,PU26,PU27,PU28 : change to I33-303150C-O05 PR325,PR366,PR392,PR395 : 2.2ohm change to 3.9ohm (R11-039A033-W08) PR349,PR350,PR360,PR363 : NC change to 1Kohm(R11-0102T12-W08) PR331,PR370,PR396,PR399 : NC change to 0ohm(R11-0000012-W08) PR413,PR414,PR415,PR416 : 0ohm change to NC PR343,PR377,PR406,PR408 : NC change to 0ohm(R11-0000012-W08)									
20181118	10	Mdoify G1 to B03-TU10455-N08(N18E-G3-A1) Mdoify G100 to B03-TU10655-N08(N18E-G2-A1) Mdoify G101 to B03-TU10645-N08(N18E-G1-KD-A1)									
20181220	70 49	Add UME46/100/101(GPU Mylar) for ME Add UME47(FABRIC) for ME Modify PC98 to C11-1067620-M09 for Power									
20181224	68	PR337 : 8.2K change to 2.43K(R11-2431T12-Y01) PR325/PR366/PR392/PR395 : 3.9R change to 4.7R(R11-047A013-Y01) PR338/PR372/PR401/PR404 : 2.2R change to 1R(R11-0010023-Y01) PC312/PC326/PC342/PC345 : 1000p change to 3300p(C11-3322012-Y01) Unstuff C741 Modify R388 from R11-499AT12-W08(49.9R1%0402) to R11-0102T12-W08(1KR1%0402)									